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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 1464**
Natsuki MAKINO et al. : Atty Docket No. 2004-0738
Serial No. 10/724,044 : Group Art Unit 1753
Filed December 1, 2003 : **Mail Stop: PETITION**

ELECTROLYTIC PROCESSING APPARATUS
AND METHOD

PATENT OFFICE FEE TRANSMITTAL FORM

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached hereto is a check in the amount of \$130.00 to cover Patent Office fees relating to filing the following attached papers:

Petition \$130.00

A duplicate copy of this paper is being submitted for use in the Accounting Division, Office of Finance.

The Commissioner is authorized to charge any deficiency or to credit any overpayment associated with this communication to Deposit Account No. 23-0975, with the EXCEPTION of deficiencies in fees for multiple dependent claims in new applications.

Respectfully submitted,

Natsuki MAKINO et al.

By

Nils E. Pedersen
Registration No. 33,145
Attorney for Applicants

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

NEP/krq
WENDEROTH, LIND & PONACK, L.L.P.
2033 K St., N.W., Suite 800
Washington, D.C. 20006-1021
Telephone (202) 721-8200
November 19, 2004

[Check No. 65244]

2004-0738



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 1464**
Natsuki MAKINO et al. : Docket No. 2003_1739A
Serial No. 10/724,044 : Group Art Unit 1753
Filed December 1, 2003 : **Mail Stop: PETITION**

ELECTROLYTIC PROCESSING
APPARATUS AND METHOD

PETITION FOR RETROACTIVE LICENSE UNDER 35 U.S.C. 184

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants in the above-referenced U.S. patent hereby petition for a retroactive foreign filing license under 35 U.S.C. 184 and in accordance with 37 C.F.R. § 5.25 and 5.14(a).

The corresponding United States application, currently on file, for which this petition for license is sought is identified above by its application number, filing date, inventors and title. In accordance with 37 C.F.R. § 5.14, no copy of this material is, accordingly, attached. Applicants understand that the licensed subject matter will be measured by the disclosure of the above-referenced U.S. patent application.

The list of foreign countries in which the unlicensed patent application material was filed is as follows:

Japan

The material was filed in Japan on December 2, 2002 and on November 28, 2003. Japanese patent application No. 2003-350529, the first filed application, was revised and refiled as application 2003-399443, the later filed application. The above-referenced U.S. patent application claims priority on both of these applications.

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THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Verified statements by Mr. Kenichi Sasabe and Mr. Yukio Fukanaga including the required parts identified in 37 C.F.R. § 5.25(3) are attached. Also attached are support documents referenced in their statements.

It is noted that many of the support documents are submitted to establish the simple fact of a communication or meeting, e.g., and not for the specific contents thereof. The contents have been redacted in many instances to protect confidential, proprietary, and trade secret information and to maintain privilege based on attorney-client communications and/or attorney work product. While some of the support documents are submitted to establish the fact of an attorney-client communication or attorney work product, the contents thereof have been redacted and no waiver of privilege is made or intended.

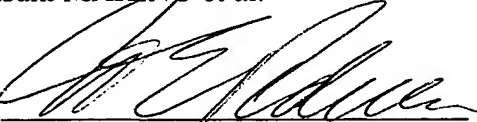
It is respectfully submitted that these statements make it clear that the subject matter in the present application was not under a secrecy order at the time it was filed in Japan, that it is not currently under a secrecy order, that the license has been diligently sought after discovery of the proscribed foreign filing and that the foreign filing without the required license under § 5.11 was through error and without deceptive intent.

Further, the fee set forth in § 1.17(h) is attached.

Accordingly, it is respectfully submitted that this petition is complete and proper, and the grant of the petition is requested.

Respectfully submitted,

Natsuki MAKINO et al.

By 

Nils E. Pedersen

Registration No. 33,145

Attorney for Applicants

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November 19, 2004



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 1464
Natsuki MAKINO et al. : Docket No. 2003-1739A
Serial No. 10/724,044 : Group Art Unit 1753
Filed December 1, 2003 :

ELECTROLYTIC PROCESSING
APPARATUS AND METHOD

**VERIFIED STATEMENT UNDER 37 C.F.R. 5.25(a)(3) IN SUPPORT OF PETITION
FOR RETROACTIVE FOREIGN FILING LICENSE**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

This statement is being made by Yukio Fukunaga of Ebara Corporation, the Assignee of U.S. Patent Application 10/724,044 referenced above. I was assigned as a team leader in Ebara of a Joint development project, which will be discussed below, in August 2002. I have personal knowledge of the acts regarding the filing of Japanese patent applications 2002-350529 and 2003-399443, which acts are discussed below. I am also attaching copies of a number of supporting documents, labeled and referenced herein as documents A-L.

Ebara Corporation began to study the feasibility of a joint development program for the development of technology for plating and planarizing of copper interconnects on semiconductor substrates. This began in July 2002. Mutual presentations between Ebara and a US company as a potential joint development partner were made. Ebara made a presentation in July 2002 in US regarding their plating tool, which had been in development in Japan since 1998. Ebara made a demonstration using test wafers supplied by the US company in Japan and presented the test results to the US company and the US company made a presentation and an explanation of a very

limited disclosure of technological concepts that they intended to develop as part of the proposed joint development program. This disclosure took place in the United States in August of 2002, however, the joint development program agreement was not reached until August of 2003.

The inventors of the above-referenced U.S. patent application, Mr. Natsuki Makino and Mr. Junji Kunisawa, had been working in Japan on the electrolytic processing apparatus and method which is the subject matter of the Japanese patent applications.

In the fall of 2002 I instructed the inventors to prepare a draft of their disclosure and to send it to Ebara Intellectual Property Department with a request for the preparation of a patent application for filing in Japan directed to their invention. However, part of what became the first-filed Japanese patent application included material which arose out of presentations in the United States. At that time, I did not realize that the application we were preparing to file in Japan included material that was developed in the United States. While I understood that the invention for which we were filing an application in Japan related to the joint development project with our U.S. partner, I did not appreciate that the application that we were filing included material which could be said to constitute an invention made in the United States for which a foreign filing license should be sought before filing in Japan.

I sought to file the application quickly in Japan, because in Japan a patent is issued to the first applicant that files for the invention. It is thus very important for the applicant to file as soon as possible after an invention is made. We had not reached any agreement with respect to the joint development project about how intellectual property was to be protected and in what manner patents might be sought so at that point I believed it was most important for us to proceed in Japan as soon as possible. It was not my intent to be deceptive on this point.

The attached documents A reference agenda and minutes of a pre-meeting I chaired on August 30 2002 for preparation of an in-house kick-off meeting. Makino and Kunisawa, who are the inventors of Japanese applications 2002-350529 and 2003-399443, were present at this meeting. These documents include a copy of memorandum of discussion on the tool specification based on discussion in a meeting held in the US between Ebara and the US company.

The attached documents B reference a copy of a white board used in an Ebara in-house meeting held on September 3, 2002 in Japan for discussing the tool specification and tool

schedule.

The attached documents C reference a copy of copyable board used at a meeting between Kunisawa, Makino, who are the inventors of Japanese applications 2002-350529 and 2003-399443, and Mr. Kosugi, a patent agent, who prepared the application document for the inventors based on the explanation given to him by the inventors. This meeting was held on November 18, 2002 in Japan.

The attached documents D reference the request for preparation of patent application for filing in Japan and the draft of the disclosure prepared by inventors Makino and Kunisawa to proceed with the filing of the application in Japan. I was aware that this application included a pad attached to a high resistant structure when I checked the draft made by the inventors and I knew that a pad disposed on the high resistant structure was shown in the presentation by our US partner in August 2002. As I knew a plating method using a pad at that time I did not think that using a pad disposed on a high resistance structure was their new idea. I also thought that if our US partner claims that the application should be a co-application, we could modify our application to include their inventors and to make the application a co-application between Ebara and our US partner. I had no knowledge that the invention made in US must be filed in US first at that time. It was approved by me and sent to IP department in the headquarters through Patent department in Precision machinery group.

Please also note the additional request for preparation of patent application referenced as documents E which involve my approval regarding the revision application of 2002-350529 filed on November 28 of 2003.

Please also note the additional request for preparation of foreign patent application referenced as documents F which I approved to file in US with priority date of Japanese filing date of 2002-350529. This application was filed in US application serial number 10/724044 on December 1, 2003.

At the time we filed these applications abroad, i.e. on December 2, 2002 and November 28, 2003, they were not under a secrecy order, and they are not currently under a secrecy order.

We began discussing these applications and the U.S. application for the U.S. joint development project partner in February of 2004. Before the meeting with our US partner, we discussed in Ebara and ETI on the applications and ownership based on the list. We noticed that

two of the applications might include information given by our US partner to Ebara in the meeting in August 2002. After discussing the contents of the applications in the meeting in February 2004, our US partner insisted that some the applications in the list included material that was developed by them in the United States. Because we had only a list of applications which included a plain abstract of each application at that time, we prepared full translations of the claims of each application and asked them to study which applications included material developed by them in the US. We agreed in March 2004 that these two applications 2002-350529 and 2003-399442 and the U.S. application for which this statement is prepared included material developed in US.

Please see the accompanying documents G which evidence the list of our patents discussed at the meeting on February 6, 2004. In a discussion in Ebara preparing this document, we found that #22 and #24 may include invention made by our US partner in US. We indicated on the list that these two applications might be co-applications between Ebara and our US partner.

Document H is minutes of the meeting between Ebara and our US partner on February 5 and 6, 2004 in US. Technical discussions, which contain confidential items between Ebara and our US partner, are redacted from this minutes and only IP issues are left on the document.

This discussion was mainly made between Mr. Sasabe, General manager of Patent department of Ebara, Mr. Musaka, Technical coordinator for Ebara of this joint development project, me, and engineers and an in-house attorney of the US partner.

Document I is a copy of an e-mail sent on March 9, 2004 by Mr. Musaka to a technical coordinator of our US partner of the JDP. Application #2 stands for Japanese application 2003-350529, #22 stands for 2003-399443.

Document J is a copy of an e-mail, which I sent to Mr. Musaka on May 7, 2004, asking not to agree to make some Japanese applications co-applications between Ebara and our US partner on a meeting held on May 7, 2004, because we were trying to get approval of Mr. Tsujimura on making them co-applications.

Document K is a copy of a meeting agenda and a copy of white board used at a meeting to investigate the history of these applications held on May 27, 2004 in Japan.

Document L is a copy of an e-mail from Mr. Musaka on June 10, 2004 reporting a result

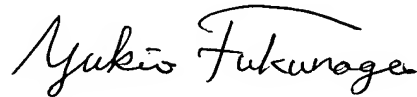
of a meeting between the Project manager of the JDP of our US partner and Mr. Kimura, Project manager of the JDP of Ebara.

We reached an agreement in June 2004 about which applications in all the applications listed and presented by Ebara at the meeting in February 2004 included material that was developed by them in the United States. And, we agreed to a process to clarify the ownership of the invention before filing an application, except those clearly belonging to Ebara only, in the US first.

I have diligently sought this retroactive foreign filing license after I discovered that our foreign filings were in fact proscribed.

I declare that all statements that I have made herein of my knowledge are true, and that all statements on information belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under § 1,001 of Title 18 of the United States code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Respectfully submitted,

A handwritten signature in cursive script that reads "Yukio Fukunaga".

Yukio Fukunaga

Date: Oct. 27, '04



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**VERIFIED STATEMENT UNDER 37 C.F.R. 5.25(a)(3) IN SUPPORT OF PETITION
FOR RETROACTIVE FOREIGN FILING LICENSE**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This statement is being made by Kenichi Sasabe of Ebara Corporation, the Assignee of applications listed below. I was promoted in 1998 to be a general manager of the Patent Department in the Precision Machinery Group of Ebara Corporation, in which position I still remain now. I was assigned in August 2003 as Patent/IP leader of a Joint development project in Ebara. I have personal knowledge of the acts regarding the preparation for this foreign filing license petition relating to the following applications that have been filed outside of the United States:

Japan

- | | |
|-----------------|-------------------|
| 1. 2002-350529 | December 2, 2002 |
| 2. 2003-015236 | January 3, 2003 |
| 3. 2003-149827 | May 27, 2003 |
| 4. 2003-161237 | June 5, 2003 |
| 5. 2003-195406 | July 10, 2003 |
| 6. 2003-310355 | September 2, 2003 |
| 7. 2003-399443 | November 28, 2003 |
| 8. 2003-431211 | December 25, 2003 |
| 9. 2004-022178 | January 29, 2004 |
| 10. 2004-023256 | January 30, 2004 |
| 11. 2004-082102 | March 20, 2004 |

PCT

PCT/JP2004/000528 filed January 22, 2004, related to JP#2, JP#3 and JP#4 above as well as one other Japanese application which includes no invention made in the U.S., and designating all countries except Japan

Taiwan

TW93101713 filed January 27, 2004 and related to JP#2, JP#3 and JP#4 above as well as one other Japanese application which includes no invention made in the U.S.

Three applications were filed in the US related to four of the Japanese applications listed above:

US Patent Application Serial No. 10/724,044, which is related to JP#s 1 and 7 above;

US Patent Application Serial No. 10/886,716 which is related to JP# 5 above; and

US Patent Application Serial No. (New), filed September 1, 2004 in the name of Keiichi KURASHINA et al. and related to JP#6 above.

I am also attaching copies of a number of supporting documents, labeled and referenced herein as documents L-BB.

As the joint development project was prepared in a highly secret condition in Ebara, I knew little of this project before I was asked to be a Patent/IP leader in the project in August 2003. I remember two acts in which I was involved before August 2003.

One action is that I prepared a list of patent applications Ebara filed in Japan for plating technology of copper interconnect on a semiconductor substrate. I prepared this list to show Ebara's background technology that Ebara had before Ebara got into the joint development project. I listed Ebara applications and the development people selected applications which were

necessary as background technology. This list was prepared in around September 2002 and updated in March 2003.

The second action I was involved in was a discussion of the ideas between Ebara Technologies Incorporated (ETI) and our US partner. A list of ideas to be developed was sent to Ebara engineers in Japan and the Ebara engineers and I discussed the ownership of the ideas to advise ETI engineers. These ideas were prepared in the US by ETI and our US partner. We found some of the ideas had already been filed in Japan by Ebara and some ideas were being prepared for filing by Ebara.

After an inventor invents something in the Precision Machinery Group in Ebara, a disclosure of the invention is made by the inventor and sent to the IP department in the headquarter of Ebara through a patent liaison in the same department as the inventor, managers supervising the inventor, and the Patent Department in the Precision Machinery Group. I check and approve the disclosure to be filed as a patent application.

If the inventors indicated that the invention included some inventions or ideas made in the US, the patent department should have noticed the error in filing in Japan first. But there was no indication that the applications included any inventions made in the US, so I did not notice that there were inventions made in the US in the applications until January 2004 when Ebara engineers and I prepared the list of Ebara applications.

In January 2004, Ebara development engineers and I prepared a list of Ebara's applications filed in Japan for a meeting held in the US between Ebara, ETI and the US partner. I made a list of Ebara applications filed later than August 2002 in Japan. Ebara engineers selected the applications which may have some relation with the joint development project. I made a table of Ebara applications to be submitted in the meeting. In the discussion for preparing the list with the Ebara engineers we noticed that two of the applications might include information given by our US partner to Ebara in a presentation in August 2002. We indicated the ownership as joint between US partner and Ebara in the table. I noticed that if the application included an invention made in the US, we must prepare a petition for a retroactive foreign filing license for the filing of the application first in Japan.

I discussed the necessity of the petition for a retroactive foreign filing license with an

attorney of our US partner at the meeting. As the table has 29 applications, it took a long time to decide ownership of each of the applications and to clarify the inventors of each invention. It was finally decided in June of 2004.

Document M is the list of Ebara patent applications filed in Japan later than August 2002, which was submitted to the meeting.

Document N is the minutes of the second workshop meeting between Ebara and our US partner held on February 5 and 6, 2004 in US. These minutes briefly describe the discussion in the meeting.

Document O is a Facsimile letter to Deputy General Manager Kondo of IP department and Manager Sakaguchi of Patent department of Ebara, which I sent on February 8, 2004 to instruct to check if there were other applications related to this joint development project filed before August 2002, which used a pad on an impregnated material, and also to instruct to make English translations of abstract and claims of some applications filed in Japan.

I have diligently sought this retroactive foreign filing license after I discovered that our foreign filings were in fact proscribed. We began discussing these applications and the U.S. application for the U.S. joint development project partner in February of 2004. As I have little experience in this matter of foreign filing licenses and obtaining retroactive foreign filing licenses, it has taken me some time to study the situation, discuss the matter with my colleagues and obtain appropriate advice in order to make this statement in support of the accompanying petition.

On February 8, 2004 I discussed briefly this problem with an attorney in the US different from Mr. Pedersen, who is filing this statement for us. I asked him his advice by e-mail on February 28, and a partner attorney sent me advice on March 3, 2004.

Document P is a copy of an e-mail I sent to an attorney for his advice on February 28, 2004. As the attorney, licensed in New York, is Japanese, this e-mail was written in Japanese.

Document Q is advice from the partner attorney sent on March 3, 2004. As the attorney from whom I asked advice is from a firm with which we consult on general advice or litigation matters, I asked Mr. Pedersen, an attorney who is a representative of Ebara in filing patent applications in the US, to proceed with the actual filing for the foreign filing license in May 2004.

Document R is a copy of an e-mail I sent to Mr. Pedersen to ask his advice on May 11, 2004.

Document S is a copy of an e-mail I sent to Mr. Pedersen on May 15, 2004 with an attachment of a draft to explain a reason why Ebara filed in Japan before filing in US.

Document T is a copy of an e-mail I sent to Mr. Pedersen on May 18, 2004.

Document U is a copy of an e-mail I sent to Mr. Musaka on May 19, 2004 regarding an advice from Mr. Pedersen.

Document V is a copy of an e-mail I sent to Mr. Fukunaga asking for preparing his statement. This e-mail includes e-mail from Mr. Pedersen on May 24, 2004.

Document AJ is a copy of e-mail I sent on June 2, 2004 to Mr. Pedersen, our attorney, asking for advice.

Document AN is a copy of e-mail from Mr. Pedersen which shows that I visited his firm on June 23, 2004 for discussion on this issue.

Document AO is a copy of e-mail I sent to Mr. Pedersen on June 26 for instruction on this issue.

Document AP is a copy of e-mail I sent to Mr. Musaka on June 29, 2004 regarding petitions based on the advice from Mr. Pedersen.

Document AS is a copy of e-mail I sent to Ms. Matsuo of Kontecs whom we asked translation of support documents for this petition and statements. This e-mail respond to her e-mail referring her e-mail. This e-mail shows that we asked translation of our support documents on July 3, 2004.

Document AV is a copy of e-mail I received from Mr. Pedersen on July 20, 2004 in reply to my e-mail on July 13, 2004.

Document AW is a copy of e-mail I sent on July 22, 2004 to inform Ms. Matsuo that I received the English translation of support documents for this petition and statements.

Beside these contacts with attorneys for the preparation of the foreign filing license, I contacted often with Mr. Musaka, who is a technical coordinator of Ebara in the Joint Development, and he contacted with the technical coordinator of our US partner to discuss about the ownership of the applications. In this discussion our US partner requested to some of the

applications to be joint applications, which include their inventions made in US. As we decided to make the Japanese applications 2002-350529 and 2003-399443 joint applications after the meeting held in February 2004, we started to prepare to submit a petition for these two Japanese applications and one US application based on one of the Japanese applications. But through the discussion with our US partner, the number of applications that they requested us to change to joint applications increased. We investigated the history of inventions and we reported the reason why we considered the inventions were made by Ebara inventors. The discussion on the ownership of the applications continued until June 2004.

In March 2004 we tried to file a petition for the two Japanese applications. After some discussions with our US partner, we tried to treat all applications requested to be joint applications together in one foreign filing license. But after precise study of the applications, we found that the general manager in development department was Mr. Fukunaga for the two Japanese applications and was Mr. Mishima for other applications. We decided in June 2004 to file the petitions in two groups to clarify the situation.

Document W is a copy of an e-mail I sent to Mr. Musaka on March 6, 2004 to send English translations of some Japanese applications for which our US partner requested to send English translations of abstracts and claims. This e-mail also explains the Japanese application 2002-350529 referred as application No.2 and Japanese application 2003-399443 referred as application No.22.

Document I is a copy of an e-mail sent on March 9, 2004 by Mr. Musaka to a technical coordinator of our US partner of the JDP for sending English translation of abstracts and claims of the Japanese applications.

Document X is a copy of an e-mail I sent to Mr. Musaka on March 9, 2004. This e-mail explains the relation of Japanese applications 2002-350529, 2003-399443 and US application based on 2002-350529.

Document BB is a copy of an e-mail Mr. Musaka sent to the US partner for sending English translation of the application on March 12, 2004.

Document Y is a copy of an e-mail I sent to General Manager Nakashiba, Deputy General Manager Akai, Deputy General Manager Kondo and Manager Shinozuka of Intellectual Property

Department in Ebara Headquarters on March 17, 2004 to propose a filing procedure for patent applications related to the JDP.

Document AZ is a copy of e-mail I sent to Mr. Nakashiba and Mr. Akai about filing petition for export license on March 24, 2004.

Document BA is a copy of e-mail I sent to Mr. Akai on March 25, 2004 reporting the result of a discussion between Mr. Musaka and our US partner. The e-mail from Mr. Musaka to me following the e-mail to Mr. Akai shows the request from our US partner expressed in the discussion.

Document AY is a copy of my notebook which shows a memo of a meeting between Mr. Fukunaga, Mr. Mishima, Mr. Kurashina and me on March 31. The reasons why Ebara considered the inventions were Ebara inventions were discussed in this meeting.

Document AG is a copy of a white board used in a meeting by Mr. Fukunaga, Mr. Mishima, Mr. Sakaguchi and me for a study of ownership of several Ebara applications on April 19, 2004.

Document Z is a copy of an e-mail I sent to Mr. Musaka and Mr. Mishima with an attachment describing Ebara's opinion explained to Mr. Musaka on April 24 on the ownership of some applications which were studied in the meeting held on April 19, 2004.

Document AA is a copy of e-mail I sent to Mr. Fukunaga on May 6, 2004 responding to e-mail from Mr. Musaka requesting a telephone conference with our US partner on May 7 at 6:00 AM in Japan time on patent applications.

Document AB is a copy of e-mail replying on May 7, 2004 to e-mail from Mr. Fukunaga requesting my checking of a draft before he reports the progress of the patent issue to Mr. Tsujimura, Director of Advanced Technology Division.

Document J is a copy of an e-mail, which Mr. Fukunaga sent to Mr. Musaka on May 7, 2004, asking not to agree to make some Japanese applications co-applications between Ebara and our US partner on a meeting held on May 7, 2004, because we were trying to get approval of Mr. Tsujimura on making them co-applications.

Document AC is a copy of an e-mail I sent on May 8, 2004 to an attorney of our US partner, in return to an e-mail I received from him. He advised me of preparing petition for

foreign filing license after a telephone conference of the Joint Development Program on May 7, 2004.

Document AI is a copy of e-mail I sent on May 18 to Mr. Musaka sending English translation of specification of application JP #9 (2004-022178) which is referred as #26. (#26 is a number in the patent list of Document M.) On a telephone conference held May 7, 2004 Mr. Mishima explained the contents of this application and he explained that this application should be Ebara sole application.

Document AH is a copy of e-mail I sent on May 20, 2004 to Messrs. Musaka, Fukunaga and Mishima explaining the result of my check for claims including pad in Ebara applications. I explained my consideration on some of the applications in this e-mail.

Document K is a copy of e-mail I sent on May 21, 2004 of a meeting agenda, and a copy of white board used at a meeting to investigate the history of applications JP#1 and #7 held on May 27, 2004.

Document AD is a copy of e-mail I sent to Mr. Mishima on May 29, 2004 for asking to submit related documents to the applications in relation to the meeting on May 27, 2004 described in Document K.

Document AK is a copy of e-mail I sent on June 8, 2004 to Mr. Musaka for sending English translation of application JP#5 (2003-195406) to be checked by our US partner before filing in US.

Document AE is a copy of e-mail I sent on June 8 to inventors of the applications for sending a questionnaire.

Document AF is a copy of an e-mail I received from Mr. Musaka and transferred to General Manager Akai and Manager Shinozuka of Ebara IP department on June 11, 2004 after a meeting between representatives of Ebara and our US partner for discussion about IP issue in JDP. In this meeting both agreed to make Japanese applications in concern to be co-applications between Ebara and our US partner.

Document AL is a copy of Agenda of #3 workshop meeting held on June 21, 2004.

Document AM is a copy of e-mail I sent to Mr. Musaka on June 18, 2004 sending documents for #3 workshop meeting. In this meeting I explained that we will make 11

applications co-applications and asked them to reconsider about two applications different from the 11 applications.

Document AQ is a copy of e-mail I sent to Mr. Musaka for sending English translation of application JP #10 which is referred as #28 (2004-23256).

Document AR is a copy of e-mail I sent to Mr. Musaka on July 9, 2004 asking any response from our US partner on two JP applications including JP #6 which are referred as #13 and #16 respectively.

Document AX is a copy of e-mail which Mr. Fukunaga sent to Mr. Musaka on July 6, 2004 inquiring the name on inventors of our US partner for filing application JP # 5 in US as a joint application.

Document AT is a copy of e-mail I sent to Mr. Shinozuka of IP Department on July 16, 2004 asking to send me copies of "Notification of invention" which are Document BC -BM respectively, and confirming who was the General manager at the time of filing.

Document AU is a copy of e-mail I received from Mr. Musaka on July 18, 2004 in response to my e-mail sent on July 9, 2004 regarding two JP applications including JP #6 which are referred #13 and #16 respectively in the e-mail.

I declare that all statements that I have made herein of my knowledge are true, and that all statements on information believed are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under § 1,001 of Title 18 of the United States code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Respectfully submitted,



Kenichi Sasabe

Date: October 30, 2004

辻村様", "福永様" <fukunaga.akira@ebara.com>, "徳重様" <tokushig. 午前 08:42 02/08/28 +0900

To: "辻村様" <tsujimura.manabu@ebara.com>, "福永様" <fukunaga.akira@ebara.com>, "徳重様" <tokushige.katsuhiko@ebara.com>, "三島様" <mishima.koji@ebara.com>, "勝岡様" <katsuoka.seiji@ebara.com>, "国澤様" <kunisawa.junji@ebara.com>, "牧野様" <makino.natsuki@ebara.com>, "神田様" <kanda.hiroyuki@ebara.com>, "並木様" <namiki.keisuke@ebara.com>, "蓬台様" <hodai@m.email.ne.jp>, "南條様(大石様)" <oishi.kunio@ebara.com>

From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: PaPキックオフ会議開催の件

Cc:

Bcc: fukunaga.yukio@ebara.com

Attached:



各位殿

題記の件、~~redacted~~キックオフミーティングを下記のとおり開催しますので、ご出席お願いいたします。
辻村統括より、お話しがあります。

- ◆ 日時: 8月30日(金) 9時~11時
- ◆ 場所: V2棟 第一会議室

当日出席できない方は、予め福永(由)までご連絡下さい。

第一開発センタ
第二プロセス開発室
福永(由) (Tel. 8970)

8月30日 redacted 1st meeting

X Polishing Pad with holes. 2.

• Z-motion. 位置制御のみ?

→ Δ (可変制御の元法?) 調整? Linear 調整?
Wf の固定 (Backing sheet)

X Anode rotation. Anode の回転? (2x)

! 2x 12 offset?

• 2nd solution line.

A, B の 2x 12

A 2x 7x 12
B 2x 7x 12 調整

• Anode with full contact

to wafers. • Polishing Pad の調整

• Wafer support

• Ceramic plate (2x 12) Δ 可変の範囲? 調整? (2015)

Switching { A 位置が保たれる
B DIN

• Voltage 調整が切れる. 11-12 調整
レバー (V, I)

• Recipe (10 step) ① 現 10 stop

• Control z-motion. ② 変位制御が可.
Control down force. 同期可

Module ???

• 2nd solution line

X Wafer. Rotation / Oscillation. Table

調整が可? 調整?

~ 10/7 の Menu
Op. Menu

~ 9/9 調整

Tsujimura", "Fukunaga "<fukunaga.akira@ebara.com>," Tokushige"<tokushige AM 08:42
02/0828+0900

To: "Tsujimura"

<tsujimura.manabu@ebara.com>,"Fukunaga"<fukunaga.akira@ebara.com>,"Tokushige"<t
okushige.katsuhiko@ebara.com>,"Mishima"
<mishima.koji@ebara.com>,"Katsuoka"<katsuoka.seiji@ebara.com>,"Kunisawa"<kunisaw
a.junji@ebara.com>,"Makino"<makino.natsuki@ebara.com>,"Kanda"<kanda.hiroyuki@eba
ra.com>,"Namiki"<namiki.keisuke@ebara.com>,"Hodai"<hodai@m.email.ne.jp>,"Nanjo
(Oishi)"<oishi.kunio@ebara.com>

From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Call-up of kickoff meeting for *redacted*

Cc:

Bcc: fukunaga.yukp@ebara.com

Attached:

To all concerned,

This message requests all concerned members to attend the kickoff meeting for the *redacted*
project scheduled as below.

Mr. Tsujimura, Chief of Technology Div., will have a speech.

Date: Friday, August 30. From 9:00 a. m. to 11:00 a.m.

Place: Meeting room 1, Building V2

Please inform Y. Fukunaga of your absence in advance.

Y. Fukunaga

Process Development Office 2

Development Center 1

Phone: 8970 (Extension)

August 30 PaP Premeeting

Z-motion

Position control only?

Load control method (from the bottom?) Linear

load?

Fixture of wafers (Backing sheet)

Anode size?

Smaller then offset?

Anode rotation

(Δ -x)

2nd solution line

Contamination of A and B
Chamber of Solution A
Chamber of Solution B } system

Anode with full contact
to wafers

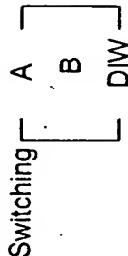
Fixture of the polishing pad

Wafer support

Ceramic plate (~25%)

Possible range? Strength?

Polishing Pad with holes



Voltage

Polarity switching
Range (V, I)
Relay switching

Menu till the end of October
OP. Menu

Recipe (~10steps) Currently 10 steps

Control z-motion } Displacement control is possible.

Control down force } Synchronization is possible.

[redacted] Module ???

2nd solution line

Wafer Rotation/oscillation table ...

Ultrapure D. I. water polishing?

Fukunaga
02.8.10

redacted 検討会 (#2) 議事録.txt
redacted プロジェクトメンバ各位殿

議事録送付致します。

二 (#2) redacted 検討会 議事録二

・日時: '02. 9. 3. (火) 8:30-10:20
・場所: V2-第一会議室
・出席者(敬称略): 木村、徳重、三島、神田、勝岡、国澤、牧野、南條、福永
(由) (記)



【主旨】 「redacted」装置の客先の提案仕様に関し理解を深め、最適対応策を検討する。

1. 「redacted」開発の背景と、客先の提案仕様について… 木村センタ長
 - ・客先 JDA Proposal に基づく開発内容説明
 - ・redacted との協業は”深く静かに”推進したい。情報はメンバ以外門外不出とする
 - ・φ200実験モジュールを3ヶ所 (redacted, サンノゼ、藤沢) に設置し、開発を加速したい。
 - ・めっきとポリッシュは最終的には一つの装置にまとめる。
 - ・redacted および redacted は、別途検討とする。

2. 実験モジュールの改造仕様について… 論議
 - ・客先提示の改造項目案に関して、実現性を論議した。
 - ・今秋設置のφ200モジュールは含浸めっきモジュールをベースにし、めっきモジュールとポリッシュモジュールとを別々に設置するのが効率的。(改造少なく、早期対応可。個々のプロセスをコンタミなしに検証可)
 - ・改造に供試可能なモジュールと引き当て(案)

redacted

サンノゼ

藤沢

ch.

te

- ・β2モジュール 1: et
- ・DRモジュール 1: p
- ・β2機 (11月～) 1: etch. 1: etch
- ・DR機 1: plate 1: plate

3. メンバ

- ・当面のメンバ: 福永 (由) ... 蓬台
- ... (めっき) 三島、神田、井出
- ... (ポリッシング) 徳重、並木
- ... (設計) 勝岡、国澤、牧野
- ... (制御) 南條

4. 次回打ち合せ

- ・日時: 9月9日 (月) 10時~12時
- ・場所: V2棟 第5会議室
- ・内容: 装置仕様、ユーティリティリスト、日程等

以上

Meeting Minute for the [redacted(project name)] Project (#2)

To all concerned members of the [redacted(project name)] project,
This document is the meeting minute for circulation.

= Meeting Minute for the [redacted(project name)] project (#2) =

- Date: Tuesday, September 3, 2002. From 8:30 a. m. to 10:20 a. m.
- Place: Meeting room 1, Building V2
- Attendants (title omitted): Kimura, Tokushige, Mishima, Kanda, Katsuoka, Kunisawa, Makino, Nanjo, Y. Fukunaga (Minute originator)

Fukunaga '02.9.3 08594

[Purpose of the meeting]: To understand the proposal of specification change for [redacted(project name)] tool made by the customer and to discuss the optimal actions.

1. Background of the "[redacted(project name)]" development and the customer-proposed specifications ... Executive General Manager Kimura

- Mr. Kimura explained the development based on the JDA Proposal of the customer.
- Ebara wants to develop the ties for collaboration with [redacted: the US company] "densely and silently". Information on the collaboration must be off-limit to others except for the concerned members.
- Ebara wants to implement the test modules for 200-mm wafer in three sites ([redacted: the US company], San Jose, Fujisawa) to accelerate the development.
- The plating module and the polishing module will finally be integrated.
- [redacted] and [redacted] will be discussed separately.

2. Change of the test module specification ... Discussion

- The members discussed feasibility of the specification change proposed by the customer.
- It is efficient to manufacture the test modules for 200-mm wafers for the site implementation in coming autumn based on Ebara's impregnation plating module and to separately install the plating module and the polishing module. (Using this configuration, we do not require large-scaled modification; thus, can respond faster. We can verify individual processes without contamination.)
- The members discussed where the modules, which can be modified, are implemented (proposal).

	[redacted: the US company]	San Jose	Fujisawa
• β 2 module			1: etch.
• DR module			1: plate
• β 2 unit (from Nov.)	1: etch.	1: etch.	
• DR unit	1: plate	1: plate	

3. Members

- Members assigned for the present are as follows.

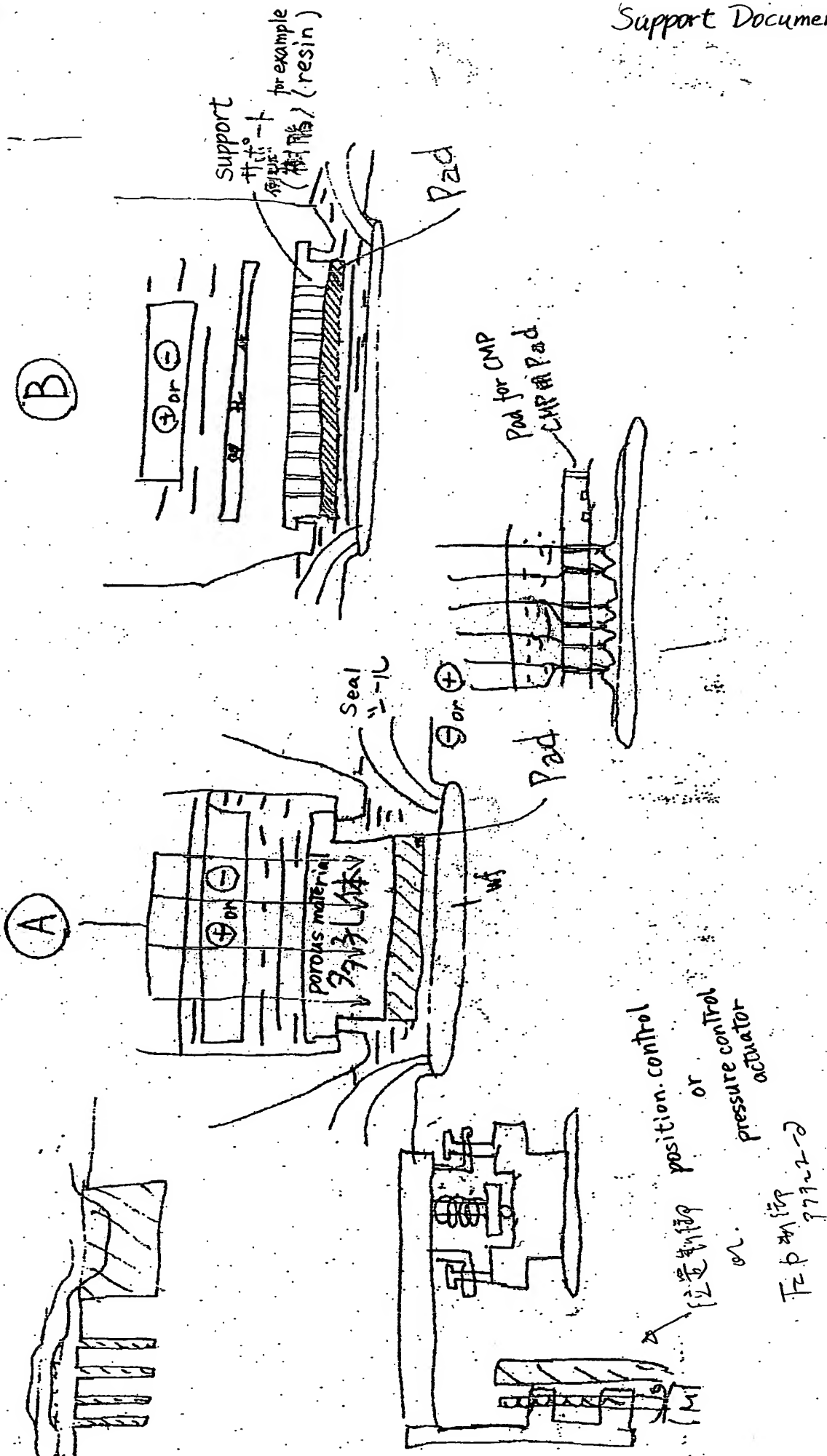
Y. Fukunaga	...	Hodai
	(Plating)	Mishima, Kanda, Ide
	(Polishing)	Tokushige, Namiki
	(Design)	Katsuoka, Kunisawa, Makino
	(Control)	Nanjo

4. Next meeting

Support Document B

- Date: Monday, September 9. From 10:00 a. m. to 12:00 a. m.
- Place: Meeting room 5, Building V2
- Agendas: Unit specifications, utility test, schedule, etc.

END OF DOCUMENT



五

(H2)

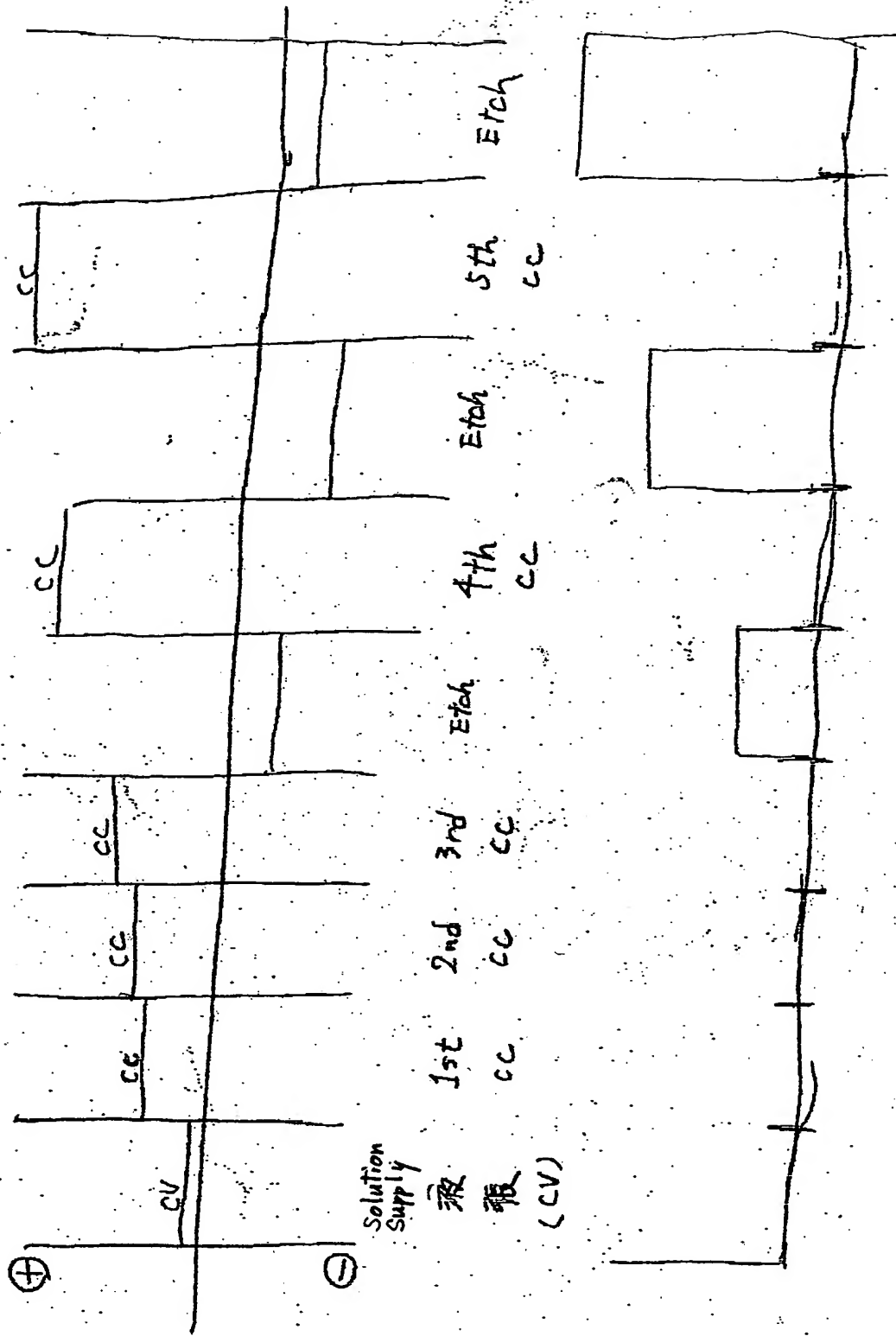
(Current)

Pressure

大田

Liquid

從



知的財産部 久保課長殿 へ 国米

IA103-3745-5745

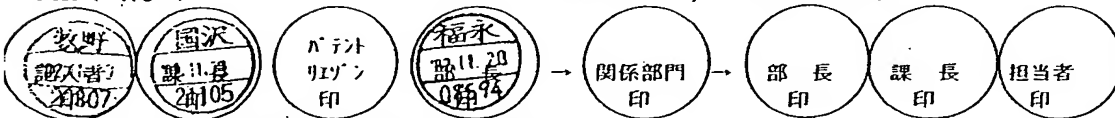
発明等届出書 (1/2) (1.特許) 2.意匠 3.その他) *1

(補足書 1.有 (2.無)

社外秘

Post (718)

Post () Post (52) 知的財産部



知財部 受付日/No.

2/2の依頼元上長記入欄の捺印欄も忘れなく御捺印下さい。

依頼日(西暦) 年 月 日

依頼元 Doc.No. 718-E2M20-1

② 太枠内をご記入下さい。

依頼元部門	(部門コード) (718)	区分(本部)	1. 管理 2. 情報・通信 3. 営業 4. 環境エンジニアリング 5. 風水力 6. 新材料・精密・電子 7. 精微・電子 8. 荏原総合研究所 9. 荏原ボイラ 10. 荏原工業洗浄 11. 荏原冷熱システム 12. その他
部門名	第1開発センター 第2プロセス開発室	関係部門印	
書類送付先	氏名: 牧野 夏木	部長印	
担当者	個人コード: 20307	課長印	
	(Post: 718 Tel: 9057)	担当者印	

発明等の名称	電解処理装置		
キーワード	パッド 多孔体 めっき エッチング 研磨 電解研磨		
関連する製品又は技術	含浸めっき装置		
製品の性格	① 重点拡販機種である	2. 重点拡販機種でない	研番成果 研 No. L-02D54709

職務発明について	① 職務発明である ② 職務発明ではないが、職務発明と同等の条件で会社に譲渡する ③ 職務発明ではなく、本発明等に関する一切の権利につき、その譲渡について会社と交渉する →右欄に捺印して知的財産部に送付してください。下の社内発明者記入欄の ところの譲渡確認印欄には捺印しないで下さい。	→下の社内発明者記入欄のところの 譲渡確認印欄に捺印してください (捺印欄)
----------	--	--

※2 「社内発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)、荏原冷熱システム(ERS)の発明者等のみ記入する。

下欄はEBRの発明者等だけに適用する。	社内発明者計 名 ※2	所属部門名	Post Tel	個人コード (5桁)	氏名	権利 持分	譲渡 確認印	米国 在住	
上記の職務発明等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社(株式会社荏原製作所)に譲渡したことを確認します。		1	第1開発センター 第2プロセス開発室 第2設計部	718 9057	20307	牧野 夏木	50%	(捺印)	
下欄はER、EICC、ERSの発明者等だけに適用する。		2	第1開発センター 第2プロセス開発室 第2設計部	718 9488	21105	国澤 淳次	50%	(捺印)	
上記の職務発明等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社()に譲渡したことを確認します。		3					%		
		4					%		
	5					%			

※3 米国に在住している場合はレ印を付ける。

出願形式 ① EBR 単独 2. EBR と EBR 以外の者との共同 3. EBR 以外の者の単独 4. その他

※4 荏原ボイラ(EB)、荏原工業洗浄(EICC)、荏原冷熱システム(ERS)は下記「EBR 以外の出願人名義」の欄に記入する。荏原総合研究所(ER)は記入要領を参照のこと。

出願手続会社	① EBR 2. EBR 以外の者 ()		
費用負担	① EBR 負担 2. 均等負担 3. その他		
EBR 以外の出願人名義※4 (計 名)	会社名又は氏名	連絡先 (住所、Tel、知財部門担当者名等)	権利持分
			%
			%

※5 「社外発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)、荏原冷熱システム(ERS)以外の発明者等を記入する。

社外発明者※5 (計 名)	会社名	氏名	住所	権利持分
				%
				%

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

発明等届出書 (2/2)

社外秘

出願 緩急	① 普通	理由: a. 社外発表 (右欄記入) b. 当社先願公開期限 c. 国内優先権主張期限	発表日: 年 月 日
	② 至急 (12月2日まで)		発表先:

契約関係※6	共同研究等契約書	1. 有 (相手:) (2) 無 (現在)
	共同出願契約書	1. 要 (作成担当: a. 当社 b. 相手先 ()) ② 不要

※6 共同出願、他社名義の出願とする根拠として契約書がある場合、契約書の写しを添付する。

調査実施状況	関連出願・公知例 出願内容に近い公知例 を2部添付する。	当社のもの	① 有 (特願 平11-367754) ② 無 (特願 2000-369201)
		他社のもの	① 有 (特開 2000-232078 (東芝)) ② 無

評価項目	発明の性質	発明の性質によりA, B, Cのうち一列を選択 (記号を○) して評価		
		A. 現在製品・技術の発明	B. 新事業製品・技術の発明	C. 先行アイデア発明
① 先行技術に対する技術的優位性		1. 同等	2. 若干優位	③ 相当優位
② 課題・手段の重要性		1. 不明	2. 普通	3. 重要
③ 独創性				④ 最重要
④ 本発明が対象とする製品の開発計画	1. 開発計画はない 2. 開発計画の終了段階である 3. 開発計画の中間段階である ④ 開発計画の初期段階である			1. 不明 2. 小 3. 中 4. 大
⑤ 本発明が製品に占める重要度	1. 小さい 2. やや小さい ③ やや大きい 4. 大きい			
⑥ 依頼元総合評価	1. 軽度 (1倍) 2. 通常 (2倍) ③ 重要 (3倍) 4. 最重要 (4倍)			

評価 計算	A列の発明	(①+②+④+⑤)×⑥= 42	出願要否	① 要 2. 公開技報でよい
	B列の発明			3. 不要 (理由:)
	C列の発明	(①+②+③+⑤)×⑥=		外国出願

特記事項 Cu配線メソッドのオーバープレート層を格段に少なくし、CMP工程負担を小さく
できることで代金を削減でき、より高品質な製品に貢献する発明。



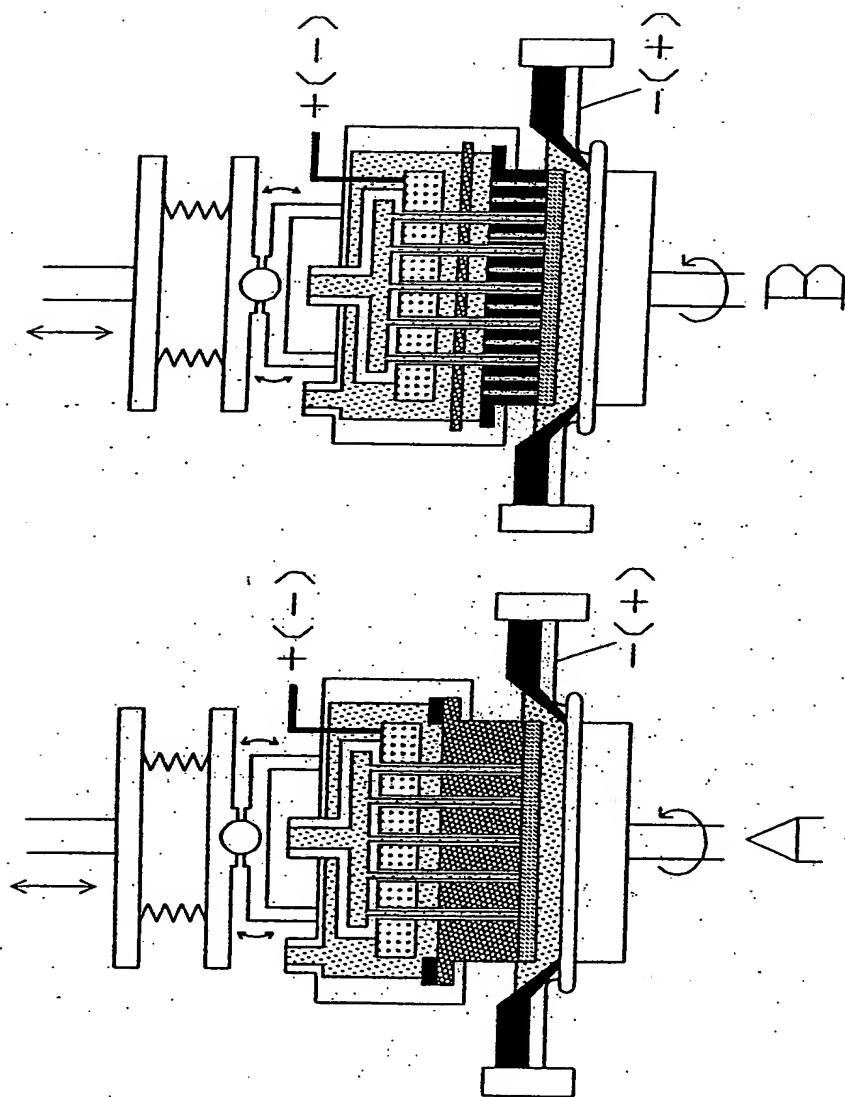
評価	① 特許性	1. なし	2. 小	3. 中	4. 大
	② 権利の広さ	1. 狭い	2. やや狭い	3. やや広い	4. 広い
	③ 本発明の回避困難度	1. 容易	2. やや困難	3. かなり困難	4. 不可
	④ 特許的総合評価	1. 軽度 (1倍) 2. 通常 (2倍) 3. 重要 (3倍) 4. 最重要 (4倍)			

知財部評価点: (①+②+③)×④=	総合評価※8	84以上 → S: 重点 64~83 → A: 重要 28~63 → B: 通常 27以下 → C: 出願せず	評価 承認者 印	担当者 印
依頼元評価点+知財部評価点=				

出願 形態	1. 通常出願	基礎出願番号:	特許事務所
	2. 国内優先権主張 3. 分割 4. 変更		
出願賞	1. 支給する 2. 支給しない (理由:)		
備考			

評価等に関するご意見は2週間以内にご連絡下さい

1. 電極と基盤の間に気孔率及び気孔径ともに任意な多孔体。
2. 多孔体は樹脂・セラミック・金属の単体及び複合体であり、織布・不織布を含む。
3. 多孔体を通して基盤表面への通液路がある。(連続気孔)
4. 多孔体はその気孔内に液体を保持することが可。
5. 多孔体の厚みは 1~20mm。
6. 電極と基盤の間には 1 つ以上の多孔体が存在。(複数可)
7. 多孔体を通じて電極側から基盤側へ及びその逆への液移動が可。(連続気孔)
8. 多孔体の一部及び全部をコーティング・焼結・封孔等の改質・表面処理してもよい。
9. 対抗電極は基盤最外周に存在する。
10. 電極は基盤表面に対し正・逆の電圧を時間軸に対して任意に印加することが可。
11. 多孔体の一部と基盤の一部は液体の薄膜を介して接触している。
12. その薄膜の厚さは 0~1mm とする。
13. 基盤処理中は液体薄膜厚さを任意に変更できる。(手段を有す)
14. 電極と多孔体は同じ空間にケーシングされている。
15. そのケースは基盤処理位置と非処理位置を任意に移動できる。(手段を有す)
16. 非処理位置では多孔体のコンディショニング(置換・洗浄・電解)が可。
17. 多孔体の一部には多孔体でない樹脂・セラミック・金属を含む。
18. 基盤処理中に多孔体と基盤との接触圧力を任意に変更できる。(手段を有す) 0~200g/cm²
19. ケースは基盤に対してチルト機構を有す。



5

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).

The column below is applicable only to inventors in EBR.	In-house inventor (Total: inventor(s)) ²		Dept.	Post Tel	Employee No. (five digits)	Name	Share of the rights	Seal for confirming the transfer	Living in U.S. ³
Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company (Ebara Corporation) upon invention.		1	Design Department Process Development Office 2 Development Center 1	718 9057	20307	Natsuki Makino	50%	Makino	
2		Design Department Process Development Office 2 Development Center 1	718 9488	21105					
The column below is applicable only to inventors in ER, EB, EICC, and ERS.		3							
Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company () upon invention.		4							
		5							

³ Put a checkmark if the investor is living in U.S.

6

Application type	<input checked="" type="radio"/> 1. Sole application by EBR 2. Joint application by EBR and a company other than EBR <input type="radio"/> 3. Sole application by a company other than EBR <input type="radio"/> 4. Other
------------------	--

7

*4 The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	<input checked="" type="radio"/> 1. EBR 2. Other than EBR ()			
Expense is:	<input checked="" type="radio"/> 1. Paid by EBR 2. Equally shared 3. Paid otherwise			
Applicant other than EBR ⁴ (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
			%	%

8

*5 The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor (Total: inventor(s)) ⁵	Company	Name	Address	Share of the interest
				%
				%

If descriptions of in-house/external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

1

Intellectual Property Dept. Mr. Kubo (Manager) <= Kunisawa

FAX 03-3745-5745

Notification of Invention (1/2) (1. Patent 2. Design 3. Other)* (Supplement: 1. Attached 2. N/A) **Confidential**

*Use this form for patent application filing. For utility model application, enclose "3. Other" with a circle and consult with Intellectual Property Dept.

Post (718)	Post ()	Post (52)	Intellectual Property Dept.
This form filled by: Makino	Manager: Kunisawa	Patent liaison:	General manager: Fukunaga
Related dept.:	General manager:	Manager:	Responsible person:
Date of receipt by Intellectual Property Dept./No.			

Be sure to affix the seal in the appropriate space of the "For the boss of the requesting dept." column on 2/2.

Date of request (Christian year): YYYY/MM/DD
 Requesting dept. Doc.No.: 718-E2N20-1

2

Fill in within heavy-line frames.

Requesting dept.	(Dept. code) Dept. name	(718) Process Development Office 2 Development Center 1	Category (Group)	1. Corporate 2. Strategic Information and Communication Systems 3. Sales 4. Environmental Engineering 5. Fluid Machinery & Systems 6. New and Renewable Energy ⑦ Precision Machinery	(Affiliate)	8. Ebara Research 9. Ebara Boiler Co., Ltd. 10. Ebara Industrial Cleaning Co., Ltd. 11. Ebara Refrigeration Equipment & Systems Co., Ltd. 12. Other ()
	Person responsible for the documents	Name: Natsuki Makino Employee No.: 20307 (Post: 718 Tel: 9057)				

3

Title of the invention	Electrochemical processing apparatus		
Keyword	Pad, porous material, plating, etching, polishing, and electropolishing		
Related product or technology	Impregnation plating apparatus		
Character of the product	① Sales-focused 2. Not sales-focused	Result of:	Job No. L-02D54709

4

About service invention	①. Yes	-> Affix the seal in the appropriate space of the "In-house inventor" column below. (Affix the seal here.)
	2. No; however, I transfer the invention to the Company under terms and conditions equivalent to those for service inventions. 3. No; I negotiate with the Company about terms and conditions of the transfer of any and all rights to the invention. -> Affix the seal in the right column and send this form to Intellectual Property Dept. Do not affix the seal in the "In-house inventor" column below.	

Confidential

9

Urgency of application filing	1. Normal ② High (by December 2.) Reason: a. External release (Fill the right column.) b. Deadline for publication of our prior application c. Deadline for claiming domestic priority Collaboration contract	Released on: YYYY/MM/DD Released to:
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10

Related contract ⁶	Written contract for joint research	1. Available (partner:) ② N/A (current)
	Written contract for joint filing of patent applications	1. Required (Prepared by: a. Us b. Partner ()) ② Not required

⁶ When there is a written contract that justifies the joint filing or filing under other name, attach a copy of it to this form.

11

Prior-art search	Related application and prior art: Attach two items of prior art related to the application.	Ours	① Available (Application No. Heisei 11-367754, Application No. 2000-369201) 2. N/A
1. Done (Fill the right column.) ② Not done		Others'	① Available (Publication No. 2000-232078 (Toshiba)) 2. N/A

12

Nature of invention	Choose A, B, or C (enclose with a circle), considering the nature of the invention.		
Evaluation item	A. Invention for current products/technologies	① B. Invention for new products/technologies	C. Invention of new ideas
(1) Technical superiority over prior art	1. None 2. A little ③ Considerable 4 Very large		
(2) Severity of challenge/means	1. Unknown 2. Normal 3. High ④ Very high		
(3) Originality	1. Unknown 2. Low 3. Medium 4. High		
(4) Development project for products based on the invention	1. N/A 2. In the final stage 3. In the intermediate stage ④ In the early stage		
(5) Importance of the invention to the products	1. Low 2. Rather low ③ Considerably high 4. High		
(6) Overall judgment by the requesting side	1. Less important (single) 2. Moderate (double) ③ Important (triple) 4. Significant (quadruple)		

13

Calculation for rating of the evaluation	For inventions of A or B	$((1)+(2)+(4)+(5)) \times (6) = 42$	Filing of the patent application is:	① Required 2. Not required; it should be published on Journal of Technical Disclosure. 3. Not required (reason:)
	For inventions of C	$((1)+(2)+(3)+(5)) \times (6) =$	Foreign filing of the patent application is:	① Required (country name: U.S, Europe, and Korea) 2. Not required 3. Not determined

14

Special note	This invention relates to a next-generation plating apparatus that greatly reduces overplating of CU wiring to minimize the load of the CMP process and its head structure of the key element of the apparatus.	Boss's seal of approval: Fukunaga
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15

Evaluation	(1) Patentability	1. None 2. Low 3. Medium 4. High
	(2) Scope of rights	1. Narrow 2. Rather narrow 3. Considerably wide 4. Wide
	(3) Indispensability of the invention to the products	1. Low 2. Rather low 3. Considerably high 4. Indispensable
	(4) Overall judgment on patenting the invention	1. Less important (single) 2. Normal (double) 3. Important (triple) 4. Significant (quadruple)

16

Evaluation by Intellectual Property Dept.: $((1)+(2)+(3)) \times (4) =$ *7
Total of the evaluation values by the requesting side and Intellectual Property Dept. *7

Overall evaluation *8	84 or more -> S: Significant 64 to 83 -> A: Important 28 to 63 -> B: Normal 27 or lower -> C: Not apply
-----------------------	--

Evaluation Approver Seal	Evaluation Approver Seal
--------------------------	--------------------------

*7 Enter the evaluation values into the formula.

*8 Place a circle on the appropriate item of the evaluation level.

17

Application category	1. Regular application	Original application No.:	Patent firm
	2. Domestic priority		
	3. Division		
	4. Change		
Award for filing the patent application		1. Will be offered 2. N/A (reason:)	
Remarks			

IPW-001 (Rev. 1.5)

Should you have any comment on the evaluation, contact us within two weeks.

1. A porous material having optional porosity and pore diameter to be placed between an electrode and a substrate.
2. The porous material is resin, ceramic, or metal or a compound of them, including woven or non-woven fabrics.
3. The porous material allows a liquid to flow through it onto the substrate surface (continuous pores).
4. The porous material can retain the liquid in the pores.
5. The porous material is 1-mm to 20-mm thick.
6. One or more pieces of the porous material can be placed between the electrode and the substrate (multiple pieces of the material can be used).
7. The porous material allows the liquid to move from the electrode side to the substrate side or vice versa (continuous pores).
8. The porous material can be wholly or partly coated, sintered, or reformed/surface-treated such as sealing.
9. A counter-electrode is located on the farthest circumference of the substrate.
10. The electrode can apply positive or negative voltage to the substrate surface anytime.
11. The porous material is partly in contact with the substrate through a medium of a liquid film.
12. The liquid film is 0-mm to 1-mm thick.
13. Thickness of the liquid film can be freely changed during substrate processing (having an appropriate method).
14. The electrode and the porous material are cased in a same space.
15. The case can be freely moved between the substrate processing position and the nonprocessing position (having an appropriate method).
16. The porous material can be conditioned (replacement of liquid, cleaning, and electroprocessing) on the non-processing position.
17. The porous material partly contains non-porous resin, ceramic, and metal.
18. The contact pressure between the porous material and the substrate can be freely changed in a range from 0 to 200 g/cm² (an appropriate means required).
19. The case has a tilt mechanism for the substrate.
- 20.

[発明部門メニューへ](#) [事業本部特許部メニューへ](#)

社外秘

一時保存したものに追記する場合、または、承認／否認する場合、上部の「編集」リンクをクリックしてください。

発明等届出書

届出日: 2003/11/12

知的財産部受付番号: K1030635 受付日: 2003/11/20

[依頼元担当一記入欄](#) [▼依頼元上長一記入欄](#) [▼事業本部特許部一記入欄](#) [▼ワークフロー情報](#)

★は必須入力項目です。

▼依頼元担当一記入欄



①【依頼元情報】

会社★	01 荏原製作所	部門	V370ニプロ設計課
整理番号 (Doc.No.)	EB3216P		
担当者	会社区分+社員番号: 0121105 氏名: 國澤 淳次 TEL: 9488		
本部名★	PP 精密・電子		

②【基本情報】

国内／外国★	国内		
四法★	特許		
発明の名称★	電解処理装置及びその方法		
キーワード	めっき エッチング CMP 電解		
関連する製品名	めっき装置 エッチング装置 CMP装置		
関連する業務コード	その1	7B配線めっき装置	その2
研番	L-03D520		
研番依頼元	部署名	V370ニプロ設計課	
職務発明について★	1.職務発明である		



③【荏原製作所／荏原総合研究所／荏原電産の発明者】

	会社	社員番号／氏名 (会社区分+社員番号)	内線NO／ポストNO／E-mail	所属部門コード／名称	発明者の持分 (%)	米国在住	代表発明者★
1	EK0001/ 荏原製作所	0120307 牧野 夏木	内線NO: 9057 ポストNO: 718 E-mail: makino.natsuki@ebara.com	V370ニプロ設計課	E		Check
2	EK0001/ 荏原製作所	0121105 國澤 淳次	内線NO: 9488 ポストNO: 718 E-mail: kunisawa.junji@ebara.com	V370ニプロ設計課	E		
該当無しおよび予定発明者							



【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

--	--	--	--	--	--	--	--

会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1		TEL: E-mail:		
該当無しおよび予定発明者				



⑤ 【出願人】

コード／名称(略称)	住所連絡先など	権利持分(%)	費用負担(%)	手続担当★
1 EK0001 荏原製作所	本社住所: 連絡先住所:〒 部署:担当: TEL: FAX: E-MAIL:	E	E	担当
該当無しおよび予定出願人				



⑥ 【出願緩急】

出願緩急	出願希望日	発表先: 発表日: その他:
	理由	

⑦ 【契約関係】

契約書有無★	無	種類	
		その他	
相手先	1		
	2		
	3		
	4		
	5		
	その他		
契約書			
共同出願契約書作成★	不要	作成担当	
		相手先	
		その他	



⑧ 【調査実施状況】

調査状況★	未調査		
調査内容	検索式:		
	資料:		
競合メーカー	Nutool ノベラス セミツール A-MAT		

【関連出願公知例】

当社の関連出願公知例★	無		
1 号	ファイル		

	または文献名:		
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	

他社の関連出願公知例★		無	
1	号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	



⑩ 【特記事項】

特記事項	先に出願済(国内優先)のものに請求項を追加しました。明細案は別途羽田知財部篠塚様宛て送付済。
------	--

⑪ 【発明等説明書(明細書素案)】

明細書		図面		その他	
添付者:		添付者:		添付者:	
添付日:		添付日:		添付日:	

▲依頼元担当一記入欄 依頼元上長一記入欄 ▼事業本部特許部一記入欄 ▼ワークフロー情報

▼依頼元上長一記入欄

⑫ 【発明部門評価】

発明の性質	B:新事業製品・技術の発明
①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)	3. 相当優位
②課題・手段の重要性	3. 重要
③独創性 (発明の性質がCのときのみ必須)	0. 未評価
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)	3. 開発計画の中間段階である
⑤本発明が製品に占める重要度(割合)	4. 大きい
⑥依頼元総合評価	3. 重要
評価点	39点

出願要否	要(理由:)
外国出願要否	要
特記事項	本件国内優先出願のため、至急手続きお願い致します。

▲依頼元担当一記入欄 ▲依頼元上長一記入欄 事業本部特許部一記入欄 ▼ワークフロー情報

▼事業本部特許部一記入欄

⑬

部長記入欄	担当	坂口さん
	コメント	原稿が知財部篠塚さん宛送付されているそうです。原稿確認してください。
担当者記入欄	コメント	クレーム追加のための国内優先出願なのでOKとします。
	添付文書	
	作業終了サイン	坂口：終了

▲依頼元担当一記入欄 ▲依頼元上長一記入欄 ▲事業本部特許部一記入欄 ワークフロー情報

▼ワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara.jp

現在の承認者:

要求 ID NTNN-5T89BU

ステータス: 完了

⑭

申請者	承認者
junji kunisawa/e/ebara.jp	<div> <div>→</div> <div> akihiko tashiro/e/ebara.jp yukio fukunaga/e/ebara.jp seimitsu zzchizai/e/ebara.jp masamichi nakashiba/e/ebara.jp </div> </div>

▼承認者情報

⑮

申請者名	申請日	CCメール
junji kunisawa/e/ebara.jp	2003/11/12	natsuki makino/e/ebara.jp

⑯

承認者役職	承認者名	承認期限	ステータス	承認日	CCメール
発明者上司	(承認不要)				
リエソン	akihiko	2003/11/19	承認	2003/11/12	

	tashiro/e/ebara_jp				
部長	yukio fukunaga/e/ebara_jp	2003/11/19	承認	2003/11/12	
事業部側特許部門	seimitsu zzchizai/e/ebara_jp	2003/11/19	承認	2003/11/19	
知的財産部-部長	masamichi nakashiba/e/ebara_jp	2003/11/26	代理承認	2003/11/20	

▼コメント

CN=akihiko tashiro/OU=e/0=ebara_jp 承認 2003/11/12 17:37:47 本件、承認いたします。
 CN=yukio fukunaga/OU=e/0=ebara_jp 承認 2003/11/12 20:16:43 承認します
 CN=seimitsu zzchizai/OU=e/0=ebara_jp 承認 2003/11/19 20:02:43 承認します。
 CN=masaaki miyazaki/OU=e/0=ebara_jp 代理承認 2003/11/20 14:02:53 中柴B打ち合わせ中につ
 き宮崎代理受入2003.11.20

To the menu for the dept. of the inventor(s) | To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: November 12, 2003

Intellectual Property Dept's receipt No.: K1030635 Date of receipt: November 20, 2003

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name ★	01 Ebara Corporation	Dept.	V370 Design Department Process Development Office 2 Development Center 1
Reference No. (Doc.No.)	EB3216P		
Responsible person	Company category + Employee No.: 0121105 Name: Junji Kunisawa TEL: 9488		
Group name★	PP Precision Machinery		

2 [Basic information]

Domestic/foreign ★	Domestic		
IP category ★	Patent		
Title of the invention	Electrochemical processing apparatus and its method		
Keyword	Plating, etching, CMP, and electrochemical processing		
Names of related products	Plating apparatus, etching apparatus, and CMP apparatus		
Related job code	No. 1	7B Wire plating apparatus	No. 2
Job No.	L-03D520		
Requesting dept.	Dept. name	V370 Design Department Process Development Office 2 Development Center 1	
About service invention ★	1. Yes		

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor ★
1	EK0001/ Ebara Corporation	0120307 Natsuki Makino	Extension No.: 9057 Post No.: 718 E-mail: makino.natsuki@ebara.com	V370 Design Department Process Development Office 2 Development Center 1	E		Check
2	EK0001/ Ebara Corporation	0121105 Junji Kunisawa	Extension No.: 9488 Post No.: 718 E-mail: kunisawa.junji@ebara.com	V370 Design Department Process Development Office 2 Development Center 1	E		
N/A and potential inventor(s)							

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1			TEL: E-mail:	E	
N/A and potential inventor(s)					

5 [Applicant]

Code/name (abbreviation)	Contact address, etc.	Share of the rights (%)	Share of the costs (%)	Prosecution by: ★
EK0001 Ebara Corporation	Headquarter address: Contact address:〒 Dept.: Responsible: TEL: FAX: E-mail:	E	E	Responsible person
N/A and potential inventor(s)				

6 [Urgency of application filing]

Urgency	Preferred data of filing Reason	Released to: Released on: Other:

7 [Related contract]

Written contract ★	N/A	Type Other
Partner	1 2 3 4 5 Other	
Contract		
Preparation of contract documents for joint application filing ★	Not required	Prepared by: Partner Other

8 [Prior-art search]

Prior-art search ★	Not done
Search details	Search formula: Material:
Competitor	Nutool, Novellus, Semitool, and A-MAT

9 [Related application and prior art]

Ours: ★	N/A
1 No. or document title:	File
2 No. or document title:	File
3 No. or document title:	File
4 No. or document title:	File
5 No. or document title:	File

Others': ★	N/A
1 No. or document title:	File
2 No. or document title:	File
3 No. or document title:	File
4 No. or document title:	File
5 No. or document title:	File

10 [Special note]

Special note	Claims have been added to the application already filed (domestic priority). The specification draft has been sent to Mr. Shinozuka of Intellectual Property Dept. at Haneda separately.
--------------	--

11 [Description of invention (specification draft)]

Specification	Drawings	Others
Attached by:	Attached by:	Attached by:
Attached on:	Attached on:	Attached on:

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
---	-------------------------------------	---------------------------------	------------------------

▼ For the boss of the requesting side

12 [Evaluation by the dept. of the inventor(s)]

Nature of the invention	B. Invention for new products/technologies
(1) Technical superiority over prior art (Quality improvement, cost reduction, energy saving, etc.)	3. Considerable
(2) Severity of challenge/means	3. High
(3) Originality (Enter data if the nature of the invention is C.)	0. Null
(4) Project for products based on the invention (development, sales, etc) (Enter data if the nature of the invention is A or B.)	3. In the intermediate stage
(5) Importance of the invention to the products	4. High
(6) Overall judgment by the requesting side	3. Important
Rating of evaluation	39 points
Filing of the patent application is:	Required (reason:)
Foreign filing of the patent application is:	Required
Special note	The application should be filed as immediately as possible because a domestic priority application will be filed for it.

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
---	---------------------------------------	-------------------------------	------------------------

13 ▼ For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	The draft has been sent to Mr. Shinozuka of Intellectual Property Dept. Check the draft.
Responsible person:	Comment	I approve the request because this is a domestic priority application for adding a claim.
	Attachment	
	Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
---	---------------------------------------	---------------------------------	----------------------

▼ Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5T89BU

Status: completed

14

Requested by:		Approved by:
junji kunisawa/e/ebara_jp		akihiko tashiro/e/ebara_jp yukio fukunaga/e/ebara_jp seimitsu zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼ Approver information

15

Requested by:	Requested on:	CC mail
junji kunisawa/e/ebara_jp	November 11, 2003	natsuki makino/e/ebara_jp

16

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	(Approval not required)				
Liaison	akihiko tashiro/e/ebara_jp	November 19, 2003	Approved	November 12, 2003	
General manager	yukio fukunaga/e/ebara_jp	November 19, 2003	Approved	November 12, 2003	
Patent Dept. of the Group	seimitsu zzchizai/e/ebara_jp	November 19, 2003	Approved	November 19, 2003	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	November 26, 2003	Approved by a proxy	November 20, 2003	

▼ Comment

CN=akihiko tashiro/OU=e/0=ebara_jp Approved November 12, 2003 17:37:47 I approve the request.
 CN=yukio fukunaga/OU=e/0=ebara_jp Approved November 12, 2003 20:16:43 OK.
 CN=seimitsu zzchizai/OU=e/0=ebara_jp Approved November 19, 2003 20:02:43 OK.
 CN=masaaki miyazaki/OU=e/0=ebara_jp Approved by a proxy November 20, 2003 14:02:53 Mr. Nakashiba is in a meeting; so Miyazaki, or his proxy, approves the request. November 20, 2003

発明部門メニューへ

事業本部特許部メニューへ

社外秘

一時保存したものに追記する場合、または、記入／承認／否認する場合、上部の「編集」リンクをクリックしてください。

外国出願依頼書

発信日: 2003/05/31

依頼元担当一記入欄

▼依頼元上長一記入欄

▼事業本部特許部一記入欄

▼ワークフロー情報

★は必須入力項目です。

▼依頼元担当一記入欄



①【依頼元情報】

会社	01 荏原製作所	部門	V370V第二ブ設計
整理番号			
担当者	社員番号: 0120307	氏名: 牧野 夏木	TEL: 9320

②【基本情報】

外国出願対象の出願	知的財産部受付番号: K1020686 四法区分: 特許 出願番号: 2002-350529 出願日: 2002/12/02 <div data-bbox="435 1014 574 1056" data-label="Text"> <input type="checkbox"/> <input type="checkbox"/> </div> 発明の名称: 電解処理装置及びその方法
出願国★	アメリカ
出願理由★	平坦化めっきの重要発明であるため



③【上記対象出願とまとめて外国出願したい案件】

※当該発明も1行目に記載されています

	国	四法区分	出願番号	出願日
1				
2				
3				
4				
5				
6				
7				
8				
9				
10				

補足事項



④【荏原製作所／荏原総合研究所／荏原電産の発明者】

会社	社員番号／氏	内線NO／ポストNO／E-mail	所属部門コード／名	持分	米国在	代表発
----	--------	-------------------	-----------	----	-----	-----

		名 (会社区分+社員番号)	称	住	明者
1	EK0001/荏原製作所	0120307 牧野 夏木	内線NO: EK0001 ポストNO: 荏原製作所 E-mail: V370	V370V第二ブ設計	E%
2	EK0001/荏原製作所	0121105 國澤 淳次	内線NO: EK0001 ポストNO: 荏原製作所 E-mail: V370	V370V第二ブ設計	E%



⑤【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

	会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1			TEL: E-Mail:		



⑥【出願人】

	出願人コード／名称 (略称)	住所連絡先など	権利 持分	費用 負担	手続担 当
1	EK0001 荏原製作所	本社住所: 東京都大田区羽田旭町11番1号 連絡先住所: 〒144-8510 東京都大田区羽田旭町11-1 部署: 知的財産部 担当: 依田 正稔 TEL: 0337436289 FAX: 0337455745	E%	E%	担当



⑦【先行技術文献】

1	見出し(文献種別)	01 自社関連先行文献	添付者:
	内容(文献名)	特願平11-367754	添付日:
	該当箇所		
	関連性の説明		
	備考		
2	見出し(文献種別)	02 他社関連先行文献	添付者:
	内容(文献名)	特開2000-232078	添付日:
	該当箇所		
	関連性の説明		
	備考		
3	見出し(文献種別)	01 自社関連先行文献	添付者:
	内容(文献名)	特願2003-015236	添付日:
	該当箇所		
	関連性の説明		
	備考		
4	見出し(文献種別)	02 他社関連先行文献	添付者:
	内容(文献名)	USP6413403	添付日:

	該当箇所		
	関連性の説明		
	備考		
5	見出し(文献種別)	02 他社関連先行文献	添付者: 添付日:
	内容(文献名)	USP6413388	
	該当箇所		
	関連性の説明		
	備考		
6	見出し(文献種別)	02 他社関連先行文献	添付者: 添付日:
	内容(文献名)	USP6409904	
	該当箇所		
	関連性の説明		
	備考		
7	見出し(文献種別)	02 他社関連先行文献	添付者: 添付日:
	内容(文献名)	USP6402925	
	該当箇所		
	関連性の説明		
	備考		
8	見出し(文献種別)		添付者: 添付日:
	内容(文献名)		
	該当箇所		
	関連性の説明		
	備考		
9	見出し(文献種別)		添付者: 添付日:
	内容(文献名)		
	該当箇所		
	関連性の説明		
	備考		
10	見出し(文献種別)		添付者: 添付日:
	内容(文献名)		
	該当箇所		
	関連性の説明		
	備考		



⑧【発明等説明書(明細書素案)】

明細書		図面		その他	
添付者:		添付者:		添付者:	
添付日:		添付日:		添付日:	

▲依頼元担当一記入欄 依頼元上長一記入欄 ▼事業本部特許部一記入欄 ▼ワークフロー情報

▼依頼元上長一記入欄

⑦

特記事項	銅配線の平坦化めっきに必要な装置構成、特にアノードヘッドの構造に関する発明であり、協業先に装置を納めています。(US)
------	---

▲依頼元担当一記入欄 ▲依頼元上長一記入欄 事業本部特許部一記入欄 ▼ワークフロー情報

▼事業本部特許部一記入欄

⑩

部長記入欄	担当	坂口さん
	コメント	お願いします。
担当者記入欄	コメント	内容確認の結果、外国出願要と考えます。
	添付文書	
	添付者:	
	添付日:	
	作業終了サイン	坂口 : 終了

▲依頼元担当一記入欄 ▲依頼元上長一記入欄 ▲事業本部特許部一記入欄 ▼ワークフロー情報

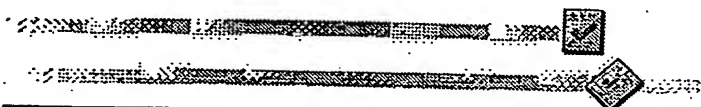
▼ワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara_jp

現在の承認者:

要求 ID NTNN-5LNM4B

ステータス: 完了



申請者	承認者
natsuki makino/e/ebara_jp	<div>⇒</div> akihiko tashiro/e/ebara_jp yukio fukunaga/e/ebara_jp seimitsu zzchizai/e/ebara_jp fumio kondo/e/ebara_jp

▼承認者情報

申請者名	申請日	CCメール
natsuki makino/e/ebara_jp	2003/05/31	junji kunisawa/e/ebara_jp

13

承認者役職	承認者名	承認期限	ステータス	承認日	CCメール
発明者上司	(承認不要)				
リエゾン	akihiko tashiro/e/ebara_jp	2003/06/07	承認	2003/06/03	
部長	yukio fukunaga/e/ebara_jp	2003/06/10	承認	2003/06/03	
事業部側特許部門長	seimitsu zzchizai/e/ebara_jp	2003/06/10	承認	2003/06/11	

▼コメント

CN=akihiko tashiro/OU=e/0=ebara_jp 承認 2003/06/03 13:49:32 本申請を承認します
 CN=yukio fukunaga/OU=e/0=ebara_jp 承認 2003/06/03 20:44:10 承認します
 CN=seimitsu zzchizai/OU=e/0=ebara_jp 承認 2003/06/11 20:15:14 外国出願承認します。

◆アクション

To the menu for the dept. of the inventor(s) To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Request of foreign filing

Submitted on: May 31, 2003

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
---	---------------------------------------	---------------------------------	------------------------

Never fail to fill ★-marked columns.

▼ For the responsible in the requesting side

1 [Information of the requesting side]

Company	01 Ebara Corporation	Dept.	V370 Design Department Process Development Office 2 Development Center 1
Reference No.			
Responsible person	Employee No.: 0120307 Name: Natsuki Makino TEL: 9320		

2 [Basic information]

Request for foreign application filing	Intellectual Property Dept's receipt No.: K1020686 IP category: Patent Application No. 2002-350529 Filing date: December 2, 2002 To File Wrapper Title of the invention: Electrochemical processing apparatus and its method
Country of filing ★	United States of America
Reason for filing ★	Important invention for plating and electropolishing

3 [Application(s) that should be foreign-filed together with the described above]

*The invention in question is listed in the first row.

	Country	IP category	Application No.	Filing date
1				
2				
3				
4				
5				
6				
7				
8				
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10				

Supplement		
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4 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.A.	Representative inventor
1	EK0001/ Ebara Corporation	0120307 Natsuki Makino	Extension No.: EK0001 Post No.: Ebara Corporation E-mail: V370	V370 Design Department Process Development Office 2 Development Center 1	E%		
2	EK0001/ Ebara Corporation	0121105 Junji Kunisawa	Extension No.: EK0001 Post No.: Ebara Corporation E-mail: V370	V370 Design Department Process Development Office 2 Development Center 1	E%		

5 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd. and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.A.
1			TEL: E-mail:		

6 [Applicant]

	Applicant code/name (abbreviation)	Contact address, etc.	Share of the rights	Share of the costs (%)	Prosecution by:
1	EK0001 Ebara Corporation	Headquarter address: 11-1 Asahi-machi, Haneda, Ohta-ku, Tokyo Contact address: 11-1 Asashi-machi, Haneda, Ohta-ku, Tokyo 144-8501 Dept.: Intellectual Property Dept. Responsible: Masatoshi Yoda TEL: 0337436289 FAX: 0337455745	E%	E%	Responsible person

7 [Documents of related prior art]

1	Index (document category)	01 Our related prior art	Attached by: Attached on:
	Detail (title)	Application No. Heisei 11-367754	
	Corresponding part		
	Relativeness		
	Remarks		
2	Index (document category)	02 Others' related prior art	Attached by: Attached on:
	Detail (title)	Publication No. 2000-232078	
	Corresponding part		
	Relativeness		
	Remarks		
3	Index (document category)	01 Our related prior art	Attached by: Attached on:
	Detail (title)	Application No. 2003-015236	
	Corresponding part		
	Relativeness		
	Remarks		
4	Index (document category)	02 Others' prior art	Attached by: Attached on:
	Detail (title)	USP6413403	
	Corresponding part		
	Relativeness		
	Remarks		
5	Index (document category)	02 Others' prior art	Attached by: Attached on:
	Detail (title)	USP6413388	
	Corresponding part		
	Relativeness		
	Remarks		
6	Index (document category)	02 Others' prior art	Attached by: Attached on:
	Detail (title)	USP6409904	
	Corresponding part		
	Relativeness		
	Remarks		
7	Index (document category)	02 Others' prior art	Attached by: Attached on:
	Detail (title)	USP6402925	
	Corresponding part		
	Relativeness		
	Remarks		
8	Index (document category)		Attached by: Attached on:
	Detail (title)		
	Corresponding part		
	Relativeness		
	Remarks		
9	Index (document category)		Attached by: Attached on: Attached by: Attached on:
	Detail (title)		
	Corresponding part		
	Relativeness		
	Remarks		
10	Index (document category)		Attached by: Attached on:
	Detail (title)		
	Corresponding part		
	Relativeness		
	Remarks		

8 [Description of invention (specification draft)]

Specification		Drawings		Others	
Attached by:		Attached by:		Attached by:	
Attached on:		Attached on:		Attached on:	

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
---	-------------------------------------	---------------------------------	------------------------

9 ▼For the boss of the requesting side

Special note	This invention relates to an apparatus configuration required for plating and electropolishing of Cu wiring, more particularly its anode head structure. We have delivered the apparatus to the collaboration partner (U.S.).
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▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
---	---------------------------------------	-------------------------------	------------------------

10 ▼For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	Please.
Responsible person:	Comment	I think foreign filing of the application is required because it has been determined to be important.
	Attachment	Attached by: Attached on:
	Sign of completion	Sakaguchi: Completed

▲ For the responsible in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
--	---------------------------------------	---------------------------------	----------------------

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5LNM4B

Status: completed

11

Requested by:		Approved by:
natsuki makino/e/ebara_jp		akihiko tashiro/e/ebara_jp yukio fukunaga/e/ebara_jp seimitsu zzchizai/e/ebara_jp fumio kondo/e/ebara_jp

▼Approver information

12

Requested by:	Requested on:	CC mail
natsuki makino/e/ebara_jp	May 31, 2003	junji kunisawa/e/ebara_jp

13

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	(Approval not required)				
Liaison	akihiko tashiro/e/ebara_jp	June 7, 2003	Approved	June 3, 2003	
General manager	yukio fukunaga/e/ebara_jp	June 10, 2003	Approved	June 3, 2003	
Patent Dept. of the Group	seimitsu zzchizai/e/ebara_jp	June 10, 2003	Approved	June 11, 2003	

▼Comment

CN=akihiko tashiro/OU=e/0=ebara_jp Approved June 3, 2003 13:49:32 I approve the request.
CN=yukio fukunaga/OU=e/0=ebara_jp Approved June 3, 2003 20:44:10 OK.
CN=seimitsu zzchizai/OU=e/0=ebara_jp Approved June 11, 2003 20:15:14 I approve the foreign
filing.

◆Action

February 6, 2004

No.	Application No.	Filing Date	Title	Abstract	Main Claims		Claims Filed	Claims Allowed	Foreign Applications
					Method	Apparatus			
1	2002-242726	22-Aug-02	Electrolytic processing apparatus	Electrolysis apparatus, comprising/ a substrate holder having an electrical contact to a periphery of a substrate/ an electrode facing the substrate/ a control element of electrical field between the electrode and the substrate, the element having almost the same diameter with the substrate and/ a drive mechanism for relative parallel movement of the substrate and the electrode.	0	1	5 Ebara	Not Filed	
2	2002-350529	02-Dec-02	Apparatus and method for electrolytic processing	redacted	1	2	9 Ebara	US only	
3	2003-015235	23-Jan-03	Plating method and apparatus therefor	redacted	1	1	11 Ebara	Not Filed	
4	2003-015236	23-Jan-03	Plating method and plating apparatus	redacted	1	1	12 Ebara	PCT, TW	
5	2003-025159	31-Jan-03	Apparatus for electrolytic processing	redacted	0	4	24 Ebara	US only	
6	2003-111327	16-Apr-03	Plating method for semiconductor substrate	redacted	1	0	26 Ebara	Under Preparation	

Support Document G

Aug 2002)

No. Application		Filing Date	Title	Abstract	What Claims		Claims	Owner	Foreign Applications
					Method	Apparatus	Total		
7	2003-138521	16-May-03	Apparatus and method for electrolytic processing	redacted	1	3	9	Ebara	Under Preparation
8	2003-145017	22-May-03	Apparatus for supplying, recovering, measuring and replenishing electrolyte	redacted	3	0	8	Ebara	Under Preparation
9	2003-148326	26-May-03	Substrate processing method and apparatus	redacted	2	1	14	Ebara	Under Preparation
10	2003-149827	27-May-03	Plating apparatus and plating method	redacted	1	1	24	Ebara	PCT, TW
11	2003-181236	05-Jun-03	Plating apparatus and plating method	redacted	1	1	16	Ebara	PCT, TW
12	2003-181237	05-Jun-03	Plating apparatus and electrolyte retaining method	redacted	0	1	5	Ebara	PCT, TW
13	2003-189791	13-Jun-03	Plating apparatus and plating method	redacted	1	1	10	Ebara	Not Decided

February 6, 2004

No.	Application No.	Filing Date	Title	Abstract	Method	Apparatus	Claims	Total	Claims	Foreign
14	2003-195406	10-Jul-03	Plating apparatus and plating method	redacted	2	2	14	Ebara	Not	Decided
15	2003-202515	28-Jul-03	Plating apparatus and plating method	redacted	1	1	8	Ebara/ redacted	Not	Decided
16	2003-310355	02-Sep-03	Apparatus for plating substrate	redacted	0	1	10	Ebara	Not	Decided
17	2003-313307	04-Sep-03	Apparatus for plating substrate	redacted	0	1	13	Ebara	Not	Decided
18	2003-314755	05-Sep-03	Method and apparatus for controlling electrolyte	redacted	2	2	20	Ebara	Not	Decided
19	2003-319055	10-Sep-03	Plating apparatus and plating method	redacted	2	1	16	Ebara	Not	Decided

February 6, 2004

App. No.	App. No.	Filing Date	Title	Abstract	Main Claims		Claims Total	Owner	Foreign Application
					Method	Apparatus			
20	2003-371159	30-Oct-03	Apparatus and method for processing substrate	redacted	1	1	14	Ebara	Not Decided
21	2003-373391	31-Oct-03	Plating apparatus and plating method	redacted	1	1	15	Ebara	Not Decided
22	2003-399443	28-Nov-03	Apparatus and method for electrolytic processing	redacted	3	3	19a	redacted Ebara	Not Decided
23	2003-402008	01-Dec-03	Plating apparatus and plating method	redacted	1	1	20	Ebara	Not Decided

February 6, 2004

No.	Application No.	Filing Date	Title	Abstract	Main Claims		Claims		Foreign	
					Method	Apparatus	Total	Owner	Applicant	Applicant
24	2003-431211	25-Dec-03	Plating method and plating apparatus	redacted	1	1	14	a	redacted	Not Decided
25	2003-431448	25-Dec-03	Plating apparatus and plating method	redacted	1	1	10	Ebara	Not Decided	Not Decided
26			Plating apparatus and plating method of substrate	redacted	2	2	17	Ebara	Not Decided	Not Decided

February 6, 2004

App. No.	Filing Date	Title	Abstract	Main Claims		Claims Total	Other Applications	Foreign Applications
				Method Apparatus	System			
27		Substrate processing apparatus	redacted	0	9	43	Ebara	Not Decided
28		Plating apparatus and plating method of substrate	redacted	3	1	13	Ebara	Not Decided
29		Plating apparatus and plating method of substrate	redacted	1	2	18	Ebara	Not Decided

Meeting Minutes – The 2nd redacted /EBARA JDA Workshop

Date; February 5 & 6, 2004

Place; redacted

Attendees; redacted

Ebara – Manabu Tsujimura, Jay Horjuchi, Yukio Fukunaga, Koji Mishima, Norio Kimura, Ray Fang
Keisuke Namiki, Keiichi Kurashina, Isao Nambu, Dan O'Connell, Kenichi Sasabe,
Katsuyuki Musaka

Redacted

Redacted

Redacted

IP List Exchange (redacted /Kenichi Sasabe)

- There exist patent for additive distribution control for wide feature leveling by Ebara's competitor, which may interfere with current development activities on pad plating. (Ebara)
 - The patent explains superfill mechanism, which is different from flat overburden (redacted)
- redacted's disclosure on pad plating ready for Ebara's review (redacted)
 - Ebara filed original Japanese patent application on touch down plating with "porous element" in 1999.
 - Will review possible addition of claim and/or coinventor (Ebara)
 - Still possible to file US patent application with redacted as coinventor (redacted)
- redacted's disclosure for e-CMP chemistries to be filed as redacted's invention, while e-CMP apparatus with the method (chemistries) to be filed as redacted /Ebara co-invention (redacted)
- Ebara's Japanese patent application items #2, 4, 10, 11, 12, 14, 22, 23, 24 to be reviewed in regards to redacted's disclosure for possible addition of redacted as coinventor (redacted)
 - Will submit abstract translation on above items (Ebara)
- Ebara's Japanese patent application item #16 to be Ebara invention (redacted)
- Ebara's disclosure item #26 and 28 to be filed as redacted /Ebara co-invention (redacted)
 - Will submit abstract translation of the draft applications (Ebara)
- Ebara's disclosure item #20 can be the same content as redacted's disclosure (redacted)
 - Will submit abstract translation of the draft application (Ebara)

Action Plan
Action Item

Owner

Due

Redacted

- 16. Abstract translation of Ebara's Japanese patent application
(Item#2, 4, 10, 11, 12, 14, 22, 23, 24)
- 17. Abstract translation of Ebara's Japanese patent application draft
(Item#26, 28, 29)

K. Sasabe

~Feb'04

K. Sasabe

~Feb'04

Musaka, Katsuyuki, 午前 06:53 04/03/09 -0800, EBARA Patent Application Translations

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: "redacted (E-mail)" <redacted.com>
Cc: "Fukunaga, Yukio (E-mail)" <fukunaga.yukio@ebara.com>, "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>
Subject: EBARA Patent Application Translations
Date: Tue, 9 Mar 2004 06:53:01 -0800
X-Mailer: Internet Mail Service (5.5.2653.19)

redacted-san,

Thank you for your time and valuable inputs in our meeting yesterday although your busy schedule.

Please find attached summary of Ebara's patent application status. There are some corrections in the one I handed to you a hard copy yesterday (highlighted in red).

<<EBARA Applications_030904.xls>>

Attached below are translations of Ebara's Japanese patent applications which hard copies I handed to you today.

<<2003-015236(#4).doc>> <<2003-149827(#10).doc>> <<2003-161236(#11).doc>>
<<2003-161237(#12).doc>> <<2003-195406(#14).doc>>
<<2003-431211(#24).doc>> <<2004-022178(#26).doc>> <<2004-023256(#28).doc>>
<<K1040028(#29).doc>>

Also, attached below is the Ebara's US patent application. As I explained to you yesterday, the #2 which was filed in Japan on 12/2/02 was abandoned, then re-filed as #22 in Japan on 11/28/03, within 1 year from the original(#2) filing date. The US patent applications for #2 as well as #22 were also filed about the same time, 12/1/03, to obtain the priority of #2, within 1 year from its original(#2) filing date in Japan.

<<GEB1998US(#22).pdf>> <<GEB1998US_Image(#22).tif>>

Please review and advise us which you want us to amend for co-invention with redacted

Best Regards,
K.Musaka

P.S. I'm still waiting for a translation of #23. I'll e-mail it to you as soon as I receive it.



EBARA Applications 030904.xls



2003-015236(#4).doc



2003-149827(#10).doc



2003-161236(#11).doc



2003-161237(#12).doc



2003-195406(#14).doc



2003-431211(#24).doc



2004-022178(#26).doc



2004-023256(#28).doc



K1040028(#29).doc



GEB1998US(#22).pdf



GEB1998US Image(#22).tif

Musaka, Katsuyuki, 午後 08:47 04/05/07 +0900, S1 Project 特許の件

To: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
From: Yukio Fukunaga <fukunaga.yukio@ebara.com>
Subject: S1 Project 特許の件
Cc: 笹部憲一 <sasabe.kenichi@ebara.com>, mishima.koji@ebara.com
Bcc: fukunaga.yukio@ebara.com
Attached:

六平 様

昨日TELCONにて打ち合わせた標記の件で、#4、#10、#12、#14、#24の
対処の方向に関して、現在辻村役員に打診しております。

役員は本日不在でまだ内諾が得られておりませんので、大変恐縮ですが5月7日の
F-t-F meetingでは「共願」を匂わさず、「ECにて検討中」という表現に留めて
頂くようお願い致します。
内諾頂き次第ご連絡致します。

なお#26に関しては、内容が理解できる程度の翻訳資料を笹部さんに依頼をして
います。時間との関係でどこまでできるかまだ分かりませんが、クレームだけで
IBMに判断を仰いでも、ラチがあかないと考えています。

以上、取り急ぎお願いのみ致します。

福永(由)

Musaka, katsuyuki, PM 08:47 04/05/07 +09000, Regarding the SI Project patent

To: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
From: Yukio Fukunaga <fukunaga.yukio@ebara.com>
Subject: Regarding the S1 Project patent
Cc: Kenichi Sasabe <sasabe.kenichi@ebara.com>, mishima.koji@ebara.com
Bcc: fukunaga.yukio@ebara.com
Attached:

Dear Mr. Musaka,

Regarding the above subject we discussed at TELCON yesterday, I have contacted Mr. Tsujimura about how we think about our approach to #4, #10, #12, #14 and #24.

He is out today and I have not yet obtained his informal consent; therefore, I kindly request you to describe the matter in the F-t-F on May 7 only as "being reviewed at EC," instead of implying "joint application."

As soon as I obtained the informal consent, I will inform that to you.

Regarding #26, I have requested Mr. Sasabe to supply me with the documents translated enough to understand their contents. Due to the time limitation, I am not sure how much we can do. However, I believe asking [redacted: the US company] opinions only by supplying it with those claims does not help.

Here, I quickly note my request as above.

Y. Fukunaga

由, 11:25 04/05/21 +0900, Fwd: Export License に関する打合せ

To: 福永(由)室長殿, 三島部長殿, 国澤課長殿, 牧野殿, 赤井部長殿, 篠塚担当部長殿, 坂口担当部長殿
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: Export License に関する打合せ
Cc: 鈴木室長殿
Bcc:
Attached:

各位

Export Licenseに関する打合せを下記にて行いますので、ご出席お願い致します。

5月27日(木曜日) 9:00-12:00
藤沢 V2棟 第5会議室

特願2002-350529

特願2003-399443

の原稿作成、出願依頼、出願、国内優先の計画、国内優先の原稿作成、出願依頼、出願、外国出願依頼、外国出願など、この出願の発明から出願に到る過程の資料を調査の上、コピーをお持ちください。

出願打合せのノート、メモ、弁理士との相談のノート、これら出願に関する記載のある社内の報告書、e-mailなど、関連すると思われる全ての資料のコピーが必要です。
よろしくお願いします。

Date: Tue, 18 May 2004 18:06:53 +0900

To: 福永(由)室長殿, 三島部長殿, 国澤課長殿, 牧野殿, 赤井部長殿, 篠塚担当部長殿, 坂口担当部長殿

From: 笹部憲一 <sasabe.kenichi@ebara.com>

Subject: Export License に関する打合せ

各位

redacted の情報が入った出願を日本で米国より先に出願した件に関して、Export Licenseを取ろうとしています。

redacted

又このときに、各判断の記録や証拠があるか確認して行く必要があります。

牧野さん、国沢さんを含めて、どのような議論が為されてどのような判断をしたか、事実確認とストーリーの明確化を行いたいと思います。

ご都合の良いところで打合せしたいと思います。

今週は赤井さんが海外出張ですので、来週やりたいと思います。

火曜日(25日)、水曜日(26日)、木曜日(27日)で都合の悪い時間をご連絡ください。

打合せは藤沢で行う予定です。

発明から日本出願までに発生した事柄

2002. 6 EbaraがredactedにEBRのめっき槽地に付いて説明した。

2002. 8 redactedがEBRにJDPで実施したいことを説明した。

2002. 8 Presentationの資料をEBRは入手。

redactedとEBR(誰)がredactedに貸与する装置について相談。

この間、何があったのかな？

2002. 12. 2

EBRが日本出願

卷之四

redacted.

中國文明之異國本國出版
之書目之考

② 29 発明内容が“IDMの発明”と記載されている。

2002-8
→ ESR
redacted
T-117-4 & T-117-5
M352610 & M352611

redacted
ESR
送達
Spec 打合せ

○金源材にpaidなつた。+ F + エッティングと押瓦力とを組合せ。

合意，中國代理，特許生，礦山學士，
出，隨，之，最，大，功，勞，也。

2002, 10, 1

近藤 博雄、田澤 清田、合登、堀江 幸平、池
出所指示、水又得火指示

上海出版界

11.19

久得國文。作。保→保環。相當。及。

更 11/20? 原稿作成後報

2002.12.2 日本出版 2002-350429

(2002.10 50 2003.4 50)

2003. 7 7-7712-1 外因致宿核

9 郭政雄 検定 俗義 漢書で小高さん 山城神社にて

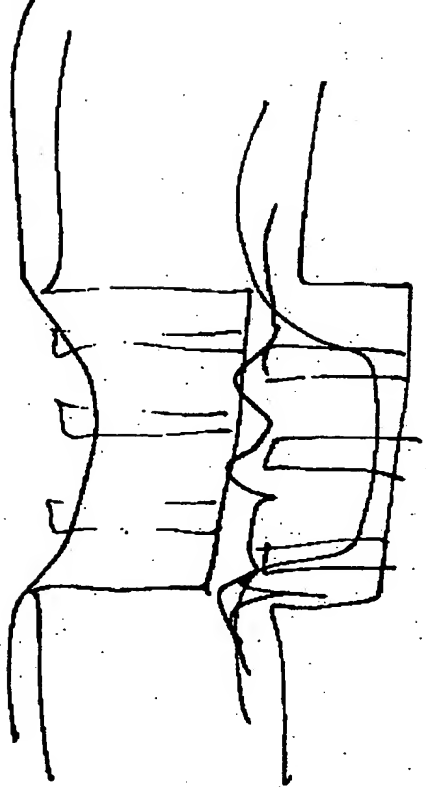
10.1
Tuy Fing.

10.23

盧允初

2003.11.28. 国内(臺大)

2003. 12. 1 US 454.116



2004.5.27

Y, 11:25 04/05/21 +0900, Fwd: Meeting regarding Export License

To: General Manager Y. Fukunaga, General Manager Mishima, Manager Kunisawa, Makino,
General Manager Akai, manager Shinozuka, Manager Sakaguchi

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Meeting regarding Export License

Cc: General Manager Suzuki

Bcc:

Attached:

To all concerned,

This message requests all concerned to attend the meeting about Export License as below.

Thursday May 27. From 9:00 a.m. to 12:00 a.m.

Meeting room 5 Building V2, Fujisawa Plant

Application No. 2002-350529

Application No. 2003-399443

The attendants are requested to check all data of processes from invention to filing of the two patents above, including patent drafting, request for filing, filing, scheduling for claiming the domestic priority, drafting for claiming the domestic priority, request for filing, filing, request for foreign filing, foreign filing, and bring the copies of them.

You must bring the copies of any kind of data if they seem to be related, including, but not limited to, notes taken in meetings for filing, memos, notes taken in consultation with our attorney, in-house reports containing articles relating to the filing, e-mails, and so on.

I call for your cooperation.

Date: Tue, 18 May 2004 18:06:53 +0900

To: General Manager Y. Fukunaga, General Manager Mishima, Manager Kunisawa, Makino,
General Manager Akai, Manager Shinozuka, Manager Sakaguchi

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Meeting regarding Export License

To all concerned,

Regarding the issue that we filed the patent applications including information of [redacted: the US company] in Japan prior to filing in the U.S.A., we are going to apply for the Export License.

[redacted]

As we summarize, we need to check records or evidences of each decision made upon each event.

With Mr. Makino and Mr. Kunisawa, I will check the facts and clarify the story, that is, what were discussed and what were decided through the sequences.

I'd like to hold the meeting when all of you are available.

Mr. Akai is on an overseas business trip this week; thus, the meeting will be held next week. Inform me when you are not available: on Tuesday (25th), Wednesday (26th), or Thursday (27th). The meeting will be held in Fujisawa.

Events occurred from invention to domestic filing

2002. 6 Ebara explained [redacted: the US company] of the plating apparatus of EBR.

2002. 8 [redacted: the US company] explained EBR that they wanted to reduce the invention to practice in the JDP.

EBR obtained the presentation data.

2002. 8 [redacted: the US company] and EBR (who) discussed the apparatus to be lent to [redacted: the US company].

I wonder what happened during this period?

2002. 12. 2 EBR filed the patent applications in Japan Patent Office.

- 2002.6 EBR -> [redacted: the US company] Explanation about the apparatus.
- 2002.8 [redacted: the US company]-> EBR Presentation about what they want to do.
[redacted: the US company]/EBR Meeting regarding the apparatus specifications. Minute.
The pad attached to the impregnant. Combination of plating, etching, and the down force.
Meeting regarding prosecution process of impregnation application at Watanabe Office
- 2002.10.1 The 1st meeting regarding filing. Kondo, Shinozuka, Kunisawa, Watanabe. Impregnation. Planarization with plating.
Intellectual Property Dept. -> Kunisawa. Advised to file. 10/2 Manager Kubota. Instruction.
- 11.19 Kubo, Kunisawa, Kosugi Kubo -> Shinozuka. Responsible staff changed. 11/20? Request for drafting
- 2002.12.2 Domestic filing 2002-350429
- 2003.7 Request for foreign filing through the workflow
- 9 Request for consideration of new matters
- 10.1 Etching <- Mr. Ogata attached his memos for preparing against Nutool to the request for approval.
- 10.23 Request for addition
- 2003.11.28 Domestic priority
- 2003.12.1 Filing in USA
- (1) Did not know that an invention achieved in the U.S.A. should be filed in USA first.
- (2) Did not realize the content of this invention includes an invention made by [redacted: the US company].
- Makino:(1) +(2)
- Kunisawa: (1)
- Fukunaga (1)

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: "M Tsujimura" <tsujimura.manabu@ebara.com>, ogata.akira@ebara.com, "Kobayashi, Fumio (E-mail)" <kobayashi.fumio@ebara.com>, fukunaga.akira@ebara.com, fukunaga.yukio@ebara.com, tokushige.katsuhiko@ebara.com, hodai.masao@ebara.com, mishima.koji@ebara.com, asami.masao@ebara.com, "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>, Kimura Norio <kimura.norio@ebara.com>, "Nambu, Isao" <inambu@ebaratech.com>, "O'Connell, Dan" <doconnell@ebaratech.com>
Cc: horiuchi.takao@ebara.com, yago.natsunosuke@ebara.com
Subject: Meeting with Mr., redacted
Date: Thu, 10 Jun 2004 23:04:21 -0700
X-Mailer: Internet Mail Service (5.5.2653.19)

Great thanks to everybody participated in the quite intensive discussion in last week while my stay in Japan. I believe our meeting today with Mr., redacted, was truly successful and satisfactory.

Dan, Nambu-san, Kimura-san and myself visited Mr., redacted today for the discussion on IP issue in JDA. (redacted san also participated by phone.) The discussion was initiated by Dan explaining historical background of this matter, "Ebara had been working on planer plating technology prior to the engagement with redacted for the JDA, and filed patents before the contract, but after initial technical information exchange with redacted on this matter. Ebara should have informed redacted the background IPs in time to avoid any confusion and conflict on the IP ownership. After internal discussion at Ebara, Ebara agreed to modify those patent applications as co-invention with redacted recognizing its impact on the program and redacted's business."

Mr., redacted stated redacted could not understand why Ebara did not submit the background IPs at the 1st workshop in Sept'03 accordingly to the JDA contract". I replied "Ebara understood the contract, and actually submitted the IP list at the workshop. However, the list was too brief to discuss the details, and re-submitted the list with abstracts in the workshop in Feb'04, which caused some delay in our initial discussion on this matter with redacted. Since then, we've been working with redacted technical coordinator for identification of IP ownership, and redacted attorneys for modification of total 8 Ebara's Japanese patent applications into co-invention with redacted applying for export license for corresponding US patent applications. redacted-san also backed us up stating "Those were the same understanding as hers".

I also explained "In order to avoid any confusion in patent application process in the future, Ebara propose to submit whole translation of IP disclosure to redacted before filing patent application for redacted's review and determining the co-ownership. redacted-san stated "1-page summary or abstract of US patent application should be sufficient." Dan stated "This process change requires redacted's strong support in timely corresponding redacted's decision to Ebara since Ebara rely on redacted's reply for filing the patent application."

Finally, I apologized the confusion and promised the compliance to the contract, and Mr., redacted replied "I'm fine, now."

I also talked with redacted-san after the meeting by phone, and she said "The meeting was quite satisfactory."

I understand it was difficult time for everybody to re-evaluate the contract and determine the countermeasure. Now, I believe, we have better understanding of the contract and how it impacts Ebara's business. We have no choice than succeeding the JDA with redacted.

Once again, thank you very much for your understanding and continuous support on this matter.

Best Regards,

K.Musaka

Mr. Musaka, 19:28 04/02/03 +0900, Ebara Patent List

To: Mr. Musaka

From: 笹部憲一 <sasabe.kenichi@ebara.com>

Subject: Ebara Patent List

Cc: 福永(由)室長殿, 三島部長殿 Mr. Y. Fukunaga, Mr. K. Mishima

Bcc:

Attached: D:\My Documents\redacted用EBR特許リスト\EBR Applications 02.2.6.xls;

Dear Mr. Musaka,

Please find attached Ebara patent application list.

Mr. Y. Fukunaga, Mr. Mishima and I selected the possible related Japanese patent applications filed later than August 2002.

We believe the owner of the applications filed before August 2003, when the PaP Project Contract was agreed, is Ebara alone, because before the contract there was no exchange of confidential information between redacted and Ebara.

Applications filed after August 2003 must be checked by the technology covered by the application. The owner in the list is our idea for the discussion in the meeting.

Last four applications are under preparation for application and not filed yet.

I think it is difficult for them to understand the contents of the each application after short explanation at the meeting. I think we had better to discuss about few applications which might be joint applications.

Best regards

February 6, 2004

Patent Application No.	Filing Date	Title	Abstract	Main Claims		Claims Total	Foreign Applications
				Method	Apparatus		
1	2002-242728	22-Aug-02 Electrolytic processing apparatus	Electrolysis apparatus, comprising/ a substrate holder having an electrical contact to a periphery of a substrate/ an electrode facing the substrate/ a control element of electrical field between the electrode and the substrate, the element having almost the same diameter with the substrate and/ a drive mechanism for relative parallel movement of the substrate and the electrode.	0	1	5 Ebara	Not Filed
2	2002-350529	02-Dec-02 Apparatus and method for electrolytic processing	redacted	1	2	9 Ebara	US only
3	2003-015235	23-Jan-03 Plating method and apparatus therefor	redacted	1	1	11 Ebara	Not Filed
4	2003-015236	23-Jan-03 Plating method and plating apparatus	redacted	1	1	12 Ebara	PCT, TW
5	2003-025159	31-Jan-03 Apparatus for electrolytic processing	redacted	0	4	24 Ebara	US only
6	2003-111327	16-Apr-03 Plating method for semiconductor substrate	redacted	1	0	26 Ebara	Under Preparation

February 6, 2004

No.	Application No.	Filing Date	Title	Abstract	Main Claims		Claims Total	Foreign Applicable
					Method	Apparatus		
7	2003-138521	16-May-03	Apparatus and method for electrolytic processing	redacted	1	3	9 Ebara	Under Preparation
8	2003-145017	22-May-03	Apparatus for supplying, recovering, measuring and replenishing electrolyte	redacted	3	0	8 Ebara	Under Preparation
9	2003-148326	26-May-03	Substrate processing method and apparatus	redacted	2	1	14 Ebara	Under Preparation
10	2003-149827	27-May-03	Plating apparatus and plating method	redacted	1	1	24 Ebara	PCT, TW
11	2003-161236	05-Jun-03	Plating apparatus and plating method	redacted	1	1	16 Ebara	PCT, TW
12	2003-161237	05-Jun-03	Plating apparatus and electrolyte retaining method	redacted	0	1	5 Ebara	PCT, TW
13	2003-169791	13-Jun-03	Plating apparatus and plating method	redacted	1	1	10 Ebara	Not Decided

February 6, 2004

No.	Application No.	Filing Date	Title	Abstract	Main Claims		Claims		Foreign	
					Method	Apparatus	Total	Owned	Applied	Applicable
14	2003-195406	10-Jul-03	Plating apparatus and plating method	redacted	2	2	14	Ebara	Not	Decided
15	2003-202515	28-Jul-03	Plating apparatus and plating method	redacted	1	1	8	Ebara/ redacted	Not	Decided
16	2003-310355	02-Sep-03	Apparatus for plating substrate	redacted	0	1	10	Ebara	Not	Decided
17	2003-313307	04-Sep-03	Apparatus for plating substrate	redacted	0	1	13	Ebara	Not	Decided
18	2003-314755	05-Sep-03	Method and apparatus for controlling electrolyte	redacted	2	2	20	Ebara	Not	Decided
19	2003-319055	10-Sep-03	Plating apparatus and plating method	redacted	2	1	16	Ebara	Not	Decided

No.	Application No.	Filing Date	Title	Abstract	Main Claims Method/Apparatus	Claims Hold	Owner	Foreign Application
20	2003-371159	30-Oct-03	Apparatus and method for processing substrate	redacted	1	1	14 Ebara	Not Decided
21	2003-373391	31-Oct-03	Plating apparatus and plating method	redacted	1	1	15 Ebara	Not Decided
22	2003-399443	28-Nov-03	Apparatus and method for electrolytic processing	redacted	3	3	redacted -ted/Ebara 19a	Not Decided
23	2003-402008	01-Dec-03	Plating apparatus and plating method	redacted	1	1	20 Ebara	Not Decided

February 6, 2004

No.	Application No.	Filing Date	Title	Abstract	Map Claims		Claims Total	Foreign Owner	Foreign Applicant
					Method	Apparatus			
24	2003-431211	25-Dec-03	Plating method and plating apparatus	redacted	1	1	14	a	redacted Not Decided
25	2003-431448	25-Dec-03	Plating apparatus and plating method	redacted	1	1	10	Ebara	Not Decided
28			Plating apparatus and plating method of substrate	redacted	2	2	17	Ebara	Not Decided

February 6, 2004

Apparatus No.	Title	Abstract	Main Claims		Claims Total	Foreign Applicants
			Method	Apparatus		
27	Substrate processing apparatus	redacted	0	9	43 Ebara	Not Decided
28	Plating apparatus and plating method of substrate	redacted	3	1	13 Ebara	Not Decided
29	Plating apparatus and plating method of substrate	redacted	1	2	18 Ebara	Not Decided

Support Document N

Meeting Minutes – The 2nd /EBARA JDA Workshop

Date; February 5 & 6, 2004

Place; redacted

Attendees; redacted

Ebara – Manabu Tsujimura, Jay Horjuchi, Yukio Fukunaga, Koji Mishima, Norio Kimura, Ray Fang
Keisuke Namiki, Keiichi Kurashina, Isao Nambu, Dan OConnell, Kenichi Sasabe,
Katsuyuki Musaka

Redacted

Redacted .

Redacted

IP List Exchange (redacted /Kenichi Sasabe)

- There exist patent for additive distribution control for wide feature leveling by Ebara's competitor, which may interfere with current development activities on pad plating. (Ebara)
 - The patent explains superfill mechanism, which is different from flat overburden (redacted)
- (redacted) s disclosure on pad plating ready for Ebara's review (redacted)
 - Ebara filed original Japanese patent application on touch down plating with "porous element" in 1999.
 - Will review possible addition of claim and/or coinventor (Ebara)
 - Still possible to file US patent application with (redacted) as coinventor (redacted)
- (redacted) s disclosure for e-CMP chemistries to be filed as (redacted) s invention, while e-CMP apparatus with the method (chemistries) to be filed as (redacted) /Ebara co-invention (redacted)
- Ebara's Japanese patent application items #2, 4, 10, 11, 12, 14, 22, 23, 24 to be reviewed in regards to (redacted) s disclosure for possible addition of (redacted) as coinventor (redacted)
 - Will submit abstract translation on above items (Ebara)
- Ebara's Japanese patent application item #16 to be Ebara invention (redacted)
- Ebara's disclosure item #26 and 28 to be filed as (redacted) /Ebara co-invention (redacted)
 - Will submit abstract translation of the draft applications (Ebara)
- Ebara's disclosure item #20 can be the same content as (redacted) s disclosure (redacted)
 - Will submit abstract translation of the draft application (Ebara)

Action Plan
Action Item

Owner

Due

Redacted

16. Abstract translation of Ebara's Japanese patent application
(Item#2, 4, 10, 11, 12, 14, 22, 23, 24)
17. Abstract translation of Ebara's Japanese patent application draft
(Item#26, 28, 29)

K. Sasabe

~Feb'04

K. Sasabe

~Feb'04



Fax. +81-3-3745-5745
(Japan)

2004.2.8.

知財部 近藤副部長殿
特許部 坂口担当部長殿

転送をお願いします。

1/1

redacted との 調整結果報告と依頼

708 笹部

確認した facts.

1. 2002.8月の meeting において redacted から 含浸材に pad を付けることが 説明されている。
2. Ebara は、他社と共同開発として 含浸材を用いためっきを開発し、1999年12月以降 日本に特許出願している。
3. 日本、他社によろ 含浸材を用いためっき出願が 1999年2月に有る。

行動計画

1. 2002.8月以前に、共同開発において、padを用いためっきの特許出願が無かったか確認する。
2. redacted として11件の出願が共同出願の可能性があり、考えており、それらの出願の 要約、請求項、回付号の説明、英訳と図を Ebara が作り、redacted に送付する。以下記出願の上記部分の英訳をお願いします。約2週間。
3. redacted と共願が必要となった場合には 発明者の追加と出願人の追加を行う。
4. 共願の可能性のある出願は

特願 2002-350529 (国内優先権)

2003-015236

2003-149827

2003-161236

2003-161237

2003-195406

2003-399443 (2002-350529の国内優先)

2003-431211

K1030466

K1040012

K1040028

英訳が4つ必要であれば、これを結構です。

US 出願有。 ②

PCT 出願有。 ④

PCT 出願有。 ⑩

PCT 出願有。 ⑪

PCT 出願有。 ⑫

日本のみ ⑬

日本のみ ⑭

日本のみ。 ⑮

redacted

5. redacted から 3件の出願が示され、2件は共同、1件は redacted 単願。

⑯

⑰

Support Document O

Fax +81-3-3745-5745
(Japan)

2004.2.8

To: Deputy General Manager Kondo in Intellectual Property Dept.
To: Manager Sakaguchi in Patent Dept.



Please forward.

1/1

Report of Coordination with [redacted: the US company] and Request

708 Sasabe

Confirmed facts

1. In the meeting held in August 2002, [redacted: the US company] explained pads would be attached to impregnants.
2. Ebara developed a plating technique jointly with a company and filed patent applications in Japan after December 1999.
3. A Japanese company filed patent applications for a plating technique using impregnants in February 1999.

Schedule of actions

1. Check if any patent application for such plating technique using pads invented in the joint development was filed before August 2002.
2. [redacted: the US company] regards that 11 applications are possible to be joint applications. Ebara is responsible for preparing English-translated abstracts, claims, brief descriptions of the drawings, explanations of symbols and drawings of these applications, and sending them to [redacted: the US company]. => Please translate the above-mentioned parts the applications listed below in about two weeks.
3. When such applications are decided to be the joint applications with [redacted: the US company], add the inventors and applicants.
4. Listed below are possible joint applications.

If the English-translated text can be used as they are, its OK.

App. No.	2002-350529	(Original application of the domestic priority)	Filed in the U.S. A.	(2)
	2003-015236		Filed through PCT.	(4)
	2003-149827		Filed through PCT.	(10)
	2003-161236		Filed through PCT.	(11)
	2003-161237		Filed through PCT.	(12)
	2003-195406		Filed in Japan only.	(14)
	2003-399443	(Domestic-priority-claimed application of 2002-350529)	Filed in Japan only.	(22)
	2003-431211		Filed in Japan only.	(24)
	K1030446			(26)
	K1040012			(28)
	K1040028			(29)

5. [redacted: the US company] disclosed three applications: two will be the joint applications while the rest ([redacted: technical field]) will be sole application of them.

Mr. Hiroyuki Hagiwara, 18:25 04/02/28 +0900, 米国における発明者追加について

To: Mr. Hiroyuki Hagiwara
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: 米国における発明者追加について
Cc:
Bcc:
Attached:

Fish & Neave
萩原弁護士殿

いつもお世話になり有難うございます。
Portlandにて口頭でお伺いしましたが、下記の点に関してアドバイスいただきたくお願い致します。

Redacted

Redacted

恐縮ですが、来週(3月第1週)末までにアドバイスいただければ助かります。

笹部 憲一

This information is intended for the use of the addressee and may contain information that is privileged and confidential. If you are not the intended recipient you are hereby notified that the unauthorized dissemination of this communication is strictly prohibited. If you have received this communication in error, please notify us immediately.

Mr. Hiroyuki Hagiwara, 18:25 04/02/28 +0900, Regarding addition of inventors in US

To: Mr. Hiroyuki Hagiwara

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Regarding addition of inventors in US

Cc:

Bcc:

Attached:

Fish & Neave

Dear Attorney Hagiwara,

We always appreciate your advice and support for the patent issues.

As I orally mentioned in Portland, I'd like to ask for your advice again regarding the following points.

[REDACTED]

[REDACTED]

We'd appreciate if you could give us your advice till the end of next week (1st week of March).

Kenichi Sasabe

[Below to the end is originally English text.]

This information is intended for the use of the addressee and may contain information that is privileged and confidential. If you are not the intended recipient you are hereby notified that the unauthorized dissemination of this communication is strictly prohibited. If you have received this communication in error, please notify us immediately.

To: "Kenichi Sasabe (E-mail)" <sasabe@fujiebara.co.jp>
Cc: "Hagiwara, Hiroyuki" <HHagiwara@fishneave.com>, "Toh, Kaede" <KToh@fishneave.com>
Subject: Response to your question regarding U.S.-Japan joint development situation

> -----Original Message-----
> From: Zamot, Lucila
> Sent: Wednesday, March 03, 2004 5:30 PM
> To: Jackson, Robert R.
> Subject: Sasabe letter
>
> <<Sasabe ltr.PDF>>



Sasabe ltr.PDF



FISH & NEAVE

Herbert F. Schwartz
Eric C. Wegman
Robert C. Morgan
Kenneth B. Herman
Robert R. Jackson
Jesse J. Jenner
W. Edward Bailey
Patricia A. Martone
Roderick R. McKelvie
James F. Haley, Jr.
Richard M. Barnes
Laurence S. Rogers
Vincent N. Palladino

Robert J. Goldman
Thomas L. Sacrest
Daniel M. Gentl
Norman H. Beamer
Kevin J. Colligan
Glenn A. Ousterhout
Susan Probst
Margaret A. Pient
Douglas J. Gilbert
Denise L. Loring
Jeffrey H. Ingelman
Mark H. Bloomberg
Jane A. Massaro

Duane-David Hough
Mark D. Rowland
Edward J. DeFrancis
Eric R. Hubbard
William J. McCabe
John M. Hintz
Richard A. Inc
Frances M. Lynch
Christopher J. Harvett
A. Jay Arnold
Steven Cherry
Joseph M. Gallaro
Jeanne C. Curtis

Gerard J. Flattmann, Jr.
Kevin P.B. Johnson
Terrence J. P. Kearney
Robert W. Morris
Avinash S. Lale
Jerie T. Gunnison
Richard L. Rainey
James E. Hopewell
Pablo D. Hender
Brian C. Cannon
Robert B. Wilson

Of Counsel
Albert E. Fey
Kenneth A. Gersoni
Gene W. Lee
Morris A. Lacey
Daniel M. Becker
Senior Attorneys
A. Peter Adler
Thomas J. Vetter
Charles Quinn
Lisa E. Crista
Gabrielle E. Higgins
Thomas P. Burke

Frederick P. Fish 1855-1930
Charles Neave 1867-1937

* California and New York Bars ** California Bar Only *** DC Bar Only

ROBERT R. JACKSON
DIRECT DIAL 212.596.9022
E-MAIL RJACKSON@FISHNEAVE.COM

March 3, 2004

VIA E-MAIL

Mr. Kenichi Sasabe
General Manager
Ebara Corporation
Patent Department
New Product Development Division
Precision Machinery Group 42-1 Honfujisawa
Fujisawa-shi 251-8502
Japan

Hypothetical Questions
Regarding U.S.-Japan
Joint Development Situation
Our File: 1184.001

Dear Mr. Sasabe:

Thank you for your inquiry.

The following is my attempt to at least partly answer your questions.

Please make sure that what I say does not reflect some factual misunderstanding by me. If you detect any such misunderstanding, please accept my apology, and please correct me.

FISH & NEAVE

Mr. Kenichi Sasabe

March 3, 2004

Page 2

redacted

FISH & NEAVE

Mr. Kenichi Sasabe

March 3, 2004

Page 3

redacted

FISH & NEAVE

Mr. Kenichi Sasabe

March 3, 2004

Page 4

redacted

FISH & NEAVE

Mr. Kenichi Sasabe

March 3, 2004

Page 5

redacted

Feedback from you regarding the foregoing would now be helpful to me.

Sincerely yours,

Robert R. Jackson
Robert R. Jackson

RRJ:lz

Mr. Pedersen, 17:04 04/05/11 +0900, Export license for Japanese application

To: Mr. Pedersen
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Export license for Japanese application
Cc: Mr. Akai
Bcc:
Attached: D:\My Documents\redacted\PaP project\Mr.Pedersen.doc;

Dear Mr. Pedersen,

Please give us your advise on the issue described in the attached document by the end of this week.

If you need more information please let me know by e-mail.

I will have a telephone conference with redacted attorney on this matter next week.

Best regards,

Kenichi Sasabe
Patent Department
Ebara Corporation

Mr. Pedersen, 15:17 04/05/15 +0900, Export License

To: Mr. Pedersen
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Export License
Cc: Mr. Akai, Mr. Saito, Mr. Y.Fukunaga
Bcc:
Attached: D:\My Documents\redacted PaP project\Export License.doc;

Dear Mr. Pedersen

I have studied your letter and the article by Mr. Helfgott but I really cannot understand how far or how precise we must describe the situations and reason of the error.

I drafted a draft attached to this e-mail.

Please give me your comment.

Please point out any comments, for example what to say, what not to say, etc.

I think this kind of document submitted to USPTO may be a part of the file wrapper of the related US application. I want to say as little as possible to get the export license.

redacted

I appreciate if you can give me your comment by 10:00pm on May 18 in Japantime (9:00am May 18 EST)

Best regards,
Kenichi Sasabe

Mr. Pedersen, 12:49 04/05/18 +0900, Export license

To: Mr. Pedersen
From: 笹部憲一 <sasabe.kenichi@ebar.com>
Subject: Export license
Cc: Mr. Akai, Mr. Shinozuka, Mr. Saito
Bcc:
Attached:

Dear Mr. Pedersen

redacted

Please give us your brief advice for the question (1) by May 19, 9:00pm Japan time (May 19, 8:00am EST)

I am sorry we don't have enough time to consider.

Best regards,
Kenichi Sasabe

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

To: Mr. Musaka
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: Export license
Cc:
Bcc:
Attached:

六平様

下記のメールはEBRの米国出願を担当している弁護士とのやり取りですが、多くの出願に関してライセンスを取ることに對する弁護士からのアドバイスです。#2、#22に関してライセンスを取ることと、関連する7件に関して取ることで、決定的に難しくなることは無さそうです。ご参考までにお送りいたします。

Date: Wed, 19 May 2004 08:44:35 +0900
To: Mr. Y.Fukunaga, Mr. Mishima
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: Export license

福永様、三島様

Pedersen弁護士から回答がきました。
昨日Pedersenに送ったメールは以下の物です。

Dear Mr. Pedersen

redacted

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

redacted

Please give us your brief advice for the question (1) by May 19, 9:00pm Japan time (May 19, 8:00am EST)

I am sorry we don't have enough time to consider.

Best regards,
Kenichi Sasabe

Subject: Export license
Date: Tue, 18 May 2004 17:28:41 -0400
Thread-Topic: Export license
Thread-Index: AcQ9Hxce2SSOqX65QCikZ2e3wEljxA=
From: "Nils E. Pedersen" <npedersen@wenderoth.com>
To: "???" <sasabe.kenichi@ebara.com>

Dear Mr. Sasabe,

redacted

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

redacted

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

redacted

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

redacted

2

redacted

Please let me know what further questions you may have.

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, LLP.

Attorneys and Counselors at Law

Patents, Trademarks, and Copyrights

2033 K Street, N.W., Suite 800

Washington, DC 20006 U.S.A.

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Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

sending an e-mail to ulp@wenderoth.com, and destroy all copies of this message and any attachments. Thank you. If you are not the intended recipient, you are not authorized to read, print, copy, retain, or disseminate this email or any information included in this email.

For more information about Wenderoth, Lind & Ponack, L.L.P., please visit us on the web at www.wenderoth.com

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

To: Mr. Musaka
From: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: Fwd: Export license
Cc:
Bcc:
Attached:

Dear Mr. Musaka,

I'd like to forward the communication with the attorney for EBR responsible for filing in the U.S.A. as a reference. He offers us some advices regarding obtaining licenses for many patent applications. Briefly to say, if we obtain licenses for #2 and #22 and seven related applications, filing in the U.S.A. will not be critically hard.

Date: Wed, 19 May 2004 08:44:35 +0900
To: Mr. Y.Fukunaga, Mr. Mishima
From: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: Fwd: Export license

Mr. Fukunaga, Mr. Mishima

Our Attorney, Mr. Pedersen gave me his reply.
The message below is the mail I sent to Mr. Pedersen yesterday.
[Below to the end is originally English text.]

由, 10:42 04/05/24 +0900, Fwd: Petition and Statement Your Ref: GEB1988

To: 福永(由)室長殿
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: Petition and Statement Your Ref: GEB1988
Cc: 赤井部長殿, 篠塚担当部長殿
Bcc:
Attached: C:\PROGRAM FILES\EUDORA\attach\petition.doc; C:\PROGRAM FILES\EUDORA\attach\verified statement.doc; D:\My Documents\redacted PaP project\Letter from Pedersen04.05.24.doc;

福永様

Pedersenさんのメールは文字化けしていますが、ブランクなどが変な文字に置き換わっているだけのようですので、添付のWord文書のようになると思います。

このような内容で直接の関係者それぞれのpetition(請願)を作っていく必要があります。

Statementの方は笹部の名前になっていますが、私は後で調べて分かった部分が多いので、直接の知識のある方をお願いすることになると思います。

Pedersenさんにはまだ相談していませんが、このプロジェクトに関する包括ライセンスを取っておく必要があると思います。

Subject: Petition and Statement Your Ref: GEB1988
Date: Sat, 22 May 2004 10:52:08 -0400
X-MS-Has-Attach: yes
Thread-Topic: Petition and Statement Your Ref: GEB1988
Thread-Index: AcRADFtJfJ/QEyZ6R6mRalz1DYNCMQ==
From: "Nils E. Pedersen" <npedersen@wenderoth.com>
To: <sasabe.kenichi@ebara.com>

May 24, 2004

Ebara Corporation

Patent Department

11-1 Asahi-cho, Haneda, Ohta-ku

Tokyo 144-8510, JAPAN

Attn: Mr. Kenichi Sasabe

Re: U.S. Patent Application

由, 10:42 04/05/24 +0900, Fwd: Petition and Statement Your Ref: GEB1988

[illegible]

Â Â Â Â Â Â Â Â Â Â Â Â Â Â Â Â Â
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 Â Â Â Â Â Â Â Â Â Â Â Â Â Â Â Â Â Serial No.ÂĖž 10/724,044

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 A A A A A A A A A A A A A A A A Your Ref: A GEB1998

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Our Ref: 2004_0738/NEP/01224

Dear Mr. Sasabe:

redacted

redacted

Â Â Â Â Â Â Â Â Â Please let me know if you have any questions.

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, L.L.P.

Attorneys and Counselors at Law

Patents, Trademarks, and Copyrights

2033 K Street, N.W., Suite 800

Washington, DC 20006 U.S.A.

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由, 10:42 04/05/24 +0900, Fwd: Petition and Statement Your Ref: GEB1988

For more information about Wenderoth, Lind & Ponack, L.L.P., please visit us on the web
at www.wenderoth.com

Y, 10:42 04/05/27 +0900, Fwd: Petition and Statement Your Ref GEB1988

To: General Manager Y. Fukunaga

From Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Petition and Statement Your Ref: GEB1988

Cc: General Manager Akai, Manager Shinozuka

Bcc:

Attached: C:\PROGRAM FILES\EUDORA\attach\petition.doc; C:\PROGRAM FILES\EUDORA\attach\verified statement.doc; D:\My Documents\redacted: the US company\PaP project\Letter from pedersen04.05.24.doc;

Dear Mr. Fukunaga,

The message sent by Mr. Pedersen was garbled; though, the garbled characters are blanks only. You can read his message in the attached Word file.

Referring the statement as Mr. Pedersen prepared, we need to prepare petitions for each person directly responsible for the issues.

His example statement is to be signed by me, Sasabe; however, I will request people who directly know about the issues because I learned many things later after studying.

Although I have not asked Mr. Pedersen for his opinion yet, I think we should obtain the open general license on this project.

[Below to the end is originally English text including garbled characters.]

kmusaka@ebaratech.com, 19:48 04/03/06 +0900, Fwd: S1プロジェクトPat Listの件

To: kmusaka@ebaratech.com
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: S1プロジェクトPat Listの件
Cc: fukunaga.yukio@ebara.com, mishima@shi.ebara.co.jp
Bcc:
Attached: D:\My Documents\redacted PaP project\redacted English translation of Ebara applications for redacted ¥2003-015236.doc; D:\My Documents\redacted PaP project\redacted English translation of Ebara applications for redacted ¥2003-149827.doc; D:\My Documents\redacted PaP project\redacted English translation of Ebara applications for redacted ¥2003-161236.doc; D:\My Documents\redacted PaP project\redacted English translation of Ebara applications for redacted ¥2003-161237.doc;

Dear Musaka-san

Please find attached translation of Ebara's Japanese applications.
We prepared the English translation of the following applications

Item No.	Application No.
4	2003-015236
10	2003-149827
11	2003-161236
12	2003-161237
14	2003-195406
24	2003-431211
26	2004-022178
28	2004-023256
29	K1040028

At the meeting I explained that the item No.26-28 was under preparation for application. But 26-28 was already filed by the end of January 2004. Item No.29 is not filed yet.

Item No. 22 is a domestic priority application (国内優先) of the original application No.2. The original application (Item No. 2) is abandoned and amended application No. 22 is alive. I explained that item No.2 was filed in US and item No.22 was not filed in US. But I found the US application included the amended claims and this US application is the application of item #22 instead of item #2.
I will send the US application on Monday because I don't have e-data of this application.

Item #23 is not prepared yet. Because I did not notice item #23 was included in the applications to be reviewed until I received the Meeting Minutes. Please give us some more time for this application.

I will send the English translations listed above in 2 separated mails.

Best regards
Kenichi Sasabe

X-Sender: yf08594@pop.ebara.co.jp
X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J
Date: Fri, 05 Mar 2004 13:03:37 +0900
To: sasabe.kenichi@ebara.com
From: Yukio Fukunaga <fukunaga.yukio@ebara.com>
Subject: S1プロジェクトPat Listの件
Cc: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>, mishima.koji@ebara.com

特許部

笹部 様

標記の件大変恐縮ですが、翻訳結果を ETI 六平さんに~3/9(US)までに
電子データにて送付をお願い致したく。
(六平さんがその後一週間半出張で留守になるため、出張前に
に説明しておきたいとのことです)

ご多忙中申し訳ございませんが、よろしくお願い致します。

福永(由)

kmusaka@ebaratech.com, 19:48 04/03/06 +0900, Fwd: Regarding S1 Project Pat List

To: kmusaka@ebaratech.com

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Regarding S1 Project Pat List

Cc: fukunaga.yukio@ebara.com, mishima@shi.ebara.co.jp

Bcc:

Attached: D:\My Documents\redacted: the US company PaP project\English translation of Ebara applications for redacted: the US company\2003-015236.doc; D:\My Documents\redacted: the US company PaP project\English translation of Ebara applications for redacted: the US company\2003-149827.doc; D:\My Documents\redacted: the US company PaP project\English translation of Ebara applications for redacted: the US company\2003-161236.doc; D:\My Documents\redacted: the US company PaP project\English translation of Ebara applications for redacted: the US company\2003-161237.doc

[Below to the beginning of the next message is originally English text excluding the bold characters.]

Dear Musaka-san

Please find attached translation of Ebara's Japanese applications.

We prepared the English translation of the following applications

Item No.	Application No.
4	2003-015236
10	2003-149827
11	2003-161236
12	2003-161237
14	2003-195406
24	2003-431211
26	2004-022178
28	2004-023256
29	K1040028

At the meeting I explained that the item No.26-28 was under preparation for application. But 26-28 was already filed by the end of January 2004.

Item No.29 is not filed yet.

Item No. 22 is a domestic priority application (**domestic priority application**) of the original application No.2. The original application (Item No. 2) is abandoned and amended application No. 22 is alive.

I explained that item No.2 was filed in US and item No.22 was not filed in US. But I found the US application included the amended claims and this US application is the application of item #22 instead of item #2.

I will send the US application on Monday because I don't have e-data of this application.

Item #23 is not prepared yet. Because I did not notice item #23 was included in the applications to be reviewed until I received the Meeting Minutes. Please give us some more time for this application.

I will send the English translations listed above in 2 separated mails.

Best regards
Kenichi Sasabe

X-Sender: yf08594@pop.ebara.co.jp
X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J
Date: Fri, 05 Mar 2004 13:03:37 +0900
To: sasabe.kenichi@ebara.com
From: Yukio Fukunaga <fukunaga.yukio@ebara.com>
Subject: Regarding S1 Project Pat List
Cc: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>, mishima.koji@ebara.com

Patent Dept.
Dear Mr. Sasabe,

I would like to ask you to send the translation result regarding the Pat list to Mr.Musaka of ETI by 9 April (US) via e-mail.

(Mr. Musaka will leave the office for the business trip for about one and a half week after that date. He says he wants to explain to [redacted: the US company] before making his trip.)

I realize you are very busy; though, I would appreciate your cooperation.

Y. Fukunaga

kmusaka@ebaratech.com, 23:12 04/03/09 +0900, S1 project patent

To: kmusaka@ebaratech.com
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: S1 project patent
Cc: fukunaga.yukio@ebara.com, mishima.koji@ebara.com
Bcc:
Attached: D:\My Documents\redacted\用EBR特許リスト\Ebara Patent Applications Mar0904.xls;

六平様

ご指摘のありましたリストのitem # 2と#22の外国出願欄を修正しました。添付します。

Item #2と#22の関係について説明します。
それぞれの出願日は

	出願番号	出願日
Item #2	2002-350529	2002.12.2
#2の国内優先出願	2003-399443	2003.11.28
Item #2のUS出願	未入手	2003.12.1

です。

日本で国内優先を行って、親出願と国内優先出願とを優先権主張して外国出願を行う事が多いのですが、国内での国内優先出願が手間取りますと、国内優先より前に外国出願することになります。この場合には、優先権主張は親出願だけとなり、親出願に開示されていない事項は外国出願日が出願日となります。

今回は11月29日が土曜日ですので、実質1移動日の違いで国内優先の方が早がったこととなりますが、米国出願は進めていた手続きに従って12月1日に出されています。このため、US出願には優先権として2002-350529のみが記されています。(親出願の優先権を生かすためには12月2日までにUS出願が必要で、優先権証明を取ったりしているよりUS出願した方が早いのでこのように処理しています。)

お送りしたUS出願原稿で#22で追加になっている部分は以下の部分です。

p.7 line 13-line 21
p.8 line 14- p.10 line 11
p.11 line 4- p.13 line 8
p.14 Fig.15, 17の説明
p.15 Fig.18-21の説明
p.36 line 5- p.37 line 6
p.38 line 5- p.45 line 2(最後)
Claim 17-21, 24-27

内容としては、複数の電極ヘッドを用いた複数段の処理、複数の処理液を用いた複数段の処理がitem #2に追加されています。

US出願は12月1日に出願されていますが、米国の代理人事務所から日本の弁理士事務所にまだApplication Noの連絡が入っておらず、現時点では分かりません。分かり次第連絡いたします。

以上、よろしくお願い致します。
笹部

Kmusaka@ebaratech.com, 23:12 04/03/09 +0900, S1 project patent

To: kmusaka@ebaratech.com

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: S1 project patent

Cc: fukunaga.yukio@ebara.com, mishima.koji@ebara.com

Bcc:

Attached: D:\My Documents\EBR Pat list for [redacted: the US company]\Ebara Patent Applications Mar0904.xls;

Mr. Musaka,

For the list items #2 and #22 you pointed out, I've corrected the descriptions in the column for foreign application filing. The corrected one is attached to this email.

The relation between Items #2 and #22 is as described below.

Their application Nos. and filing dates are:

	Application No.	Filing date
Item #2	2002-350529	December 2, 2002
Domestic priority application for #2	2003-399443	November 28, 2003
U.S. application of Item #2	N/A	December 1, 2003

Usually, we first file an original patent application and its domestic priority application in Japan, and then file its foreign application with a claim of priority for the original and domestic priority applications. In cases where it takes long time to file domestic priority applications, we file relevant foreign applications in advance of the domestic priority applications. In these cases, priority is claimed for their original applications only; for items not disclosed in the original applications, the foreign application filing date becomes the filing date.

For Items #2 and #22, the domestic priority application was filed one operating day earlier than the U.S. application (because November 29 is Saturday), which was filed on December 1 in the ongoing process.

As a result, the U.S. application claims priority for 2002-350529 only.

(To make priority for the original application effective, the U.S. application must have been filed on or before December 2. These steps have been taken because filing the U.S. application is more time-effective than obtaining priority certificates.)

The following items have been added to #22 in the submitted U.S. application draft.

p.7 line 13 to line 21

p.8 line 14 to line 11 in p.10.

p.11 line 4 to line 8 in p.13

p.14 Description of Figs.15 and 17

p.15 Description of Figs.18 to 21

p.36 line 5 to line 6 in p.37

p.38 line 5 to line 2 in p.45 (end)

Claims 17 to 21 and 24 to 27

Descriptions on a multi-stage process using multiple electrode heads and a multi-stage process using multiple processing liquids have been added to Item #2.

Regarding to the U.S. application filed on December 1, our attorney firm in Japan is not informed of the application No. from the attorney firm in the United States. I will let you know as soon as I figure out the No.

Sincerely,

Sasabe

中柴部長殿、赤井副部長殿、近藤副部長殿、篠塚担当部長殿、23:51 04/03/17 +0900、^{redac}_{-ted} 関連出

To: 中柴部長殿、赤井副部長殿、近藤副部長殿、篠塚担当部長殿
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: ^{redac}_{-ted} 関連出願の出願方法
Cc: 福永(由)室長殿、三島部長殿、坂口担当部長殿
Bcc:
Attached:

知財部各位

^{redac}_{-ted} 関連の新規出願については、今後下記のようにしたいと考えますので、問題点のご検討をお願いします。
大きな問題点がなければ、この案をベースに進めたいと考えます。

^{redac}_{-ted} とは共同開発契約の中で、

1. このプロジェクトにかかわる発明は、発明後30日以内に相手側の Technical Coordinator に書類で連絡する
 2. 連絡を受けた側はその案件が共願に該当するか検討し回答する
 3. 特許出願後2ヶ月以内に、出願のコピーを相手側に渡す。
- ことになっています。なお、Technical Coordinatorは、^{redac}_{-ted} ^{redac}_{-ted} さん、EBR:六平さんです。

このため、今後I社関連出願は、

1. 発明等届出書の段階で ^{redac}_{-ted} 関連となる可能性について検討する。(特許部→福永由紀夫室長)
2. ^{redac}_{-ted} 関連の可能性のあるものは、発明の要約の英訳を作成し、Excel sheetに記入して六平さんに送付する。
3. 六平さんはI社に連絡し、検討を依頼する。
4. 上記2、3と並行して、弁理士に依頼して出願書類を作成する。
5. ^{redac}_{-ted} からの回答が、共願希望の場合には、^{redac}_{-ted} の発明者を加えて、英訳し、米国第1国出願とする。
6. 出願から2ヶ月以内に、出願現行のコピーを六平さんを通して ^{redac}_{-ted} に渡す。
7. ^{redac}_{-ted} の回答が、共願不要であれば、荏原の発明者のみで日本国内に出願する。
8. クレームと要約との英訳を作成し、出願から2ヶ月以内にコピーを六平さんを通して ^{redac}_{-ted} に渡す。

対象となる出願は、接触、擦りを伴う含浸めっき、及び電解加工、電解CMPです。

今後、新規の出願に関しては上記の方法によることと致したく、問題点のご検討をお願いします。

特に、共願の場合は将来の問題を防止する意味で米国第1国出願としますので、ご注意ください。

万一、^{redac}_{-ted} 関連と思われる出願がチェックなしに知財部に回っていると思われる場合には、恐縮ですが、ご連絡をお願いします。

米国第1国出願とした場合には、6ヶ月以上1年以内経過した後、米国から外国出願します。

なお、共同開発が継続しますので、エクスポートライセンスは取得しておいた方がよいと考えます。

昨年のEBR関連会社の問題のその後、及び現在ライセンスを取得する上での問題について、SSDに確認してください。

General Manager Nakashiba, Deputy General Manager Akai, Deputy General Manager Kondo, Manager Shinozuka, 23:51 04/03/17+0900, How to file [redacted: the US company]-involved applications

To: General Manager Nakashiba, Deputy General Manager Akai, Deputy General Manager Kondo, Manager Shinozuka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: How to file [redacted: the US company]-involved applications

Cc: General Manager U. Fukunaga, General Manager Mishima, Manager Sakaguchi

Bcc:

Attached:

To all concerned in Intellectual Property Dept.

I propose that new [redacted: the US company]-involved applications will be filed in the procedure described below. Your check and review would be very appreciated.

If everything is OK, I will go ahead based on this proposal.

According to the joint development contract with [redacted: the US company],

1. Any invention linked to this project shall be reported to Technical Coordinator of the other side with a written notification within 30 days of the invention;
2. The side receiving the report shall consider and reply whether the invention is subject to a joint patent application or not, and;
3. Copies of the application documents shall be delivered to the other side within two months of the patent application filing.

Technical Coordinator of [redacted: the US company] is [redacted: personal name] and of EBR is Mr. Musaka.

Considering this contract, follow the procedure described below for filing [redacted: the US company]-involved applications:

1. Consider the possibility that an invention may be related to [redacted: the US company] upon preparation of "Notification of Invention" (Patent Dept. -> General Manager Yukio Fukunaga).
2. For an invention that may be related to [redacted: the US company], translate the abstract of the invention into English. Then, fill out the Excel form and submit it to Mr. Musaka.
3. Mr. Musaka will contact [redacted: the US company] and ask for its review.

4. Along with Steps 2 and 3, ask appropriate attorneys to prepare documents for application filing.
5. When [redacted: the US company] replies that the patent application of the invention should be a joint application, add an inventor or inventors in [redacted: the US company] to the documents and translate them into English. Then, file the first application in the United States.
6. Deliver a copy of the application draft through Mr. Musaka to [redacted: the US company] within two months of the application filing.
7. When [redacted: the US company] replies that the joint patent application of the invention is not required, file the application in Japan under name(s) of the inventor(s) in Ebara only.
8. Translate the claims and the abstract of the invention into English and submit copies of the translations through Mr. Musaka to [redacted: the US company] within two months of the application filing.

Applications related to impregnation plating, electro-chemical process, and electro-chemical mechanical polishing that involve contact and rubbing are subject to the procedure above.

I propose that new applications will be filed according to the procedure above in the future, and your check and review would be greatly appreciated.

Take particular note of joint applications that would be filed first in the United States to prevent future trouble.

If any [redacted: the US company]-involved application appears to have been sent to Intellectual Property Dept. with no check done, I would be very grateful for reporting me about it.

To file the first patent application of an invention in the United States, the application will be filed in the United States as a foreign application in six months or more and within one year.

Appropriate export licenses should be obtained because the joint development continues. For the troubles occurred after the issues caused by an affiliate of EBR last year and current issues related to obtaining the licenses, consult SSD.

Mr. Musaka, 三島部長殿, 14:43 04/04/29 +0900, ^{redac}_{-ted} /EBR 出願

To: Mr. Musaka, 三島部長殿

From: 笹部憲一 <sasabe.kenichi@ebara.com>

Subject: ^{redac}_{-ted} /EBR 出願

Cc: 福永(由)室長殿

Bcc:

Attached: D:\My Documents\^{redac}_{-ted} PaP project\六平様送付資料のコメント.doc; D:\My Documents\^{redac}_{-ted} PaP project\Ownership of patent applications 04.04.29.xls; D:\My Documents\^{redac}_{-ted} PaP project\三島さん^{redac}_{-ted} 資料\Toshiba\プレゼン擦りJuly.01.ppt; D:\My Documents\^{redac}_{-ted} PaP project\三島さん^{redac}_{-ted} 資料\Toshiba\擦りめつきSept.01.ppt;

4月24日にお話しましたEBRの主張をお送りします。
referenceはお持ちと思いますが、念のためお送りします。
referenceのvolが大きいため、何度かに分けてお送りします。

六平様

荏原の出願が荏原の権利であることを redacted に説明するための資料です。

4 について

4 月 24 日にお話しましたが、本日資料を見直していて、redacted の 2002 年 8 月の資料の "Tool Design / Process Development Plan" の表に Design Modification として

"Provide adjustable wafer/pad distance coupled to applied Volt."

という言葉を見つけました。

24 日には redacted からはパッドとウエハの押付け力 (Down force) は常に+なので、パッドとウエハは接触していると考えていましたが、これでは差が言えなくなりました。

このため、電流が逆転しないことを理由にしました。電流の大きさを変えることは redacted からは開示されていませんので、上記 Design Modification にある applied Volt. も電流の polarity の変化と考えました。

このため、クレーム 1、2、6.8 の voluntary amendment も applied voltage を applied plating voltage に変更する程度としたいと思います。

redacted に出している英文は、日本出願の翻訳でほぼ正確な翻訳ですが、英文のクレームとして検討した物ではありませんので、実際に外国出願する場合には翻訳は変わります。

この場合にも、電圧が基板側がカソード電圧又はゼロになるような範囲に限定した翻訳にします。

三島さんは redacted から示されたのはヘッドにパッドをつけた図と、めっきとエッチングを繰り返すプロセスの図だけだとのことですが、8/23/02 の日付の Tool Modification for 200mm Plating & Electropolishing Modules という議事録 (jointly agreed between Ebara and redacted that ...) という文書があり、control z-motion、control down force by distance and calibrate distance vs force などが合意されていますので、三島さんが記憶している 2 枚の図よりはもう少し具体的な議論がされていたかもしれません。

#10 について

Ebara の単願としたい。このためクレーム 13 は取り下げる。

#12、14、24 について

全て Ebara の単願と考える。

添付 補正案

Mr. Musaka, General Manager Mishima 14:43 04/04/29 +0900,[redacted: the US company]/EBR application

To: Mr. Musaka, General Manager Mishima
From: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: [redacted: the US company]/EBR application
Cc: General Manager U. Fukunaga
Bcc:

Attached: D:\MyDocuments\[redacted: the US company]PaP project\Comments on documents sent by Mr. Musaka.doc; D:\MyDocuments\Ownership of patent applications 04.04.29.xls; D:\MyDocuments\[redacted: the US company]PaP project\Mr. Mishima[redacted: the US company],[redacted: a Japanese company]document\[redacted: a Japanese company]\PresentationRubbingJuly.01.ppt; D:\MyDocuments\[redacted: the US company]PaP project\Mr. Mishima[redacted: the US company],[redacted: a Japanese company]document\[redacted: a Japanese company]\RubbingPlatingSept.01.ppt;

I send you the Ebara's point of view that I have talked on April 24.
I think you have the reference, but I send it, just in case.
Because the volume of reference is huge, I will divide it into several mails.

Dear Mr. Musaka,

This is a document to explain [redacted: the US company] the applications filed by Ebara in Japan should belong to Ebara

Regarding #4

As I have informed on April 24, I found words, "Provide adjustable wafer/pad distance coupled to applied Volt." as Design Modification in the table "Tool Design / Process Development Plan" in the documents of August 2002 by [redacted: the US company] when I was reviewing the document today.

On 24th, I had been thinking that the pad and the wafer was always in contact because of the pressing force of the pad and the wafer (down force) was always + based on the presentation by [redacted: the US company]. However, because of it, we can no longer say the difference.

Therefore, I used a point that the current does not invert for that reason. Changing the current intensity is not disclosed by [redacted: the US company]; therefore, I interpreted the applied Volt. in the above Design Modification as change of current polarity.

Therefore, I would like to make changes to voluntary amendment in the claims 1, 2, 6, 8 to the degree, from applied voltage to applied plating voltage.

Although the English translation submitted to [redacted: the US company] is the translation of the Japanese patent application and is almost exact translation. However, this is not discussed for using as the claims in English, the translation will be changed when actually filing it for a foreign application.

In this case, too, the translation is going to be a range limited such that the voltage on the substrate side becomes either the cathode voltage or zero.

Mr. Mishima says what [redacted: the US company] presented were only a drawing of a head having a pad and a drawing of a process repeating plating and etching. However, the minutes, Tool Modification for 200mm Plating & Electropolishing Modules, dated on 8/23/02, contains a sentence (jointly agreed between Ebara and [redacted: the US company] that ...), and matters including control z-motion, control down force by distance and calibrate distance vs force have been agreed. Therefore, more in-depth discussions might have been taken place than what Mr. Mishima remembers about two drawings.

Regarding #10

We desire to file it as the Ebara solo application. Therefore, we drop the claim 13.

Regarding #12, 14, 24

We see all of them for the Ebara solo application.

Attachment Preliminary amendments

由, 08:55 04/05/06 +0900, Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/

To: 福永(由)室長殿
From: 笹部憲一 <sasabe.kenichi@ebaracom>
Subject: Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/04 at 5:00 pm
Cc:
Bcc:
Attached: C:\PROGRAM FILES\EUDORA¥attach¥EBARA
Applications_0309041^{redac}ted_invent_05_04_04_Musaka.xls;

福永様
金曜日6:00AMの電話会議、笹部は対応可能です。他の方が対応可能でしたら、六平さんにOK回答していただきたくお願いします。
三島さんにも出席いただいたほうが良いと思います。
私は今日は10時半ごろから羽田に行かなければならないので、恐縮ですが、お願い致します。

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: "Fukunaga, Yukio (E-mail)" <fukunaga.yukio@ebara.com>, "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>, "Nambu, Isao" <inambu@ebaratech.com>
Cc: "Kimura, Norio" <nkimura@ebaratech.com>
Subject: FW: Ebara Patent Applications and subject of telecon 5/06/04 at 5:00 pm
Date: Tue, 4 May 2004 23:43:53 -0700
Importance: high
X-Mailer: Internet Mail Service (5.5.2653.19)

Folks,

Please find attached IP list on which [redacted] can added summary of our discussion today in the last column.

Understanding each company's position on those patent applications at this time, we'd like to propose a telephone conference as follows,

Date & Time: 5/6(Thu) 5:00pm(EDT), 5/7(Fri) 6:00am(JST)
Call-In: TBD (Will send you separate e-mail once notified by redacted.)
Attendees: redacted-san, redacted Attorneys
 EC/ETI - Sasabe-san, Fukunaga-san, Nambu-san, Musaka
 (Please add appropriate person(s) if necessary.)

I understand it's very early in the morning. However, that's only time attorneys are available. Also, originally, [redacted] -san was proposing sometime in next week, but all the sudden, she is in a hurry to conclude the discussion, and wants to hold the meeting in this week.

I really appreciate for your generous understanding and strong support on this matter.

Best Regards,
K.Musaka

-Original Message

Redacted

由, 08:55 04/05/06 +0900, Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/

redacted

Y, 08:55 04/05/06 +0900, Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/

To: General Manager Y. Fukunaga

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/04 at 5:00 pm

Cc:

Bcc:

Attached: C:\PROGRAM FILES\EUDORA\attach\EBARA

Applications_030904ユ_[redacted: the US company]_invent_05_04_04_Musaka.xls;

Mr. Fukunaga,

I can attend the telephone conference to be held from 6:00 am on Friday. If the other members can attend the conference, please replay to Mr. Musaka that we are ready.

I think Mr. Mishima should also attend the conference.

Today I will leave for Haneda around 10:30, so I cannot handle the matter. Your arrangement would be greatly helpful.

[Below to the end is originally English text.]

Yukio Fukunaga, 14:14 04/05/07 +0900, Re: S1 Project 特許の件

To: Yukio Fukunaga <fukunaga.yukio@ebara.com>
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Re: S1 Project 特許の件
Cc:
Bcc:
Attached:

福永様
共願6件は #2、#22、#26、#28、#29、#30のことですね。
#26は三島さんのコメントはありましたが、共願として良いですか？
他の点については、これで良いと思います。

At 13:55 04/05/07 +0900, you wrote:
笹部様

下記のメール案を作成してみましたので、内容をご検討頂きたいをお願いします。
(本日中の回答希望にしましょうか？)
(あるいは六平さんにECにて検討中ということにして、時間をもらいましょうか？)

福永(由)

辻村 役員殿

標記の件、現状報告と懸案事項のご相談を申し上げます。

【現状】

2月のWorkshop後、笹部さんセンターで特許の帰属について、下記のように^{redac}_{ted}と調整中
です。

- ・検討案件: 30件
 - ・荏原単願: 19件
 - ・IBM・荏原共願: 6件
 - ・調整中: 5件 (内4件はJDP契約前出願、内3件PCT出願済み)

【懸案事項】

荏原としては極力単願での調整を進めてきましたが、上記調整中の5件は、荏原が単願
を主張
するものの、折り合いが付いておりません。
(今朝方の先方Attorneyを含めたテレコンでも、平行線を辿ったままです)

内容が所謂擦りめっきの方法と装置であるため、当方は2001年頃実施していた「擦り
めっき」の
資料(日付はなし)を提示して理解を求めましたが、^{redac}_{ted}の主張はJDPに入る前に荏原の
バック
グラウンド技術を開示すべきだったのに、今になって開示するのは手続きとしておかしい、と
いう具合です。
また^{redac}_{ted}として、S1プロジェクトの成果としての期待(メンツ?)もあるようにも感じます。

【対処案】

上記調整中5件に関し、両社ギリギリの線で受容できそうな下記の案を提案したいと考
えます。

- ・日本出願およびPCT出願(USは除く)は、荏原単独のまま (ただし一部クレーム補正

必要)

・US出願は共願 (ただしworkshop時に提案受けた^{redac}_{ted}の発明を新たに組み込むこと)

●本対処方法に関し、アドバイス頂ければ幸いです。

対処案でOKであれば、笹部さんの方で作業を進めて頂く予定です。

福永(由)

Yukio Fukunaga, 14:14 04/05/07 +0900, Re: Regarding S1 project patent

To: Yukio Fukunaga <fukunaga.yukio@ebara.com>
From: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: Re: Regarding S1 project patent
Cc:
Bcc:
Attached:

Mr. Fukunaga,

You mean the six joint applications are #2, #22, #26, #28, #29, and #30.

Mr. Mishima has commented on #26. Is it OK that #26 will be a joint application?

For the rest, I think the draft is OK.

At 13:55 04/05/07 +0900, you wrote:

Mr. Sasabe,

I've prepared a draft of an e-mail as shown below. Please check and review its details.

(Should we request a response to the e-mail within today?)

(Or, should I make a report to Mr. Musaka that the matter is under consideration at EC to gain some time?)

Y. Fukunaga

Member of the Board, Mr. Tsujimura,

Regarding to the subject matter, I will report the current situation and present related concerns.

[Current situation]

After the workshop in February, we are in coordination with [redacted: the US company] for application filing, led by Mr. Sasabe, as described below.

- Under discussion: 30 applications
- Sole application by Ebara: 19 applications
- Joint application by [redacted: the US company] and Ebara: 6 applications
- Under coordination: 5 applications (four of which have been filed before conclusion of the JDP contract and three of which have been also filed as PCT applications.)

[Related concern]

Ebara has made best efforts so that the applications can be filed as sole applications; however, no agreement is reached for the five applications under coordination that Ebara insists should be filed as sole applications.

(The telephone conference, held this morning with the inclusion of the other side's attorney ended up without any progress.)

Those applications are related to the method and apparatus for "rubbing & plating," so we presented documents (without date) on studies about "rubbing & plating" implemented around 2001. With these materials, we asked for their understanding. [redacted: the US company], however, maintained as follows: Ebara should have disclosed the background technique before implementation of the JDP. Disclosing the technique at this late date is an unjustifiable action.

[redacted: the US company] has probably placed expectations on (and had pride about) potential results of the S1 project.

[Proposed action]

For the five applications under coordination, we would like to make a proposal below that may be at least accepted by both the companies:

- Sole application by Ebara for Japanese and PCT applications (excluding U.S. applications) (Correction of some claims is required.)
- Joint application for U.S. applications (Incorporation of the invention by [redacted: the US company] proposed at the workshop is required.)

Your advice on this proposal would be appreciated.

If the proposal described above is OK, I will ask Mr. Sasabe to go forward

Y. Fukunaga

redacted

11:17 04/05/08 +0900, Re: Disclosures Number 2 and 22 first filed in Japan

To: redacted <redacted.com>
From: 笹部憲一 <sasabe.kenichi@ebaracom>
Subject: Re: Disclosures Number 2 and 22 first filed in Japan
Cc: Mr. Y.Fukunaga, Mr. Mishima, Mr. Musaka, Mr. Akai
Bcc:
Attached:

Dear redacted-san

Thank you for your e-mail.

I think the Ebara inventors made their invention in Japan. But I will confirm them on Monday.

I will discuss with Mishima-san and Fukunaga-san about the facts and the reasons of the error, and I will send you our story.

Thank you very much for your help.

Best regards,
Kenichi Sasabe

At 17:39 04/05/07 -0400, you wrote:

redacted

redacted

PREPARED BY ^{redac}_{ted} ATTORNEY / PRIVILEGED AND CONFIDENTIAL

三島部長殿, 13:58 04/05/29 +0900, 米港特許庁にExport Licenseを申請するに当たっての

To: 三島部長殿
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: 米港特許庁にExport Licenseを申請するに当たっての資料の件
Cc:
Bcc:
Attached:

S1プロジェクトに関する出願に関連する資料のコピーをお出してください。

Export Licenseを申請するには、直接関与した人の請願書と証拠資料の提出が必要です。

現在ペンディングになっている物も含めて、#2, 4, 10, 11, 12, 13, 14, 16, 20, 22, 24, 26, 28, 29合計14件に関する資料(発明に関する資料、発明者への指示、出願依頼、弁理士との相談、知財部との相談、木村さん、六平さん、IBMとのコレポン、ノート、e-mail など)のコピーをご提出ください。

福永さん、知財部、牧野さん、国沢さんには27日に依頼しました。

General Manager Mishima 13:58 04/05/29 +0900, Regarding documents for Export License application to USPTO

To: General Manager Mishima

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Regarding documents for Export License application to USPTO

Cc:

Bcc:

Attached:

Submit copies of documents on the application fling linked to the S1 project.

Upon export license application, application forms filled by those directly involved and evidence documents must be submitted.

Submit copies of documents on the 14 applications in total, including the pending ones: #2, 4, 10, 11, 12, 13, 14, 16, 20, 22, 24, 26, 28, and 29 (documents related to the invention, instructions to the inventors, request of application filing, consultation with the patent agent and Intellectual Property Dept., correspondence between Mr. Kimura and Musaka and [redacted: the US company], related notebooks and e-mails, etc.).

I already asked Mr. Fukunaga, Intellectual Property Dept., Mr. Makino, and Mr. Kunisawa on May 27 to submit the documents.

倉科殿, 並木殿, 中田課長殿, 三島部長殿, 神田課長殿, 長井殿, 山, 21:59 04/06/08 +0900, redacted

To: 倉科殿, 並木殿, 中田課長殿, 三島部長殿, 神田課長殿, 長井殿, 山本殿716, 森沢殿, 井出殿753, 鈴木秀直殿, 君塚リーダー殿, 国澤課長殿

From: 笹部憲一 <sasabe.kenichi@ebaracom>

Subject: redacted 米国発明の外国出願に関する協力依頼の件

Cc: 牧野殿, 赤井部長殿, 坂口担当部長殿

Bcc:

Attached: D:\My Documents\redacted PaP project\調査協力依頼040609.doc; D:\My Documents\redacted PaP project\Pedersen依頼\Retroactive Foreign Filing License Statement2.xls; D:\My Documents\redacted PaP project\発明者質問状.doc;

redacted と実施しているS1(PaP)プロジェクトにおいて、EBRが日本で単独出願していた出願に対し、redacted から共願にするよう要求があり、調整しておりますが、現在13件が共願の検討対象となっています。

redacted と共願にする場合には、redacted の発明者を追加することになり、米国で為した発明は米国に最初に出願しなければならない規定に違反します。このため、米国特許庁及び商務省に Retroactive Foreign Filing Licenseを請願する必要があります。これに関しまして、添付依頼書に基づき、質問書へのご回答を戴きたくお願い致します。

なお、6月21日に redacted と打合せが予定されており、それまでに対応する必要がありますので、恐縮ですが6月11日までにご回答いただきたく、ご協力お願い致します。

作成日
DATE 2004. 6. 9. P. 1

宛 先
FOR 下記各位

DOC.No. 708-A460901

題 目 TITLE	全 TOTAL	枚 SHEETS
米国発明の海外出願に 関する協力依頼の件		
作成目的 PURPOSE	調査協力依頼	
プロジェクト名 PROJECT	S1	
用 途 SERVICE	Export License	
JOB No.	荏原製番 EBARA SER.No	
ITEM No.	機名/装置名 MODEL / EQUIP.	台数 SET

redac
-ted と実施している S1 (PaP) プロジェクトにおいて、EBR が日本で単独出願していた出願に対し、redac
-ted か
ら共願にするよう要求があり、調整しておりますが、現在 13 件が共願の検討対象となっています。

redac
-ted と共願にする場合には、redac
-ted の発明者を追加することになり、米国で為した発明は米国に最初に出願し
なければならない規定に違反します。このため、米国特許庁及び商務省に Retroactive Foreign Filing
License を請願する必要があります。

既に共願にすることが決まっている牧野さん、国沢さんには既にお話を伺いましたが、他の方にも添付資
料にご記入の上特許部宛て返送をお願いします。(国澤殿：表の #28 分割アードについてご回答ください。)
請願が認められるためには、違反に気づいた後、速やかに手続きを行うことが必要ですので、恐縮ですが、
至急 6 月 11 日までに ご回答をお願いします。

該当する出願は添付の EBR/redac
-ted 共願検討出願の表に記載の物です。

発明内容の簡単なメモをつけてありますが、出願原稿をご覧になりたい方は特許部笹部 (8550) 又は坂口
(9020) までご連絡ください。

質問用紙は質問書 A と質問書 B に分かれています。

質問書 A は発明者の S1 (PaP) プロジェクトとの関連に関する質問です。発明者毎に 1 回お答えください。

質問書 B は各出願に関する質問です。出願 1 件ごとにご回答ください。複数の出願の発明者になっている方
は、恐縮ですが質問書 B をコピーしてご使用ください。

e-mail でもお送りしておきますので、必要な場合はプリントアウトして戴いても結構です。

依頼先

716 倉科殿、716 並木殿、716 中田殿、716 三島殿、753 神田殿、753 長井殿、716 山本殿、756 森澤殿、
753 井出殿、716 鈴木殿、EU 君塚殿

cc 760 国澤殿、760 牧野殿

A・実施または手配 ACTION NECESSARY	発 行 ISSUED BY	承 認 APPROVED BY	係 CHECKED	員 BY
B・関 連 部 署 CONTENTS ESSENTIAL	精密・特許部		笹部	
C・参 考 まで INFORMATION ONLY				

Kurashina, Namiki, Manager Nakada, General Manager Mishima, Manager Kanda, Nagai, Yama, 21:59 06/06/08 +0900, [redacted: the US company]

To: Kurashina, Namiki, Manager Nakada, General Manager Mishima, Manager Kanda, Nagai, Yamamoto716, Morisawa, Ide753, Hidenao Suzuki, General Manager Kimizuka, Manager Kunisawa

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Regarding request of your cooperation about foreign filing of inventions with [redacted: the US company] in USA

Cc: Makino, General Manager Akai, Manager Sakaguchi

Attached: D:\My Documents\ [redacted: the US company] Pap project\Call for cooperation for investigation 040609.doc; D:\My Documents\ [redacted: the US company] Pap project\Pedersen Request\Retroactive Foreign Filing License Statement2.xls; D:\My Documents\ [redacted: the US company] Pap project\Questionnaire to inventors.doc;

Regarding the S1 (PaP) project operated with [redacted: the US company], [redacted: the US company] has requested us to change the sole applications filed by EBR in Japan to the joint applications. We have worked on this issue and identified 13 applications are subject to discussion for joint application.

If they are filed as the joint applications with [redacted: the US company], inventors of [redacted: the US company] will be added. This violates the regulation providing any invention achieved in the U.S.A. shall be filed in the U.S.A. first. To solve this problem, we need to get up a petition for Retroactive Foreign Filing License to Department of Commerce and the United States Patent and Trademark Office

I attached a document regarding this issue. I'd like to request all of you to respond the questionnaire.

Please note that a meeting will be held on 21 June with [redacted: the US company]. We need to prepare till that date. I realize all of you are very busy; though, please return your answer by 11 June. I call for your cooperation.

作成日
DATE

2004. 6. 9.

P. 1

宛 先
FOR

All concerned

DOC.No.

708-A460901

題 目 TITLE	Request for your cooperation regarding foreign filing of inventions in the U.S.A.	全 枚 TOTAL SHEETS
作成目的 PURPOSE	Request for investigation	
プロジェクト名 PROJECT	S1	用 途 SERVICE
JOB No.		Export License
ITEM No.		在 原 製 番 EBARA SER.No
	機名/装置名 MODEL / EQUIP.	台数 SET

Regarding the S1 (PaP) project operated with [redacted: the US company], [redacted: the US company] has requested us to change the sole applications filed by EBR in Japan to the joint applications. We have worked on this issue and identified 13 applications are subject to discussion for joint application.

If they are filed as the joint applications with [redacted: the US company], inventors of [redacted: the US company] will be added. This violates the regulation providing any invention achieved in the U.S.A. shall be filed in the U.S.A. first. To solve this problem, we need to get up a petition for Retroactive Foreign Filing License to Department of Commerce and the United States Patent and Trademark Office.

Though I already requested Mr. Makino and Mr. Kunisawa, whose inventions have already determined to be joint applications, I'd like to request other members to answer the questionnaire, an attached file. When you complete, please return to Patent Dept. (To Mr. Kunisawa: Please answer Item #28 in the list about divided anode).

To make our petitions granted, quick action must be taken as soon as we realized violation. I understand all if you are very busy; though, please return your answer immediately by **11 June**.

The applications in question are listed on an attached file regarding the filing of EBR/[redacted: the US company] joint applications.

I gave brief comments about the inventions; though, please contact Sasabe (8550) or Sakaguchi (9020) in Patent Dept. if you wish to refer drafts of the applications.

The questionnaire is divided into Form A and B.

Form A lists questions about relations between the inventor and the S1 (PaP) project. All inventors are requested to answer.

Form B lists questions about each application. All inventors are requested to answer per application. If multiple inventors achieve the invention, please make a copy of Form B and answer. I send the same document via e-mail as well. You can print out if necessary.

Person who are requested to answer the questionnaire

716 Kurashina, 716 Namiki, 716 Nakada, 716 Mishima, 753 Kanda, 753 Nagai, 716, Yamamoto, 756 Morisawa, 753 Ide, 716 Suzuki, Kimizuka of EU
cc: 760 Kunisawa, 760 Makino

A・実施または手配
ACTION NECESSARY発 行
ISSUED BY承 認
APPROVED BY係
CHECKED員
BYB・関連部署
CONTENTS ESSENTIAL

Patent Dept.

Sasabe

C・参考まで
INFORMATION ONLY

Precision Machinery Group



EBARA CORPORATION

Support Document AF

赤井部長殿、篠塚担当部長殿、16:11 04/06/11 +0900, Fwd: Meeting with Mr. redacted

To: 赤井部長殿、篠塚担当部長殿
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: Meeting with Mr. redacted
Cc: 坂口担当部長殿
Bcc:
Attached:

赤井様、篠塚様

いろいろとお手数をかけていますredactedの特許の件ですが、下記のように解決の方向に向かうことになりました。

6月10日にredactedでredactedのProject ManagerであるMr. redactedと荏原のProject Managerである木村さん、ETIのDan O'connell、南部さんとで会談し、特許出願の件で、契約違反等の問題になりかけていた件をとりあえず解決してくれました。今後の出願は、明確にredactedと関連しないものは荏原単願の日本出願でよいですが、redactedが関係する可能性のあるものは基本的に米国出願とすることとし、出願前に英文原稿をredactedに見せることにします。辻村さんにもこの方向で了解をもらっています。こうすると、米国出願の件数が増えること(日本出願を何件かまとめて米国出願できなくなる)、出願までの日数が増えること、原稿作成が日本の弁理士、redacted、米国弁護士それぞれで変更、修正される可能性があり、新たな問題が出てくる可能性が有ることなど、いくつか問題が考えられますが、このredactedの件に関しては特別扱いとすることとします。知財部にも、いろいろとご迷惑を掛けることが増えると思いますが、よろしくお願い致します。

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: "M Tsujimura" <tsujimura.manabu@ebara.com>, ogata.akira@ebara.com, "Kobayashi, Fumio (E-mail)" <kobayashi.fumio@ebara.com>, fukunaga.akira@ebara.com, fukunaga.yukio@ebara.com, tokushige.katsuhiko@ebara.com, hodai.masao@ebara.com, mishima.koji@ebara.com, asami.masao@ebara.com, "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>, Kimura Norio <kimura.norio@ebara.com>, "Nambu, Isao" <inambu@ebaratech.com>, "O'Connell, Dan" <doconnell@ebaratech.com>
Cc: horiuchi.takao@ebara.com, yago.natsunosuke@ebara.com
Subject: Meeting with Mr. redacted
Date: Thu, 10 Jun 2004 23:04:21 -0700
X-Mailer: Internet Mail Service (5.5.2653.19)

Great thanks to everybody participated in the quite intensive discussion in last week while my stay in Japan. I believe our meeting today with Mr. redacted was truly successful and satisfactory.

Dan, Nambu-san, Kimura-san and myself visited Mr. redacted today for the discussion on IP issue in JDA. (redacted-san also participated by phone.) The discussion was initiated by Dan explaining historical background of this matter, "Ebara had been working on planer plating technology prior to the engagement with redacted for the JDA, and filed patents before the contract, but after initial technical information exchange with redacted on this matter. Ebara should have informed redacted the background IPs in time to avoid any confusion and conflict on the IP ownership. After internal discussion at Ebara, Ebara agreed to modify those patent applications as co-invention with redacted recognizing its impact on the program and redacted's business."

Mr. redacted stated "redacted could not understand why Ebara did not submit the

background IPs at the 1st workshop in Sept'03 accordingly to the JDA contract". I replied "Ebara understood the contract, and actually submitted the IP list at the workshop. However, the list was too brief to discuss the details, and re-submitted the list with abstracts in the workshop in Feb'04, which caused some delay in our initial discussion on this matter with redacted. Since then, we've been working with redacted technical coordinator for identification of IP ownership, and redacted attorneys for modification of total 8 Ebara's Japanese patent applications into co-invention with redacted applying for export license for corresponding US patent applications. redacted-san also backed us up stating "Those were the same understanding as hers".

I also explained "In order to avoid any confusion in patent application process in the future, Ebara propose to submit whole translation of IP disclosure to redacted before filing patent application for redacted's review and determining the co-ownership. redacted-san stated "1-page summary or abstract of US patent application should be sufficient." Dan stated "This process change requires redacted's strong support in timely corresponding redacted's decision to Ebara since Ebara rely on redacted's reply for filing the patent application."

Finally, I apologized the confusion and promised the compliance to the contract, and Mr. redacted replied "I'm fine, now."

I also talked with redacted-san after the meeting by phone, and she said "The meeting was quite satisfactory."

I understand it was difficult time for everybody to re-evaluate the contract and determine the countermeasure. Now, I believe, we have better understanding of the contract and how it impacts Ebara's business. We have no choice than succeeding the JDA with redacted.

Once again, thank you very much for your understanding and continuous support on this matter.

Best Regards,
K.Musaka

General Manager Akai, Manager Shinozuka, 16:11 04/06/11 +0900, Fwd: Meeting with Mr. [redacted: personal name]

To: General Manager Akai, Manager Shinozuka
From: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: Fwd: Meeting with Mr. [redacted: personal name]
Cc: Manager Sakaguchi

Dear Mr. Akai, Mr. Shinozuka,

Regarding the issue related to [redacted: the US company] that we have worked on, I have a news that it will be solved as shown below.

In the meeting held on June 10 in [redacted: the US company], Mr. [redacted: personal name], Project Manager of [redacted: the US company], Mr. Kimura, Project Manager of Ebara, and Mr. Dan O'connell and Mr. Nanbu of ETI discussed the patent filing issue and finally managed to solve the point that might cause breach of contract.

In future, inventions clearly irrelevant to [redacted: the US company] can be sole applications of Ebara, however, if they are possibly relevant to [redacted: the US company] basically, they will be joint applications. English drafts will be shown to [redacted: the US company] before filing. Mr. Tsujimura has already agreed with this direction. This procedure may cause other problems, such as, that the number of filing in the U.S.A will be increased (combining a batch of applications filed in Japan to one US application will not be allowed); that days taken for preparing for filing patent application will be increased; or that drafts may be changed or corrected by Japanese patent attorney, [redacted: the US company], patent attorneys in the U.S.A; however, regarding the issue that [redacted: the US company] is involved is exceptional.

On the way to solve the problem, we may cause more inconveniences to Intellectual Property Dept.; though, I appreciate your understanding and cooperation.

[Below to the end is originally English text.]

04.4.19

福永(由)

三島

坂口

西村

#4

① 明細書

(電圧の大小
の差を比較)

redacted 開示

電圧 ④ 電解装置の出力

redacted 内容の支離滅裂
出所が redacted と相違

全部共通部分は図3

① 事実 (図3) は明確に示す
redacted 開示とは違っていると
述べている。空欄がある。

plating 12 図に ON/OFF 押当て有る
EBR original

② EBR original 3.4.7.9.10.11.12
は分割して EBR 単原 他は共通

③ 又は方法等所 装置 EBR 単原

④ 全部共通部分 但し 細かい部分 1/2 up.
詳細 → redacted の細かい部分 1/2 up.

① ② ③ はそれぞれ 6 平方メートルに渡す
redacted の説明者 三島 B → 詳細部分

#12

Claim 1: 2001.7.9 redacted の内容が
EBR の説明を主張

既出部分のパスは 三島 B によって 図3 へ
二層のパスの図から 図3 へ EBR のパス

#14

図3 へ 水素シールド外した → 国内特許
Claim 1 の #4 の claim 8 と 同内容

Claim 2 の共通部分 (redaction)
他は EBR original

#14 (3点)

基振保持に上下は EBR original.

claim 3, 4, 5 の discussion (21点)

claim 6 EBR 717P. ^{redacted} の Down force 仕様は +

claim 7 EBR

8, 9, 10, 11, 12 の 7, 9 送属

claim 13 の 相対運動後通電 EBR idea

14 の 13 の送属

claim 1, 2 の 共振の中心を得るための成立条件?

#24

claim 1 「静止状態に達して通電」, 即ち削除

#4 の claim 1 の 共振の中心を得るための成立条件?
共振の中心を得るための成立条件? #4, claim 1 の 共振 EBR 717P の送属

claim 12 EBR original 離肉機構

13, 14 12 の送属

15 振動の EBR idea

#10

claim 1 シールを削除

押圧離肉機構の中心は EBR original

claim 13 温度調整機構 ^{redacted} 要求
→ 共振

claim 16 押圧機構, 共振の中心は, 共振の中心?

17 EBR original

18

19~24 共振の中心は直感で推定

claim 2~

4 押圧機構 EBR original

5, 6 共振 EBR original

7 共振の中心

8, 9, 10, 11 air bag EBR original

12 11 の送属

14 押圧機構破壊 EBR original

15 EBR original 共振機構

#4

A Specification

Amplitude of plating voltage

Pressing and Detaching

[redacted: the US company] disclosure

voltage +, — include electro-etching

As the inventions of [redacted: the US company] have not been filed, ask [redacted: the US company] if they want to file their inventions.

Ebara don't want to make the whole application a joint application.

1. Facts should be made clear for each claim.

This invention is different from the technology that [redacted: the US company] presented.

Some points of their presentation gave us a chance to consider.

Plating technology with the current repeating ON and OFF and with a pad repeating touching and detaching the substrate is Ebara's original technology.

2. EBR original applications 3, 4, 7, 9, 10, 11, 12 will be divided and made Ebara sole application. Others will be joint application.

3. Or, method claims will be jointed, and apparatus claims

will be Ebara sole.

4. Make all applications joint applications. Give us some

rights for their patents useful for Ebara in return.

Patent Dept. → List up patents of [redacted: the US company] useful for Ebara.

Summarize 1, 2 and 3 above, and will send to Mr. Musaka.

Inventors' names of [redacted: the US company]

General Manager Mishima → Patent Dept.

#12

Claim 1: Ebara will claim that the invention is Ebara original based on a small diameter polishing pad presented to [redacted: company name] in 2001.7

Mr. Mishima will search Ebara's applications regarding a pad for plating filed so far and inform Patent Dept.

Supplying solution between two layers of a pad is Ebara's idea.

#14

The phrase "to water tightly seal the edge part" should be deleted. → domestic priority application

Claim 1 of this application has the same invention with claim 8 of #4.

Claim 2 is joint filing. (rotation)

Other claims are Ebara original.

04.4.19

Y, Fukunaga

Mishima

Sakaguchi

Sasabe

#14(continue)

Claim 3, 4, 5 were not discussed.

Claim 6 is Ebara idea. [redacted: the US company] presented down force was always +.

Claim 7 : EBR

Claim 8, 9, 10, 11 and 12 are dependent claims of claim 7.

Claim 13 : applying current after relative motion is Ebara idea

Claim 14 is a dependent claim of claim 13.

Claim 1 and 2 may be joint applications, but may be difficult to be patented.

#24

Claim 1 : the phrase carrying current "in a state that the conductor layer is static to the porous product", "—" part should be deleted.

In this claim 1, plating solution compositions were added to Claim 1 of #4 application. Plating solution is publicly known. We will claim this claim is Ebara idea like claim 1 of application #4.

Claim 12 : Ebara original. A pressing and separating mechanism. 13, 14 Dependent claims of claim 12.

14 : Vibration is Ebara idea.

Vertical movement of the substrate holding part is Ebara original idea.

#10

Claim 1 : Seal should be deleted

A pressing and separating mechanism is Ebara original idea.

Claim 13 : Temperature adjust mechanism is on the tool requirement list of [redacted: the US company] → joint application

Claim 16 : pressing and plating is publicly known. No patentability?

17 : Ebara original

18 : Ebara original

19-24 : not related to plating

Claim 2

4 : torque sensor for detecting running torque is Ebara original idea.

5, 6 : air bag is Ebara original idea.

7 : multilayer structure of the porous product may be publicly known.

8, 9, 10 and 11 : air bag is Ebara original idea

12 : Dependent claim of claim 11.

14 : pressurize the backside of the substrate with fluid is Ebara original idea.

15 : Ebara original. Vibrating mechanism is Ebara original idea.

Mr. Musaka, Mr. Y.Fukunaga, Mr. Mishima, 00:48 04/05/20 +0900, Fwd: S1出願

To: Mr. Musaka, Mr. Y.Fukunaga, Mr. Mishima
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: S1出願
Cc:
Bcc:
Attached: D:\My Documents\redacted PaP project\各出願の要点.xls;

各位

電話打合せに基づき、クレームにパッド(またはそれに類する物)の記述のある出願を確認しました。
添付の表のようになります。

三島さんとは相談しましたが、福永さんとは相談できていません。
電話会議で下記#13、16を話すことにするか、明朝福永さんと相談します。
この情報は参考としておいてください。

福永さん、三島さんに先程お送りした物を若干修正しています。

含浸材(高抵抗体)にパッドをつけたものを対象と考えます。("アノードの表面にパッド"まで含めると、含浸めっきや、TSBの特許まで入ってしまいます。)

#11:六平さんとの議論に出ましたが、パッドの記述はありません。日本出願はEBR単願、外国出願(PCT)は#4、10、12とまとめて1件になっていますので共願としたいと思います。

#13:フェースダウンのめっきです。含浸材の上に基板接触体があり、基板と接触します。この出願はクレームの英訳を作っていません。基板接触体は従属項で出てくるので、Excel sheetの英訳には基板接触体がかかれていませんでした。"a substrate contact element disposed on the resistive porous element"をexcel sheetの記述に追加する必要があります。フェースダウンなので、S1とは無関係と出来ますでしょうか。共願も止むなしと思います。

#15:金属イオンを透過させない隔膜を基板表面に接触させ、金属イオンの供給を制限する物です。クレームでは含浸材又は高抵抗体は記述されていないので、含浸材+パッドという構成とは異なり、無関係と考えます。図では全て高抵抗体の表面に隔膜が配置されています。パッドで擦って添加剤を除去するのとは考えが異なります。これはクレームの英訳を作っていません。

#16:分割含浸材+多孔質体。含浸材の分割を主な発明とするものですが、多孔質体の均一な接触を目的としており、IBMが興味があるなら共願でしょうか。これはクレームの英訳を作っていません。

#21:アノードと被めっき面の間にイオン交換膜を配置する物です。クレームには含浸材や高抵抗体はなく、イオン交換体だけがあると解釈できますので、無関係としたいと思います。図3(メインの実施例)では含浸剤の変わりにイオン交換体が置かれています。他の実施例では、含浸材の上にイオン交換膜が配置されています。クレームでは含浸材の上にイオン交換膜という構成ではありませんので、無関係とします。

検討対象の

#4、#10、#12は多孔質接触体と含浸材、又は多層の多孔質材をクレームしています。(これはPCT出願していますので、#11も含めて、対象国全てに関するExport Licenseを取るようになります。多分通常のerrorの理由説明の他に、対象国名を並べて書くだけで済むと思います。)

#14、#24はパッドのクレームはありませんが、接触なじませの出願です。

#26, 28, 29, 30はパッドのクレームはありません。

クレームの英訳を作った物は #4, 10, 11, 12, 14, 22, 24, 26, 28, 29だと思います。上記13, 15, 16, 21は英訳がありません。

ここに書いていない物も全てクレームをチェックしましたが、他にはパッドの記述はありません。

Mr. Musaka, Mr. Fukunaga, Mr. Mishima, 00:48 04/05/20 +0900, Fwd: S1 application

To: Mr. Musaka, Mr. Y. Fukunaga, Mr. Mishima
From: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: Fwd: S1 application
Cc:
Bcc:
Attached: D:\My Documents\¥[redacted: the US company]PaP project¥points of each application.xls;

To all concerned,

Based on the telephone conference, I have identified patents that contain descriptions of a pad (or a means equivalent to it) in their claims.
They are as listed in the attachment.

I have discussed the matter with Mr. Mishima, but not with Mr. Fukunaga yet.
I will either discuss #13 and 16 below in the telephone conference or talk with Mr. Fukunaga tomorrow morning.
Regard this information is only for your reference.

I have slightly made corrections on what I sent to Mr. Fukunaga and Mr. Mishima earlier.

We regard impregnants (highly resistive element) with a pad fall into the category. (If we extend to cover "a pad on an anode surface," impregnation plating and [redacted: a Japanese company]) patents are also going to be included.)

#11: As mentioned during the discussion with Mr. Musaka, there is no pad description. For the Japanese patent application, we would like to file it as Ebara's solo application. But for the international application (PCT), as it is a bundle of #4, 10, and 12, we would like to file it as a joint application.

#13: It is a facedown-type plating. On the impregnant, a substrate contact element exists and this contacts with the substrate. We have not translated the claims into English. The substrate contact element is described in the dependent claims; therefore, it was not written in the translation in the Excel form. A sentence "a substrate contact element disposed on the resistive porous element" needs to be added to the description in the Excel form. Since this is the facedown-type, I wonder if it can be deemed to have no relation with S1. I think its joint application is unavoidable.

#15: This application restricts metal ion supply by contacting a barrier membrane that impermeates metal ions with a substrate surface. The claims do not describe neither the impregnant nor the highly resistive element. Therefore, we assume it is different from a construction of an impregnant + a pad, thus, has no relation. In the drawing, the barrier membranes are arranged on all surfaces of the highly resistive element. Its approach is different from additive removal by scrubbing with a pad. We have not translated the claims into English.

#16: Segmented impregnant + porous material. Although this application holds segmentation of the impregnant as the primary invention, the segmentation is for uniform contact of the porous material. If [redacted: the US company] is interested in this, this may be filed as the joint application.
We have not translated the claims into English.

#21: This application has an ion exchange membrane between an anode and a plating target. The claims do not describe the impregnant or the highly resistive element, and the method is interpreted as having the ion exchanger only; thus, I want to conclude this has no relation. In Fig. 3 (main preferred embodiment), an ion exchanger is mounted instead of an impregnant. In other preferred embodiments, an ion exchange membrane is placed on an impregnant. The claims do not describe a structure having an ion exchange membrane on an impregnant; we shall conclude this has no relation.

The applications under review, #4, #10 and #12, claim a porous material contactelement and an impregnant or a multi-layered porous material. (Since this is filed for PCT, we will have to obtain the Export License, including #11, for all target countries. Most likely, just listing the names of the target countries in addition to ordinal explanations for error, I think.)

Although #14 and #24 do not claim on a pad, they are applications related to better contact.

The applications #26, 28, 29, and 30 do not claim on a pad.

Claims have been translated into English for #4, 10, 11, 12, 14, 22, 24, 26, 28, and 29, I think. The applications 13, 15, 16, and 21 above do not have English translations.

I have checked all claims even not written here, and those other than mentioned here do not describe a pad.

Mr. Musaka, 19:09 04/05/18 +0900, Fwd: Re: #26出願(2004-022178)

To: Mr. Musaka
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: Re: #26出願(2004-022178)
Cc: Mr. Y.Fukunaga, Mr. Mishima
Bcc:
Attached: D:\My Documents\redacted PaP project\EBR application English translation\特願
2004-022178\2004-022178specification.doc; D:\My Documents\redacted PaP project\EBR
application English translation\特願2004-022178\Drawing圧縮\Draw p1.lzh; D:\My
Documents\redacted PaP project\EBR application English translation\特願2004-
022178\Drawing圧縮\Draw p2.lzh; D:\My Documents\redacted PaP project\EBR application
English translation\特願2004-022178\Drawing圧縮\Draw p3.lzh; D:\My Documents\redacted
PaP project\EBR application English translation\特願2004-022178\Drawing圧縮\Draw
p4.lzh; D:\My Documents\redacted PaP project\EBR application English translation\特願2004-
022178\Drawing圧縮\Draw p5.lzh; D:\My Documents\redacted PaP project\EBR application
English translation\特願2004-022178\Drawing圧縮\Draw p6.lzh; D:\My Documents\redacted
PaP project\EBR application English translation\特願2004-022178\Drawing圧縮\Draw
p7.lzh; D:\My Documents\redacted PaP project\EBR application English translation\特願2004-
022178\Drawing圧縮\Draw p8.lzh; D:\My Documents\redacted PaP project\EBR application
English translation\特願2004-022178\Drawing圧縮\Draw p9.lzh;

六平様

前回の電話会議で三島さんから説明した#26の明細書の英訳です。
クレームだけでは、redactedの権利が含まれているかどうか分からないので、明細書の訳を作り
ました。

但し、時間もあまりなかったので、明細書の全文ではなく、前半だけの英訳です。
後半は、知財部がつけた部分で、装置としてベベルエッチやリンス、無電解キャップめっきな
どが書かれています。後半部分は、JDPとは関係のない内容で、クレームもされていません
ので、翻訳は省略させていただきました。

図は圧縮してありますが、解凍できなければご連絡ください。(自動解凍ではありません)
三島さんにコメントしてもらう予定でしたが、本日出張ですので、明日三島さんに依頼します。
六平さんの判断も必要と考えますと、福永さんがコメントされています。
前回の電話会議と、それ以降のredactedとの打合せ状況を考えて、コメントいただければありが
たく存じます。

X-Sender: yf08594@pop.ebara.co.jp
X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J
Date: Tue, 18 May 2004 18:46:44 +0900
To: 笹部憲一 <sasabe.kenichi@ebara.com>, mishima.koji@ebara.com
From: Yukio Fukunaga <fukunaga.yukio@ebara.com>
Subject: Re: #26出願(2004-022178)

笹部様

翻訳有り難うございました。

六平さんにコメントを付けて、送って頂けますでしょうか。
(出来れば「何故在原単願と判断しているか」のコメントもあった方がよいのですが、
本日三島さんが外回りのため、コメントできるとしても明日になります)

まずは六平さんに送って、目を通して頂くのがよいと考えます。
(redactedにはまだ提出せずに、六平さんの判断も必要と考えます)

福永(由)

Mr. Musaka, 19:09 04/05/18 +0900, Fwd: Re: #26 application (2004022178)

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Re: #26 application (2004-022178)

Cc: Mr. Y.Fukunaga, Mr. Mishima

Bcc:

Attached: D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\2004-022178specification.doc;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p1.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p2.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p3.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p4.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p5.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p6.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p7.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p8.lzh;
D:\MyDocuments\redacted: the US company\PaP project\EBR application English translation\Patent application 2004-022178\Compressed Drawings\Draw p9.lzh;

Dear Mr. Musaka,

This is the English translation of the #26 specification, which was explained by Mr. Mishima in the previous telephone conference.

Since our US partner will not be able to determine whether the rights of redacted: the US company are included or not only by checking the claims, we translated the specification. However, we did not have enough time, and we only translated the first half, not the entire specification.

The latter half is the section added by Intellectual Property Dept., describing bevel etching, rinsing, and electroless cap plating as the apparatus. The latter portion has no contents relating to JDP and no claims are made; therefore, we skipped translating the section.

The drawings are compressed, and contact me if you cannot uncompress them. (They do not automatically decompress.)

I was planning to have comments from Mr. Mishima today. However, since he is out today, I will request that to Mr. Mishima tomorrow.

Mr. Fukunaga has commented me that he thinks Mr. Musaka's decision is also necessary. I appreciate your comments on this matter based on the discussions in the previous telephone conference and the perceptions acquired from the subsequent meetings.

X-Sender: yf08594@pop.ebara.co.jp

X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J

Date: Tue, 18 May 2004 18:46:44 +0900

To: Kenichi Sasabe <sasabe.kenichi@ebara.com>, mishima.koji@ebara.com

From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Re: #26 application (2004-022178)

Dear Mr. Sasabe,

Thank you for sending me the translation.

I appreciate if you send it to Mr. Musaka with the comment.

(If possible, I think it is better to have his comment on "why he has determined it for Ebara's sole application." Since Mr. Mishima is out today, it will be tomorrow if he can comment on it.)

I think it is good to first send it to Mr. Musaka and have him read it.

(I think we should not yet submit it to [redacted: the US company], and Mr. Musaka also needs to make decision about it.)

Y. Fukunaga

Mr. Pedersen, 09:43 04/06/02 +0900, Export License

To: Mr. Pedersen
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Export License
Cc:
Bcc:
Attached:

Dear Mr. Pedersen

redacted

Please give us your advise.

Best regards,
Kenichi Sasabe

Mr. Musaka, 15:37 04/06/08 +0900, Fwd: 英文翻訳の件

To: Mr. Musaka
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Fwd: 英文翻訳の件
Cc: Mr. Y.Fukunaga, Mr. Shinozuka, Mr. Sakaguchi
Bcc:
Attached: C:\PROGRAM FILES\EUDORA\attach\特願2003-195406翻訳.doc;

六平様

#14(2003-195406)の英訳をお送りします。
日本出願の優先日を確保するため、日本出願のそのままの英訳となっていますが、外国出願用に若干の構成の修正があります。
前回クレームのみ英訳してもらった事務所とは別の事務所で外国出願用に英訳していますので、クレームの部分も英訳しなおしています。

redacted でチェックする際、クレームの変更は問題ありませんが、明細書の内容を変更する場合には、それに関連する部分は、外国出願日が出願日となりますので、ご注意願います。修正する場合には、出来るだけ元の明細書をそのまま残し、修正部分を追加するようにしてください。

宜しくお願いします。

To: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: 英文翻訳の件
X-Mailer: Lotus Notes Release 5.0.8 June 18, 2001
From: shinozuka.shuhei@ebara.com
Date: Mon, 7 Jun 2004 14:14:11 +0900
X-MIMETrack: S/MIME Sign by Notes Client on shuhei shinozuka/e/ebara.jp(Release 5.0.8 |June18, 2001) at 2004/06/07 14:14:14,Serialize by Notes Client on shuhei shinozuka/e/ebara.jp(Release 5.0.8 |June18, 2001) at 2004/06/07 14:14:14,Serialize complete at 2004/06/07 14:14:14,S/MIME Sign failed at 2004/06/07 14:14:14: 暗号キーが見つかりません。Serialize by Router on ntnhan22m/e/ebara.jp(Release 5.0.12 |February 13, 2003) at 2004/06/07 02:14:17 PM

笹部部長殿

特願2003-195406の英文翻訳をお送り致します。

.....
篠塚 脩平

(株)荏原製作所 知的財産室
〒144-8510 東京都大田区羽田旭町11-1
TEL:03-3743-6872
FAX:03-3743-5745
E-mail:shinozuka.shuhei@ebara.com
.....

Mr. Musaka, 15:37 04/06/08 +0900, Fwd: Regarding the English translation

To: Mr. Musaka
From: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: Fwd: Regarding the English translation
Cc: Mr. Y.Fukunaga, Mr. Shinozuka, Mr. Sakaguchi
Bcc:
Attached: C:\PROGRAM FILES\EUDORA\attach\Patent Application No. 2003-195406 translation.doc;

Dear Mr. Musaka,

I send you the English translation of #14 (2003-195406).

To assure the priority date of the Japanese patent application, it is the direct translation of the Japanese application. However, it was given some layout corrections for foreign filing. This English translation is done by an office different from one, which translated only claims into English last time. Therefore, the claims section is again translated into English.

When checking it at [redacted: the US company], although changes in the claims is no problem, be careful that changes in the contents of the specification will regard its filing date as the filing date of the foreign application for those parts relating to the changes. When making corrections, it is best to leave the specification as is and add the corrections.

Thank you for your cooperation.

To: Kenichi Sasabe <sasabe.kenichi@ebara.com>
Subject: Regarding the English translation
X-Mailer: Lotus Notes Release 5.0.8 June 18, 2001
From: shinozuka.shuhei@ebara.com
Date: Mon, 7 Jun 2004 14:14:11 +0900
X-MIMETrack: S/MIME Sign by Notes Client on shuhei shinozuka/e/ebara_jp(Release 5.0.8 |June18, 2001) at 2004/06/07 14:14:14,Serialize by Notes Client on shuhei shinozuka/e/ebara_jp(Release 5.0.8 |June18, 2001) at 2004/06/07 14:14:14,Serialize complete at 2004/06/07 14:14:14,S/MIME Sign failed at 2004/06/07 14:14:14: cryptography key not found,Serialize by Router on ntnhan22m/e/ebara_jp(Release 5.0.12 |February 13, 2003) at 2004/06/07 02:14:17 PM

Dear General Manager Sasabe,

I send you the English translation of the patent application:

.....
Shuhei Shinozuka
Intellectual Property Dept.
Ebara Corporation
11-1 Asahicho Haneda Ota-ku
〒144-8510 Tokyo
TEL: 03-3743-6872
FAX: 03-3743-5745
E-mail: shinozuka.shuhei@ebara.com
.....

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
 To: "kurashina.keiichi@ebara.com" <kurashina.keiichi@ebara.com>, "hodai.masao@ebara.com" <hodai.masao@ebara.com>, "mishima.koji@ebara.com" <mishima.koji@ebara.com>, "Wada. Yutaka (E-mail)" <wada.yutaka@ebara.com>, "fukunaga.yukio@ebara.com" <fukunaga.yukio@ebara.com>, "nambu.isao@ebara.com" <nambu.isao@ebara.com>, "Fang, Rui" <rfang@ebaratech.com>, "Kumekawa, Masayuki" <mkumekawa@ebaratech.com>, "namiki.keisuke@ebara.com" <namiki.keisuke@ebara.com>, "kimura.norio@ebara.com" <kimura.norio@ebara.com>, "asami.masao@ebara.com" <asami.masao@ebara.com>, "Manabu Tsujimura" <tsujimura.manabu@ebara.com>
 Cc: "Yamamoto, Satoru (E-mail)" <yamamoto.satoru@ebara.com>, "kanda.hiroyuki@ebara.com" <kanda.hiroyuki@ebara.com>, "nakada.tsutomu@ebara.com" <nakada.tsutomu@ebara.com>, "Owatari Akira (E-mail)" <owatari.akira@ebara.com>, "Nanjo, Takahiro (E-mail)" <nanjo.takahiro@ebara.com>, "Maekawa, Fumio (E-mail)" <maekawa.fumio@ebara.com>, "makino.natsuki@ebara.com" <makino.natsuki@ebara.com>, "Morisawa. Shinya (E-mail)" <morisawa.shinya@ebara.com>, "Kunisawa. Junji (E-mail)" <kunisawa.junji@ebara.com>, "katsuoka.seiji@ebara.com" <katsuoka.seiji@ebara.com>, "Tokusige Katsuhiko (E-mail)" <tokusige.katsuhiko@ebara.com>, "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>, "jthoriuchi@aol.com" <jthoriuchi@aol.com>, "Kozo Nakao" <nakao.kozo@ebara.com>, "Fumio Kobayashi" <kobayashi.fumio@ebara.com>, "Akira Ogata" <ogata.akira@ebara.com>, "Fukunaga Akira (E-mail)" <fukunaga.akira@ebara.com>, "Natsunosuke Yago" <yago.natsunosuke@ebara.com>
 Subject: Revised - 3rd ^{redac}_{ted} JDP Workshop (6/21/04) Agenda
 Date: Wed, 16 Jun 2004 21:45:22 -0700
 Importance: high
 X-Mailer: Internet Mail Service (5.5.2653.19)

Folks,

Please find attached 3rd ^{redac}_{ted} JDP Workshop agenda which was revised based on discussion with ^{redac}_{ted} -san of ^{redac}_{ted} today.

Please note that the meeting location has been changed from ^{redac}_{ted} to ^{redac}_{ted}.

Please review and provide any inputs.

Best Regards,
 K.Musaka



Agenda rev1.doc

3rd redacted EBARA JDA Workshop Meeting Agenda

Date & Time: June 21, 2004 (Mon) 9:00am-5:30pm

Place: ETI
redacted

Phone: redacted

Agenda:

June 21, 2004(Mon)

redacted

* IP		
- IP List Update	K.Sasabe	3:30pm-5:00pm
* Wrap-Up with Action Plan Review	K.Musaka	5:00pm-5:20pm
* Closing Remarks	redacted	5:20pm-5:30pm

----- Dinner (Location TBD) -----

Mr. Musaka, 18:51 04/06/18 +0900, S1 IP list

To: Mr. Musaka

From: 笹部憲一 <sasabe.kenichi@ebara.com>

Subject: S1 IP list

Cc: Mr. Y.Fukunaga, Mr. Mishima

Bcc:

Attached: D:\My Documents\redacted PaP project\#3Workshop 04.06.21\EBR_redacted 04.06.21.ppt;
D:\My Documents\redacted 用EBR特許リスト\Ebara Patent Applications June15,2004.xls; D:\My
Documents\redacted PaP project\#3Workshop 04.06.21\Translation of claims of #13 Facedown
plating .doc; D:\My Documents\redacted PaP project\#3Workshop 04.06.21\Translation of
claims of #16 Apparatus for plating substrate.doc;

六平様

#3 workshop のIPの資料をお送りします。

パワーポイント

Excel sheet

#13のクレームの英訳

#16のクレームの英訳

です。

パワーポイントは会議で使用するものです。1.5Hrですので、かなり省略してやります。

Excel sheetは

#30,31,32が追加されています。全て共願です。

2,4,10,11,12,14,22,24,26,28,29は共願としました。

#13は従属項にパッドがあることを追記しました。

#13のクレーム及び#16のクレームの英訳は#13,#16のownershipの検討のための物です。
この帰属がもめることが無ければ、出す必要はないと思います。

Mr. Musaka, 18:51 04/06/18 +0900, S1 IP list

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: S1 IP list

Cc: Mr. Y.Fukunaga, Mr. Mishima

Bcc:

Attached: D:\My Documents\IBM PaP project\#3Workshop 04.06.21\EBR_[redacted: the US company] 04.06.21.ppt; D:\My Documents\EBR patent list for [redacted: the US company] \Ebara Patent Applications June15,2004.xls; D:\My Documents\[redacted: the US company] PaP project\#3Workshop 04.06.21\Translation of claims of #13 Facedown plating .doc; D:\My Documents\[redacted: the US company] PaP project\#3Workshop 04.06.21\Translation of claims of #16 Apparatus for plating substrate.doc;

Dear Mr. Musaka

I send IP document for #3 workshop.

The document is consist of

PowerPoint

Excel sheet

English translation of #13 application

English translation of #16 application.

PowerPoint document is for the meeting. As I have only 1.5hours, I will omit considerably.

In Excel sheet

#30, 31 and 32 are added. All joint applications.

#2, 4, 10, 11, 12, 14, 22, 24, 26, 28 and 29 are changed to joint applications.

Description of a pad in a dependent claim is added in abstract of #13.

English translations of applications #13 and 16 are for study of ownership of these applications.

If the ownership of these applications will not be a concern, I will not use these documents.

Subject: Petitions for retroactive foreign filing license
Date: Wed, 23 Jun 2004 16:18:24 -0400
X-MS-Has-Attach: yes
Thread-Topic: Petitions for retroactive foreign filing license
Thread-Index: AcRZXzyE2tZKas7ERrC1q9TDC9IGAw=
From: "Nils E. Pedersen" <npedersen@wenderoth.com>
To: "?????" <sasabe.kenichi@ebara.com>

Dear Mr. Sasabe,

It was nice to see you again this afternoon. I hope you have an uneventful trip back to Japan.

redacted

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, L.L.P.
Attorneys and Counselors at Law
Patents, Trademarks, and Copyrights
2033 K Street, N.W., Suite 800
Washington, DC 20006 U.S.A.

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For more information about Wenderoth, Lind & Ponack, L.L.P., please visit us on the web at www.wenderoth.com



20040738 Fukunaga Statement - revision 1.rtf



20040738 Fukunaga Statement - revision 2.rtf

From: "Sasabe" <2233754801@jcom.home.ne.jp>
To: <sasabe.kenichi@ebara.com>
Subject: Fw: Export License
Date: Sat, 26 Jun 2004 02:19:51 +0900
X-Mailer: Microsoft Outlook Express 5.50.4133.2400

----- Original Message -----

From: Sasabe
To: npedersen@wenderoth.com
Cc: akai.yuichi@ebara.com
Sent: Thursday, June 24, 2004 7:52 PM
Subject: Export License

Dear Mr. Pedersen

Thank you for the meeting on June 23.

redacted

Thank you for your cooperation.
Best regards
Kenichi Sasabe

Mr. Musaka, 10:15 04/06/29 +0900, #3 Workshop Meeting IP presentation

To: Mr. Musaka
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: #3 Workshop Meeting IP presentation
Cc: Mr. Y.Fukunaga
Bcc:
Attached: F:¥2004.6^{redac}_{-ted} ¥EBR^{redac}_{-ted} 04.06.21.ppt; F:¥2004.6^{redac}_{-ted} ¥Ebara Patent Applications June18,2004.xls; F:¥2004.6^{redac}_{-ted} ¥Translation of claims of #13 Facedown plating .doc;
F:¥2004.6^{redac}_{-ted} ¥Translation of claims of #16 Apparatus for plating substrate.doc;

六平様

先日は有難うございました。
会議で使用した資料をお送りいたします。

なお、荏原の米国出願を担当しているPedersen *redacted*

Mr. Musaka, 10:15 04/06/29 +0900,#3 Workshop Meeting IP presentation

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: #3 Workshop Meeting IP presentation

Cc: Mr. Y.Fukunaga

Bcc:

Attached: F:\2004.6 [redacted: the US company]\EBR_[redacted: the US company]
04.06.21.ppt; F:\2004.6 [redacted: the US company]\Ebara Patent Applications
June18,2004.xls; F:\2004.6 [redacted: the US company]\Translation of claims of #13
Facedown plating .doc; F:\2004.6 [redacted: the US company]\Translation of claims of #16
Apparatus for plating substrate.doc;

Dear Mr. Musaka

Thank you very much at the meeting.

I send the documents I used for presentation at the meeting.

I talked with an attorney, Mr. Pedersen, who is representing Ebara in US filing. Based his
advice *redacted*

Mr. Musaka, Mr. Y.Fukunaga, 12:40 04/06/30 +0900, #28 English translation

To: Mr. Musaka, Mr. Y.Fukunaga
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: #28 English translation
Cc: Mr. Shinozuka
Bcc:
Attached:

Dear Mr. Musaka

Please find attached English translation of #28 (2004-23256).
Claim 1 is modified from Japanese original claim to eliminate a limitation of peripheral seal.

Best regards,
Kenichi Sasabe

Mr. Musaka, 21:09 04/07/09 +0900, Ebara Applications #13 and #16

To: Mr. Musaka
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Ebara Applications #13 and #16
Cc: Mr. Y.Fukunaga
Bcc:
Attached:

Dear Mr. Musaka

At the workshop meeting on June 22, we asked ^{redac}_{-ted} to reconsider the ownership of applications #13 and #16.

Is there any response from ^{redac}_{-ted} on this matter?

Please confirm how they consider.

We are preparing for filing petition for foreign filing license also for these applications. If it is not necessary we will delete these numbers from the draft of the petition.

Matsuo, Kontechs, 13:15 04/07/13 +0900, Re: 翻訳データについて確認させていただきます

To: "Matsuo, Kontechs" <saiko.matsuo@kontechs.com>
From: 笹部憲一 <sasabe.kenichi@ebar.com>
Subject: Re: 翻訳データについて確認させていただきます
Cc:
Bcc:
Attached:

At 11:25 04/07/13 +0900, you wrote:
笹部様

コンテックスの松尾です。
今朝の打ち合わせの際にはありがとうございました。
原稿を拝見いたしました。そこで、いくつか確認させていただきます。

●電子データをご用意くださっているところではないかと思いますが、
電子データでいただけるものは、なるべく電子データでお願いいたします。
A、Vの2枚目、Zの2枚目も電子データがあれば大変助かります。
また、EおよびE2はウェブサイトの画面かと思いますが、
これもデータで落としたものをいただけると、大変助かります。

出来るだけ電子データをそろえてお送りします。

●社名にマーキングがないページがいくつかありました(V、V'、V''、Z)。
マーキングされているものとして、翻訳してよろしいですか？
チェックを十分出来ていないため、抜けがあると思います。気が付かれた場合には、
お願いします。

●S'''に人名(英語)があります。この方のお名前はどのように扱ったらよろしい
ですか？
Pedersenは残してください。

●Z'''にも人名(英語)がありますが、この方はETIの方なので、そのままでもよろし
いですね？

Dan O'connellは残してください。

以上です。どうぞよろしくお願い申し上げます。

*****平成16年7月1日より株式会社になりました*****

松尾彩子 (Matsuo Saiko)
株式会社コンテックス 翻訳サービス部
〒242-0024 神奈川県大和市福田3丁目1-21
電話/FAX: 0466-81-7759(荏原総研内線: 7706)
社内メール: ER気付外注室
e-mail: saiko.matsuo@kontechs.com

Matsuo, Kontechs, 13:15 04/07/13 +0900, Re: Questions about data for translation

To: "Matsuo, Kontechs" <saiko,matsuo@kontechs.com>

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Re: Questions about data for translation

Cc:

Bcc:

Attached:

At 11:25 04/-7/13 +0900, you write:

Dear Mr. Sasabe

This is Matsuo of Kontechs.

Thank you for the meeting this morning.

I looked through the document. I have some question.

- I suppose you are preparing electronic data of the document. Please supply electric data as much as possible.

If you can supply electronic data of A', second page of V', second page of Z'', it will be helpful for us.

I think document E and E2 are hard copies of website. If you can download it and supply it to us, it is also a great help for us.

I will try to supply electronic data as much as I can.

- On some pages (V, V', V'', Z) company names are not masked. May we treat these names as masked?

As I could not check enough, there may be some errors. If you find such a error, please ~~a~~ it is masked.

- There is a human name on S'''. How should we treat it?

Please leave "Pedersen" not masked.

- There is a human name on Z'''. This gentleman is from ETI. I will leave it not masked.

Please leave "Dan O'connel" not masked.

That is all my question.

I look for your response.

***** Kontechs became a joint-stock company from July 1, 2004 *****

Saiko Matsuo

Kontechs Corp. Translation Service Dept.

3-1-21 Fukuda, Yamato-shi, Kanagawa-ken 242-0024

Tel/Fax: 0466-81-7759 (Ebara Research 7706)

In-house mail: ER out-sourcing section

e-mail: saiko.matsuo@kontechs.com

篠塚担当部長殿, 20:16 04/07/16 +0900, Export License

To: 篠塚担当部長殿
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Export License
Cc: 赤井部長殿
Bcc:
Attached:

次の国内受付番号の発明届出書のコピーをお送りください。
同時に、出願時の事業部の部長が福永由紀夫さんか、三島さんのどちらかを教えてください。

出願番号	国内受付番号	事業部部長
2002-242726	K1020505	
2003-015235	K1020693	
2003-015236	K1030031	
2003-025159	K1030036	
2003-111327	K1030262	
2003-149827	K1030250	
2003-161236	K1030263	
2003-161237	K1030264	
2003-169791	K1030261	

Manager Shinozuka, 20:16 04/07/16 +0900, Export License

To: Manager Shinozuka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Export License

Cc: General Manager Akai

Bcc:

Attached:

Please send me copies of "Notification of Invention"s of the following domestic receipt numbers.

Application Number	Domestic Receipt Number	General Manager of Development
2002-242726	K1020505	
2003-015235	K1020693	
2003-015236	K1030031	
2003-025159	K1030036	
2003-111327	K1030262	
2003-149827	K1030250	
2003-161236	K1030263	
2003-161237	K1030264	
2003-169791	K1030261	

Musaka, Katsuyuki, 18:52 04/07/18 -0700, RE: Ebara Applications #13 and #16

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: '笹部憲一' <sasabe.kenichi@ebara.com>
Cc: fukunaga.yukio@ebara.com
Subject: RE: Ebara Applications #13 and #16
Date: Sun, 18 Jul 2004 18:52:59 -0700
X-Mailer: Internet Mail Service (5.5.2653.19)

Sasabe-san,

Sorry for the long delay in my response, but ^{redac}_{ted} san has not been back from her vacation yet and I do not expect any feedback from ^{redac}_{ted} on this matter until she comes back to work on next Thu, 7/22.

Can you hold the petition application till then?

Regards,
K.Musaka

-----Original Message-----

From: 笹部憲一 [mailto:sasabe.kenichi@ebara.com]
Sent: Friday, July 09, 2004 8:09 AM
To: kmusaka@ebaratech.com
Cc: fukunaga.yukio@ebara.com
Subject: Ebara Applications #13 and #16

Dear Mr. Musaka

At the workshop meeting on June 22, we asked ^{redac}_{ted} to reconsider the ownership of applications #13 and #16.

Is there any response from ^{redac}_{ted} on this matter?

Please confirm how they consider.

We are preparing for filing petition for foreign filing license also for these applications. If it is not necessary we will delete these numbers from the draft of the petition.

Subject: RE: Export License

Date: Tue, 20 Jul 2004 16:59:41 -0400

X-MS-Has-Attach: yes

Thread-Topic: Export License

Thread-Index: AcRo0q+o22ngJmXHQRuswmPN/FU93QFrh65A

From: "Nils E. Pedersen" <npedersen@wenderoth.com>

To: "?????" <sasabe.kenichi@ebara.com>

Cc: "Joseph Gorski" <jgorski@wenderoth.com>

Dear Mr. Sasabe,

Thank you for your email of last week. I am sorry that it took so long to get back to you.

redacted

redacted

Unfortunately I will be out of the office until August 2, 2004. I have discussed the present matter with Joe Gorski, so please send/copy any correspondence in the meantime to Joe as well, and he can assist you in my absence.

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, LLP.
Attorneys and Counselors at Law
Patents, Trademarks, and Copyrights
2033 K Street, N.W., Suite 800

Washington, DC 20006 U.S.A.

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For more information about Wenderoth, Lind & Ponack, LLP., please visit us on the web at www.wenderoth.com

-----Original Message-----

From: sasabe.kenichi@ebaracorp.com [<mailto:sasabe.kenichi@ebaracorp.com>]
Sent: Tuesday, July 13, 2004 8:12 AM
To: Nils E. Pedersen
Cc: akai.yuichi@ebaracorp.com
Subject: Export License

Dear Mr. Pedersen

redacted

redacted

redacted



C46411.DOC

コンテックス松尾様, 21:10 04/07/22 +0900, 納品受領の件

To: コンテックス松尾様
From: 笹部憲一 <sasabe.kenichi@ebar.com>
Subject: 納品受領の件
Cc:
Bcc:
Attached:

松尾様

翻訳を受領いたしました。
請求書をお送りください。
有難うございました。

Matsuo, Kontechs, 21:10 04/07/22+0900, Receiving the delivered translation

To: Ms. Matsuo, Kontechs

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Receiving the delivered translation

Cc:

Bcc:

Attached:

I have received the translation.

Please send the bill to me.

Thank you very much.

ד/י / ד/ח / ח א

Yukio Fukunaga, 19:56 04/07/06 +0900, Please inform us of the names of inventors of [redacted: the US company] (Urgent)

X-Sender: yf08594@pop.ebara.co.jp

X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J

Date: Tue, 06 Jul 2004 19:56:12 +0900

To: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>

From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Please inform us name of inventors of [redacted: the US company] (Urgent)

Cc: shinozuka.shuhei@ebara.com, sasabe.kenichi@ebara.com

Dear Mr. Musaka

For the US filing of the application S1 Pat. List #14(2003-195406), please promptly inform us of the names of the inventors of [redacted: the US company].

The priority limit is coming close, July 10.

Please e-mail to Mr. Shinozuka (IP department) and Mr. Sasabe by the early morning of July 7.

Is the full name of [redacted: the US company] as follows?

[redacted: the US company]

(As Mr. Sasabe is out of the office today, I report to you for him)

Y. Fukunaga

04.3.31 Y.Fukunaga, Mishima, Kurashina, Sasabe

#4: This invention was what Ebara presented to [redacted: the US company].

#14: Ebara reported [redacted: the US company] about pad in January 2003.

This invention belongs to Ebara.

#24: Tha same process with #14. Plating solution was also Ebara's solution.

There is a report on this development.

#12:

redacted

redacted

Support Document A7

nakashiba.masamichi@ebara.com, 赤井副部長殿, 09:05 04/03/24 +0900, Re: I社関連出願の出願

To: nakashiba.masamichi@ebara.com, 赤井副部長殿
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Re: ^{redac}_{ted} 関連出願の出願方法
Cc:
Bcc:
Attached:

中柴様、赤井様

まず教えていただきたいことがあります。

このプロジェクトのプレーヤーは3名いて ^{redac}_{ted}、EC、ETIです。
EBR側の登録メンバーは

Project Manager : N. Kimura (ETI/EC)
Technical Coordinator : K. Musaka (ETI)
ETI Tech Team : K. Namiki, R. Fang (ETI)
EC Project Team Leader : Y. Fukunaga (EC)
Patent/IP Leader : K. Sasabe (EC)
となっています。

^{redac}_{ted} にEBRの装置があり、その装置を使って ^{redac}_{ted} とETIと時によってECとが実験や解析、打合せなどを行っています。

こういう中で、出願案件が主としてECから出され、しかし ^{redac}_{ted}、ETIの寄与もあるとして考えた場合 ^{redac}_{ted} が主として発明した物ば ^{redac}_{ted} が中心となって出願するはずですが、ECがライセンスを取ればよいのでしょうか。それとも、ETI ^{redac}_{ted} もライセンスが必要なののでしょうか。

EC又はETIがライセンスを取ればよいのなら、以前から話を進めてもらっているSSDのライセンスの話に追加してしまえばよいように思います。
^{redac}_{ted} も含めて、プロジェクトとして何らかのまとまった申請が必要なら、I社に相談する必要があると思いますし、その場合には ^{redac}_{ted} からここを使いたいとの要求が出るかもしれません。

誰が、どのような範囲に関してライセンスを取る必要があるのかを、まず明確にしたいと思います。
誰に依頼するかはその上で決めればよいと思います。

At 10:48 04/03/23 +0900, you wrote:

笹部様
どう考えますか

Forwarded by masamichi nakashiba/e/ebara.jp on

2004/03/23
10:47

yuichi akai
2004/03/22 17:25

To: masamichi nakashiba/e/ebara.jp@ebara.jp
cc: sasabe.kenichi@ebara.com, fumio kondo/e/ebara.jp@ebara.jp, shuhei shinozuka/e/ebara.jp@ebara.jp, fukunaga.yukio@ebara.com, mishima.koji@ebara.com, sakaguchi.yoshiharu@ebara.com

Subject: Re: ^{redac}_{ted} 関連出願の出願方法 (Document link: masamichi nakashiba)

nakashiba.masamichi@ebara.com, Deputy General Manager Akai, 09:05 04/03/24, Re:
Filing procedure of applications related to [redacted: the US company]

To: nakashiba.masamichi@ebara.com, Deputy General Manager Akai

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Re: Filing procedure of applications related to [redacted: the US company]

Cc :

Bcc:

Attached:

Dear Mr. Nakashiba and Mr. Akai

First of all I have something that I would like you to teach me.

There are three players in this project, i.e [redacted: the US company], Ebara Corp. and ETI.

The registered members of Ebara side are:

Project Manager: N. Kimura (ETI/EC)

Technical Coordinator: K. Musaka (ETI)

ETI Tech Team: K. Namiki, R. Fang (ETI)

EC Project Team Leader: Y. Fukunaga (EC)

Patent/IP Leader: K. Sasabe (EC)

There is a processing tool made by Ebara in [redacted: the US company] facility. [redacted: the US company] and ETI, and in some cases Ebara Corp., are conducting experiments, analysis and meeting together.

In this situation if ideas for applications are made mainly by EC, and ETI and [redacted: the US company] also contributing the ideas (if [redacted: the US company] mainly made the idea, [redacted: the US company] will lead the filing), is filing the petition for export license only by EC enough, or ETI and [redacted: the US company] also should file the petition?

If export license only by EC or ETI is necessary, I think this filing can be integrated in the filing of the export license that IP department has been proceeding with SSD.

If a filing for a comprehensive export license for this project including [redacted: the US company] is necessary, [redacted: the US company] may propose a firm they want to use for this filing.

I would like to clarify who, and for what area, should file the export license.
Whom we ask to represent us can be decided later.

At 10:48 04/03/23 +0900, you write:

Dear Mr. Sasabe

How do you think?

----- Forwarded by masamichi nakashiba/e/ebara_jp on .

2004/03/23

10:47 -----

yuichi akai

2004/03/22 17:25

To: masamichi nakashiba/e/ebara_jp@ebara_jp

cc: sasabe.kenichi@ebara.com, fumio kondo/e/ebara_jp@ebara_jp, shuhei
shinozuka/e/ebara_jp@ebara_jp, fukunaga.yukio@ebara.com, mishima.koji@ebara.com,
sakaguchi.yoshiharu@ebara.com

Subject: Re: Filing procedure of applications related to [redacted: the US company]
(Document link: masamichi nakashiba)

赤井副部長殿, 11:18 04/03/25 +0900, Fwd: JDP Patent Applications

To: 赤井副部長殿
From: 笹部憲一 <sasabe.kenichi@ebaratech.com>
Subject: Fwd: JDP Patent Applications
Cc: 篠塚担当部長殿, 近藤副部長殿, 中柴部長殿, 福永(由)室長殿
Bcc:
Attached: D:\My Documents\redacted\用EBR特許リスト\Ebara Patent Applications Mar0904.xls;

赤井様

先週六平さん、福永(由)さんとredacted関係の出願について打合せを行い、その結果に基づいて六平さんがredactedのredactedさんと打ち合わせた結果だそうです。輸出ライセンスを取って日本出願を生かしたいもの、USで出願したので日本出願(2004.1頃)を取り下げたいものなどがあります。対応について検討して回答する必要があります。めっきが中心ですので現在は近藤さんの範囲ですが、フライングで赤井さんに協力をお願いします。赤井さんが藤沢に来られる時に、福永さんを含めて相談したいと思います。Item番号の分かるリストは篠塚さんが持っていると思いますが、念のため貼付しておきます。(ブルーの部分は2004.3.9の変更分です。)

redactedの件は今後の出願に関しても相談しておいた方がよいと思います。

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebaratech.com>, "Fukunaga, Yukio (E-mail)" <fukunaga.yukio@ebaratech.com>
Cc: "Nambu, Isao (E-mail)" <isao.nambu@nifty.ne.jp>, "Kimura, Norio (E-mail)" <kimura.norio@ebaratech.com>, "Hodai, Masao (E-mail)" <hodai.masao@ebaratech.com>, "Mishima, Koji (E-mail)" <mishima.koji@ebaratech.com>
Subject: JDP Patent Applications
Date: Wed, 24 Mar 2004 17:29:06 -0800
Importance: high
X-Mailer: Internet Mail Service (5.5.2653.19)

Sasabe-san, Fukunaga-san,

I had a meeting with redacted-san on last Monday regarding patent applications through the JDP.

Followings basically explain how she wants us to handle this matter.

Item#2(USP) and Item#22(JP) - Add "redacted" and "redacted" as co-inventor. (So, EC/redacted have to apply for export license.)

Item#4(JP), #10(JP), #12(JP), #14(JP), #24(JP) - redacted-san believes redacted,s posses rights as co-inventors. However, she generously understood complexity of the correction process, and will discuss with patent attorney to decide which of the following 3 options they want to pursue.

Opt.1 - Withdraw. Then, re-submit as redacted/Ebara co-invention.

Opt.2 - Add redacted,s as co-applicants.

Opt.3 - Add redacted,s as co-inventors. (Apply for export license)

Item#11(JP) - redacted-san does not believe redacted owns any rights as co-inventor. So, it's OK as it is now, Ebara's own invention.

Item#26(JP), #28(JP), #29(JP) – Abandon all JPs since Philippe already submitted disclosure covers #26 and #28, and so as #29 by ^{redac}_{ted}. So, those are being filed as USP under ^{redac}_{ted} /Ebara co-inventions.

^{redacted}'s disclosure which hard copy we reviewed in last week will be also filed as USP under ^{redac}_{ted} /Ebara co-invention.

Please re-discuss with folks in Japan if those are acceptable, and let me know any issues/concerns.

Thank you for your understanding and strong support on this matter.

Best Regards,
K.Musaka

Deputy General Manager Akai, 11:18 04/03/25 +0900, Fwd: JDP Patent Applications

To: Deputy General Manager Akai

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: JDP Patent Applications

Cc: Manager Shinozuka, Deputy General Manager Kondo, General Manager Nakashiba,
General Manager Y. Fukunaga

Bcc:

Attached: D:\My Documents\Ebara patent list for [redacted: the US company]\Ebara
Patent Applications Mar0904.xls;

Dear Mr. Akai

I discussed with Messrs. Musaka and Fukunaga last week about applications related to [redacted: the US company]. This is a result of a talk between Mr. Musaka and [redacted: personal name] of [redacted: the US company].

There were some applications for which we will have an export license and use the Japanese applications as they are, some applications for which the Japanese applications (filed around January, 2004) shall be dismissed as US applications containing similar inventions have been filed in US, and so on.

We must consider how to treat these applications and reply to him.

As plating is the main technology, which is covered by Mr. Kondo, I would like to ask Mr. Akai's cooperation though you are not in charge of this technology yet. When Mr. Akai comes to Fujisawa, I would like to have a discussion including Mr. Fukunaga.

Mr. Shinozuka should have the list of the applications by which you know the item numbers. I attach the list to this mail just in case. (portions colored blue were modified on March 9, 2004.)

We had better discuss also about future filing related to [redacted: the US company].

[Below to the end is originally English text.]

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: "redacted (E-mail)" <redacted>
Cc: "Fukunaga, Yukio (E-mail)" <fukunaga.yukio@ebara.com>, "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>
Subject: RE: EBARA Patent Application Translations
Date: Fri, 12 Mar 2004 09:05:57 -0800
X-Mailer: Internet Mail Service (5.5.2653.19)

redac
-ted -san,

Please find attached translation of Ebara's Japanese patent application item#23.

<<2003-402006(#23).doc>>

I believe that's the last item we agreed to prepare the translations, and have not been submitted.

Please review and advise how you want us to handle the matter.

Best Regards,
K.Musaka

> -----Original Message-----

> From: Musaka, Katsuyuki
> Sent: Tuesday, March 09, 2004 9:53 AM
> To: redacted (E-mail)
> Cc: Fukunaga, Yukio (E-mail); Sasabe Kenichi (E-mail)
> Subject: EBARA Patent Application Translations

> redac
> -ted -san,

> Thank you for your time and valuable inputs in our meeting yesterday
> although your busy schedule.

> Please find attached summary of Ebara's patent application status. There
> are some corrections in the one I handed to you a hard copy yesterday
> (highlighted in red).

> << File: EBARA Applications_030904.xls >>

> Attached below are translations of Ebara's Japanese patent applications
> which hard copies I handed to you today.

> << File: 2003-015236(#4).doc >> << File: 2003-149827(#10).doc >> <<
> File: 2003-161236(#11).doc >> << File: 2003-161237(#12).doc >> << File:
> 2003-195406(#14).doc >> << File: 2003-431211(#24).doc >> << File:
> 2004-022178(#26).doc >> << File: 2004-023256(#28).doc >> << File:
> K1040028(#29).doc >>

> Also, attached below is the Ebara's US patent application. As I explained
> to you yesterday, the #2 which was filed in Japan on 12/2/02 was
> abandoned, then re-filed as #22 in Japan on 11/28/03, within 1 year from
> the original(#2) filing date. The US patent applications for #2 as well as
> #22 were also filed about the same time, 12/1/03, to obtain the priority
> of #2, within 1 year from its original(#2) filing date in Japan.

>
> << File: GEB1998US(#22).pdf >> << File: GEB1998US_Image(#22).tif >>
> Please review and advise us which you want us to amend for co-invention
> with redacted
>
> Best Regards,
> K.Musaka
>
> P.S. I'm still waiting for a translation of #23. I'll e-mail it to you as
> soon as I receive it.



2003-402006(#23).doc

発明等届出書 (1/2)

1.特許

2.意匠

3.その他) ※1

(補足書 1.有 2.無)

社外秘

※1 原則として特許出願とする。但し、実用新案で出願したい場合は、「3.その他」に○を付し知的財産部と相談する。

Post (716)

Post (708)

Post (52) 知的財産部

知財部 受付日/No.

2003.01.21/K1030031

2/2の依頼元上長記入欄の捺印欄もお忘れなく御捺印下さい。

依頼日(西暦)

'03年 1月 10日

依頼元 Doc.No.716-1

太枠内をご記入下さい。

依頼元部門	(部門コード) 部門名 書類送付先 担当者	(V350) 第一開発セク、第二開発室、開発一部 氏名: 倉科 敬一 個人コード: 21155 (Post:716 Tel:8556)	区分(本部)	1. 管理 2. 情報・通信・制御 3. 風水力 4. インジニアリッ 5. 精密・電子	関係会社	6. 荏原総研 7. 荏原ボイラ 8. 荏原工業洗浄
-------	--------------------------------	--	--------	--	------	----------------------------------

発明等の名称	基板のめっき装置及びめっき方法		
キーワード	めっき、平坦性、均一性、埋設性		
関連する製品又は技術	DMP、含浸めっき、パワめっき		
製品の性格	1. 重点取扱機種である	2. 重点取扱機種でない	研番成果 研 No.L-02D547

※2 「社内発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)の発明者等のみ記入する。

下欄はEBRの発明者等だけに適用する。

上記の職務発明※3等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社(株式会社荏原製作所)に譲渡したことを確認します。

下欄はER、EB、EICCの発明者等だけに適用する。

上記の職務発明※3等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社()に譲渡したことを確認します。

社内発明者(計)	所属部門名	Post Tel	個人コード	氏名	権利 持分	認印	米国※4 在住
1	第一開発セク 第二開発室	716	2 1 1 5 5	倉科 敬一	60%	倉科	
2	第一開発セク 第一開発室	715	0 8 3 2 0	並木 計介	20%	並木	
3	第一開発セク 第二開発室	716	2 0 2 4 8	中田 勉	10%	中田	
4	同上	716	1 3 0 1 0	三島 浩二	10%	三島	
5					%		

※3 届出発明が職務発明でないと考えた場合は認印欄に押印せずに送付する。

※4 米国に在住している場合はレ印を付ける。

出願形式 1. EBR 単独 2. EBR と EBR 以外の者との共同 3. EBR 以外の者の単独 4. その他

出願手続会社	1. EBR 2. EBR 以外の者 ()		
費用負担	1. EBR 負担 2. 均等負担 3. その他		
EBR 以外の出願人名義※5 (計 名)	会社名又は氏名	連絡先 (住所、Tel、知財部門担当者名等)	権利持分 費用負担
			% %
			% %

※5 荏原ボイラ(EB)、荏原工業洗浄(EICC)は上記「EBR 以外の出願人名義」の欄に記入する。荏原総合研究所(ER)は記入要領を参照のこと。

社外発明者(計) 名	会社名	氏名	住所	権利持分
				%
				%
				%

※6 「社外発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)以外の発明者等を記入する。

出願 緩急	1. 普通 (2) 至急 (1 月 21 日まで)	理由: a. 社外発表 (右欄記入) b. 当社先願公開期限 c. 国内優先権主張期限	発表日: '03年 1 月 24 日 発表先: 米国 協業社
----------	-------------------------------	---	-----------------------------------

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

発明等届出書 (2/2)

社外秘

⑨

契約関係※7	共同研究等契約書	1. 有 (相手:) ② 無
	共同出願契約書	1. 要 (作成担当: a. 当社 b. 相手先 ()) ② 不要

※7 共同出願、他社名義の出願とする根拠として契約書がある場合、契約書の写しを添付する。

⑩

調査実施状況 ① 調査済み (右欄記入) 2. 未調査	関連出願・公知例 出願内容に最も近い 公知例を2部添付する。	当社のもの	① 有 (K1020693) 2. 無
		他社のもの	① 有 (特開2000-232078) 2. 無

⑪

発明の性質 評価項目	発明の性質によりA, B, Cのうち一列を選択 (記号を○) して評価		
	A. 現在製品・技術の発明	B. 新事業製品・技術の発明	C. 先行アイデア発明
① 先行技術に対する技術的優位性	1. 同等 2. 若干優位 3. 相当優位 ④ 断然優位		
② 他社侵害確認の難易度※8	1. 極めて困難 2. かなり困難 3. やや困難 ④ 容易		
③ 課題・手段の重要性	1. 不明 2. 普通 3. 重要 ④ 最重要		
④ 他社における本発明の回避困難度	1. 容易 2. やや困難 ③ かなり困難 4. 不可		
⑤ 実施関係	1. 不明 2. 国内のみ小規模 3. 国内のみ大規模 ④ 国内と外国で実施	1. 未定 2. 試作予定 3. 試作中又は済 4. 採用決定	
⑥ 技術的実現性	—	—	1. 不明 2. 困難 3. 容易 4. 検討済
⑦ 独創性	—	—	1. 不明 2. 小 3. 中 4. 大
⑧ 群評価※9	1. 普通 (1倍) 2. 重要 (2倍) ③ 最重要 (3倍)		

※8 他社が本発明等を侵害しているか否かの判別の程度のこと。

※9 本発明及び他の関連する発明で形成する発明群における、本発明の他の発明に対する相対的な重要度の評価。

⑫

評価計算式	依頼元評価ランク※10	⑬ 出願要否
A列, B列発明 (①+②+③+④+⑤)×⑧=57	45以上 →S 30~44 →A 20~29 →B 19以下 →C	① 要 2. 公開技報でよい 3. 不要 (理由:)
C列発明 (①+②+③+⑥+⑦)×⑧=		外国出願 ① 要 (国名: 米国) 2. 不要 3. 未定

※10 該当の評価ランクに○を付ける。

⑭

特記事項	103.1.10 小野寺理士と打合せ済み。至急お願いしたいです。
------	----------------------------------

⑮

発明の 評価	知財部評価点	知財部評価ランク※11	総合 評価 ※12	S: 最重要 A: 重要 B: 通常 C: 公開技報 D: 見合せ E: 会社都合
	①特許性: 22	(①+②+③+④)×⑤=16		
	②権利の広さ: 2	36以上 →S		
	③他社侵害確認の難易度: 2	24~35 →A		
	④本発明の回避困難度: 2	16~23 →B		
	⑤群評価: 2	15以下 →C		

※11 評価点を記入し、該当の評価ランクに○を付ける。 ※12 該当の評価ランクに○を付ける。

⑯

出願形態	1. 通常出願 2. 国内優先権主張 3. 分割 4. 変更	基礎出願番号:	特許事務所
出願賞	1. 支給する 2. 支給しない (理由:)		
備考			

Confidential

1


Date of receipt
by IP Dept./No.
2003.01.21/K10
30031

Sakaguchi
03.1.15

2

Requesting dept.	(Dept. code) Dept. name	(V350) Process Development Office 2 Development Center 1	Category (Group)	1. Corporate 2. Strategic Information and Communication Systems 3. Fluid Machinery & Systems 4. Engineering 5. Precision Machinery	(Affiliate)	6. Ebara Research 7. Ebara Boiler Co.,Ltd. 8. Ebara Industrial Cleaning Co.,Ltd.
	Person responsible for the documents	Name: Keiichi Kurashina Employee No.: 21155 (Post: 716 Tel: 8556)				

3

Title of the invention	Plating Method and apparatus of substrate			pp,01	
Keyword	Plating, planarity, uniformity, filling ability				
Related product or technology	DMP, Impregnation plating; Bump plating				
Character of the product	<input checked="" type="radio"/> 1. Sales-focused <input type="radio"/> 2. Not sales-focused	Result of:	Job No. L-02D547		

4

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).

The column below is applicable only to inventors in EBR.	In-house inventor (Total: inventor(s)) ²		Dept.	Post Tel	Employee No. (five digits)	Name	Share of the rights	Seal for confirming the transfer	Living in U.S. ³
Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company (Ebara Corporation) upon invention.		1	Process Development Office 2 Development Center 1	716	21155	Keiichi Kurashina	60%	Kurashina	
The column below is applicable only to inventors in ER, EB, EICC, and ERS.		2	Process Development Office 1 Development Center 1	715	08320	Keisuke Namiki	20%	Namiki	
Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company () upon invention.		3	Process Development Office 2 Development Center 1	716	20248	Tsutomu Nakada	10%	Nakada	
		4	Same as above	716	13010	Koji Mlshima	10%	Mlshima	
		5							

³ Put a checkmark if the inventor is living in U.S.

5

Application type	1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR 3. Sole application by a company other than EBR 4. Other
------------------	--

6

*4 The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	(1) EBR 2. Other than EBR ()			
Expense is:	1. Paid by EBR 2. Equally shared 3. Paid otherwise			
Applicant other than EBR ⁴ (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
			%	%

7

*5 The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor (Total: inventor(s)) ⁵	Company	Name	Address	Share of the interest
				%
				%

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

8

Urgency of Application filing	1. Normal 2. High (by January 21.) Reason: a. External release (Fill the right column.) b. Deadline for publication of our prior application c. Deadline for claiming domestic priority Collaboration contract	Released on: 2003/1/24 Released to: Cooperative company in US
----------------------------------	---	--

Notification of Invention (2/2)

Confidential

9

Related contract ^{*6}	Written contract for joint research	1. Available (partner:) 2. N/A (current)
	Written contract for joint filing of patent applications	1. Required (Prepared by: a. Us b. Partner ()) 2. Not required

^{*6} When there is a written contract that justifies the joint filing or filing under other name, attach a copy of it to this form.

10

Prior-art search	Related application and prior art: Attach two items of prior art related to the application.	Ours	1. Available (K1020693) 2. N/A
1. Done (Fill the right column.) 2. Not done		Others'	1. Available (Publication No. 2000-232078) 2. N/A

11

Evaluation item	Nature of invention		
	Choose A, B, or C (enclose with a circle), considering the nature of the invention.		
	A. Invention for current products/technologies	B. Invention for new products/technologies	C. Invention of new ideas
(1) Technical superiority over prior art	1. None 2. A little 3. Considerable 4. Very large		
(2) Difficulty to find infringement ^{*8}	1. Very difficult 2. Considerably difficult 3. A little difficult 4. Easy		
(3) Severity of challenge/means	1. Unknown 2. Normal 3. High 4. Very high		
(4) Difficulty of design around	1. Easy 2. A little difficult 3. Considerably difficult 4. Impossible		-
(5) Applicability to production	1. Unknown 2. Domestic small scale 3. Domestic large scale 4. Domestic and abroad	1. Not decided 2. Planned to trial prod. 3. Under or finished trial production 4. Decided to adopt	-
(6) Technical realizability			1. Unknown 2. Difficult 3. Easy 4. Study finished
(7) Originality			1. Unknown 2. Low 3. Medium 4. High
(8) Group judgement ^{*9}	1. Normal (single) 2. Important (double) 3. Most important (triple)		

^{*8} Difficulty to judge if other company infringes this invention

^{*9} Judge of importance of this invention to other inventions in an invention group comprising this invention and other related inventions

12

Calculation for rating	Rating by requesting department
For inventions of A or B ((1)+(2)+(3)+(4)+(5))×(8) = 57	45 or higher → S 30-44 → A 20-29 → B Less than 19 → C
For inventions of C ((1)+(2)+(3)+(6)+(7))×(8) =	

13

Filing of the patent application is:	1. Required 2. Not required; it should be published on Journal of Technical Disclosure. 3. Not required (reason:)
Foreign filing is:	1. Required (country name:) 2. Not required 3. Not decided

14

Special note	2003.1.10 Discussed with patent agent Ono. Please proceed urgent.
--------------	---

Boss's seal of approval:
Mishima

15

Evaluation	Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept ^{*11}	Overall evaluation ^{*12}
	(1) Patentability: 2 (2) Scope of rights: 2 (3) Difficulty to find infringement: 2 (4) Difficulty of design around: 2 (5) Group judgement: 2	$((1)+(2)+(3)+(4)) \times (5) = 16$ 36 or higher → S 24-35 → A 16-23 → B Less than 15 → C	S: Most important A: Important B: Normal C: Journal of Technical Disclosure. D: No filing E: By company circumstance

Evaluation
Approver
Seal: Kubo
03.1.28

Evaluation
Approver
Seal:
Shinozuka

^{*11} Enter the evaluation values and circle the appropriate rank. ^{*12} Place a circle on the appropriate item of the evaluation level.

16

Application category	<input checked="" type="radio"/> 1. Regular application <input type="radio"/> 2. Domestic priority <input type="radio"/> 3. Division <input type="radio"/> 4. Change	Original application No.:	Patent firm
			Ono
Award for filing the patent application		1. Will be offered 2. N/A (reason:)	
Remarks			

Should you have any comment on the evaluation, contact us within two weeks.

① 発明等届出書 (1/2)

①.特許

2.意匠

3.その他 ※1

(補足書 1.有・2.無)

社外秘

Post (75)

Post (708)

Post (708)

K1030250

知財部 受付日/No.

2003.04.19/K1030250

2/2の依頼元上長記入欄の捺印欄も忘れなく印捺下さい。

依頼日(西暦)

2003年 2月 19日

依頼元 Doc.No.715-B32191

② 太枠内をご記入下さい。

依頼元部門	(部門コード) 部門名	(V512.) 技術統括 第一開発センター 第一 プロセス開発室	区分 (本部)	1. 管理 2. 情報・通信 3. 営業 4. 環境エンジニアリング 5. 風水力 6. 新エネルギー 7. 精密・電子	(関係会社)	8. 荏原総合研究所 9. 荏原ボイラ 10. 荏原工業洗浄 11. 荏原冷熱システム 12. その他 ()
書類送付先 担当者	氏名: 並木 計介 個人コード: 08320 (Post: 715 Tel: 9244)					

③


発明等の名称	パルスめっき機構		
キーワード	異方性、多孔質パッド、パルス電圧印加		
関連する製品又は技術	含浸めっき装置		
製品の性格	① 重点拡販機種である	2. 重点拡販機種でない	研番成果 研 No. L-02D54709.

④

職務発明について	① 職務発明である 2. 職務発明ではないが、職務発明と同等の条件で会社に譲渡する 3. 職務発明ではなく、本発明等に関する一切の権利につき、その譲渡について会社と交渉する →右欄に捺印して知的財産部に送付してください。下の社内発明者記入欄の ところの譲渡確認印欄には捺印しないで下さい。	一下の社内発明者記入欄のところの 譲渡確認印欄に捺印してください (捺印欄)
----------	--	--

※2 「社内発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)、荏原冷熱システム(ERS)の発明者等のみ記入する。

⑤

下欄はEBRの発明者等だけに適用する。 上記の職務発明等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社(株式会社荏原製作所)に譲渡したことを確認します。	社内発明者(計) 名 ※2	所属部門名	Post Tel	個人コード (5桁)	氏名	権利 持分	譲渡 確認印	米国※3 在住
1 第一開発センター 第二プロセス開発室		716 9427	13010	三島 浩二	10 %			
2 第一開発センター 第二プロセス開発室		716 8566	20248	中田 勉	10 %			
3 第一開発センター 第二プロセス開発室		716 8556	21155	倉科 敬一	40 %			
4 第一開発センター 第一プロセス開発室		715 9244	08320	並木 計介	40 %			
5					%			
下欄はER、EB、EICC、ERSの発明者等だけに適用する。 上記の職務発明等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社()に譲渡したことを確認します。								

※3 米国に在住している場合はレ印を付ける。

⑥

出願形式	①. EBR 単独	2. EBR と EBR 以外の者との共同	3. EBR 以外の者の単独	4. その他
------	-----------	-----------------------	----------------	--------

※4 荏原ボイラ(EB)、荏原工業洗浄(EICC)、荏原冷熱システム(ERS)は下記「EBR 以外の出願人名義」の欄に記入する。荏原総合研究所(ER)は記入要領を参照のこと。

⑦

出願手続会社	① EBR				2. EBR 以外の者 ()					
費用負担	① EBR 負担				2. 均等負担				3. その他	
EBR 以外の 出願人名義※4 (計 名)	会社名又は氏名	連絡先(住所、Tel、知財部門担当者名等)			権利持分	費用負担				
					%	%				
					%	%				

※5 「社外発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)、荏原冷熱システム(ERS)以外の発明者等を記入する。

⑧

社外 発明者 (計 名) ※5	会社名	氏名	住所	権利持分
				%
				%
				%

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

発明等届出書 (2/2)

社外秘

出願 緩急	① 普通 ② 至急 (3月 中 日まで)	理由: a. 社外発表 (右欄記入) b. 当社先願公開期限 c. 国内優先権主張期限	発表日: 年 月 日 発表先:
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契約関係※6	共同研究等契約書	1. 有 (相手:) 2. 無
	共同出願契約書	1. 要 (作成担当: a. 当社 b. 相手先 ()) ② 不要

※6 共同出願、他社名義の出願とする根拠として契約書がある場合、契約書の写しを添付する。

調査実施状況	関連出願・公知例 出願内容に近い公知例 を2部添付する。	当社のもの	1. 有 () 2. 無
		他社のもの	1. 有 () 2. 無

評価項目	発明の性質によりA, B, Cのうち一列を選択 (記号を○) して評価		
	A. 現在製品・技術の発明	B. 新事業製品・技術の発明	C. 先行アイデア発明
① 先行技術に対する技術的優位性	1. 同等	2. 若干優位	3. 相当優位 ④ 断然優位
② 課題・手段の重要性	1. 不明	2. 普通	3. 重要 ④ 最重要
③ 独創性			1. 不明 2. 小 3. 中 ④ 大
④ 本発明が対象とする製品の開発計画	1. 開発計画はない 2. 開発計画の終了段階である ③ 開発計画の中間段階である 4. 開発計画の初期段階である		-
⑤ 本発明が製品に占める重要度	1. 小さい	2. やや小さい	3. やや大きい ④ 大きい
⑥ 依頼元総合評価	1. 軽度 (1倍)	2. 通常 (2倍)	3. 重要 (3倍) ④ 最重要 (4倍)

評価	A列の発明	(①+②+④+⑤)×⑥= 60
計算	B列の発明	15 × 4 = 60
	C列の発明	(①+②+③+⑤)×⑥=

出願要否	① 要 2. 公開技報でよい 3. 不要 (理由:)
外国出願	① 要 (国名: 米国) 2. 不要 3. 未定

特記事項	小野先生にみらいいたはる...
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上長印

評価	① 特許性	1. なし ② 小 3. 中 4. 大
	② 権利の広さ	1. 狭い ② やや狭い 3. やや広い 4. 広い
	③ 本発明の回避困難度	1. 容易 ② やや困難 3. かなり困難 4. 不可
	④ 特許的総合評価	1. 軽度 (1倍) ② 通常 (2倍) 3. 重要 (3倍) 4. 最重要 (4倍)

知財部評価点: (①+②+③)×④= 12
依頼元評価点 + 知財部評価点 = 72

※7 評価点を記入する。

総合評価※8	84以上 → S: 重点 64~83 → A: 重要 28~63 → B: 通常 27以下 → C: 出願せず
--------	--

※8 該当の評価ランクに○を付ける。



出願形態	1. 通常出願 2. 国内優先権主張 3. 分割 4. 変更	基礎出願番号:	特許事務所
出願賞	1. 支給する 2. 支給しない (理由:)		
備考			

評価等に関するご意見は2週間以内にご連絡下さい

(1) Patent 2. Design 3. Other *

(Supplement: 1. Attached 2. N/A)

Confidential

Post 1718

Post () Post (52) Intellectual Property Dept.

This form filled by: Namiki 03.2.19	Manager: Nakada 03.2.19	Patent liaison: Nagai	General manager: Mishima	Related dept.: Sasabe	General manager: Nakashiba 03.3.4	Manager: Kondo	Responsible person: Shinozuka 03.4.10	Date of receipt by IP Dept./No. 2003.04.10/K10 30250
---	-------------------------------	--------------------------	-----------------------------	--------------------------	---	-------------------	---	--

A Venn diagram with two overlapping circles. The left circle is labeled 'Sakaguchi' and '03.2.28'. The right circle is labeled 'Sakaguchi' and '03.4.08'. The overlapping region is shaded gray.

Date of request (Christian year): YYYY/MM/DD
Requesting dept. Doc.No.: 718-E2N20-1

2

Requesting dept.	(Dept. code) Dept. name	(V512) Process Development Office ,Development Center 1	Category (Group)	1. Corporate 2. Strategic Information and Communication Systems 3. Sales 4. Environmental Engineering 5. Fluid Machinery & Systems 6. New and Renewable Energy 7. Precision Machinery	(Affiliate)	8. Ebara Research
	Person responsible for the documents	Name: Keisuke Namiki Employee No.: 08320 (Post: 715 Tel: 9244)				9. Ebara Boiler Co.,Ltd. 10. Ebara Industrial Cleaning Co.,Ltd. 11. Ebara Refrigeration Equipment & Systems Co., Ltd. 12. Other ()

3

Title of the invention	Pulse Plating System			pp,01	limura
Keyword	Unisotropic, porous pad, pulse voltage				03.4.10
Related product or technology	Impregnation plating apparatus				
Character of the product	<input type="radio"/> 1. Sales-focused <input type="radio"/> 2. Not sales-focused		Result of:	Job No. L-02D54709	

4

About service invention	<p>① 1. Yes</p> <p>2. No; however, I transfer the invention to the Company under terms and conditions equivalent to those for service inventions.</p>	<p>-> Affix the seal in the appropriate space of the "In-house inventor" column below.</p>
	<p>3. No; I negotiate with the Company about terms and conditions of the transfer of any and all rights to the invention.</p> <p>-> Affix the seal in the right column and send this form to Intellectual Property Dept. Do not affix the seal in the "In-house inventor" column below.</p>	<p>(Affix the seal here.)</p>

יום ויגבולתי פנומחא ווו חלב החתולות וסליל קרית

5

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).

<p>The column below is applicable only to inventors in EBR.</p> <p>Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company (Ebara Corporation) upon invention.</p> <p>The column below is applicable only to inventors in ER, EB, EICC, and ERS.</p> <p>Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company () upon invention.</p>	In-house inventor (Total: inventor(s)) ²		Dept.	Post Tel	Employee No. (five digits)	Name	Share of the rights	Seal for confirming the transfer	Living in U.S. ³
		1	Process Development Office 2 Development Center 1	716 9427	13010	Koji Mishima	10%	Mishima	
		2	Process Development Office 2 Development Center 1	716 8566	20248	Tsutomu Nakada	10%	Nakada	
		3	Process Development Office 2 Development Center 1	716 8556	21155	Keiichi Kurashina	40%	Kurashina	
		4	Process Development Office 1 Development Center 1	715 9244	08320	Keisuke Namiki	40%	Namiki	
		5							

³ Put a checkmark if the inventor is living in U.S.

6

Application type	1. Sole application by EBR 2. Joint application by EBR and a company other than EBR 3. Sole application by a company other than EBR 4. Other
------------------	---

7

The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	(1. EBR 2. Other than EBR ())			
Expense is:	1. Paid by EBR 2. Equally shared 3. Paid otherwise			
Applicant other than EBR ⁴ (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
			%	%

8

The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor (Total: inventor(s)) ⁵	Company	Name	Address	Share of the interest
				%
				%
				%

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

Confidential

Notification of Invention (2/2)

9

Urgency of application filing	1. Normal 2. High (by Middle of March) Reason: a. External release (Fill the right column.) b. Deadline for publication of our prior application c. Deadline for claiming domestic priority Collaboration contract	Released on: YYYY/MM/DD Released to:
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10

Related contract ⁶	Written contract for joint research	1. Available (partner:) 2. N/A (current)
	Written contract for joint filing of patent applications	1. Required (Prepared by: a. Us b. Partner ()) 2. Not required

⁶ When there is a written contract that justifies the joint filing or filing under other name, attach a copy of it to this form.

11

Prior-art search	Related application and prior art: Attach two items of prior art related to the application.	Ours	1. Available () 2. N/A
(1) Done (Fill the right column.) 2. Not done		Others'	1. Available () 2. N/A

12

Nature of invention	Choose A, B, or C (enclose with a circle), considering the nature of the invention.		
Evaluation item	A. Invention for current products/technologies	B. Invention for new products/technologies	C. Invention of new ideas
(1) Technical superiority over prior art	1. None 2. A little 3. Considerable 4. Very large		
(2) Severity of challenge/means	1. Unknown 2. Normal 3. High 4. Very high		
(3) Originality	1. Unknown 2. Low 3. Medium 4. High		
(4) Development project for products based on the invention	1. N/A 2. In the final stage 3. In the intermediate stage 4. In the early stage		
(5) Importance of the invention to the products	1. Low 2. Rather low 3. Considerably high 4. High		
(6) Overall judgment by the requesting side	1. Less important (single) 2. Moderate (double) 3. Important (triple) 4. Significant (quadruple)		

13

Calculation for rating of the evaluation	For inventions of A or B	$((1)+(2)+(4)+(5)) \times (6) = 60$	Filing of the patent application is:	1. Required 2. Not required; it should be published on Journal of Technical Disclosure. 3. Not required (reason:)
	For inventions of C	$((1)+(2)+(3)+(5)) \times (6) =$	Foreign filing of the patent application is:	1. Required (country name: U.S) 2. Not required 3. Not determined

14

Special note	Please ask Patent agent Ono.	Boss's seal of approval: Mishima
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15

Evaluation	(1) Patentability	1. None 2. Low 3. Medium 4. High
	(2) Scope of rights	1. Narrow 2. Rather narrow 3. Considerably wide 4. Wide
	(3) Indispensability of the invention to the products	1. Low 2. Rather low 3. Considerably high 4. Indispensable
	(4) Overall judgment on patenting the invention	1. Less important (single) 2. Normal (double) 3. Important (triple) 4. Significant (quadruple)

16

Evaluation by Intellectual Property Dept.: $((1)+(2)+(3)) \times (4) = 72$
Total of the evaluation values by the requesting side and Intellectual Property Dept. $72 = 72$

Overall evaluation *8	84 or more -> S: Significant 64 to 83 -> A: Important 28 to 63 -> B: Normal 27 or lower -> C: Not apply
--------------------------	--

Evaluation Approver Seal: Kondo	Evaluation Approver Seal: Shinozua 03.4.10
---------------------------------------	---

*7 Enter the evaluation values into the formula.

*8 Place a circle on the appropriate item of the evaluation level.

17

Application category	1. Regular application 2. Domestic priority 3. Division 4. Change	Original application No.:	Patent firm
Award for filing the patent application		1. Will be offered 2. N/A (reason:)	
Remarks			

Should you have any comment on the evaluation, contact us within two weeks.

発明等届出書 (1/2)

(1.特許)

2.意匠

3.その他) ※1

(補足書 1.有・2.無)

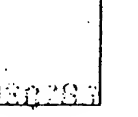
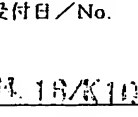
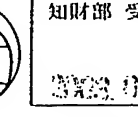
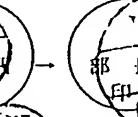
社外秘

①

Post (716)

Post (709)

Post (52) 知財財産部



2/2の依頼元上長記入欄の捺印欄もお忘れなく御捺印下さい。

K030263

知財部 受付日/No.

2003.04.16/K1030263

②

太枠内をご記入下さい。

依頼日(西暦)

'03年 4月 1日

依頼元 Doc.No.716-

依頼元部門	(部門コード) 部門名 書類送付先 担当者	(V350) 第一開発セク. 第二開発室 開発一部 氏名: 倉科 敬一 個人コード: 21155 (Post:716 Tel:8556)	区分 本部	1. 管理 2. 情報・通信・制御 3. 風水力 4. エンジニアリング 5. 精密・電子	(関係会社)	6. 荏原総研 7. 荏原ボイラ 8. 荏原工業洗浄
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③

発明等の名称	基板のめっき装置及びめっき方法		
キーワード	めっき、平坦性、均一性、埋設性。		
関連する製品又は技術	DMP、含浸めっき、パッドめっき		
製品の性格	1. 重点取扱機種である	2. 重点取扱機種でない	研番成果 研 No. L-02D547.

④

※2「社内発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)の発明者等のみ記入する。

下欄はEBRの発明者等だけに適用する。

上記の職務発明※3等に関し、私(発明者・考案者・創作)は発明等の時点において日本及び外国における一切の権利を会社(株式会社荏原製作所)に譲渡したことを確認します。

下欄はER、EICCの発明者等だけに適用する。

上記の職務発明※3等に関し、私(発明者・考案者・創作)は発明等の時点において日本及び外国における一切の権利を会社()に譲渡したことを確認します。

社内発明者(計)	所属部門名	Post Tel	個人コード	氏名	権利 持分	認印	米国※4 在住
1	第一開発セク 第二開発室	716	2 0 2 4 8	中田 勉	20%		
2	第一開発セク 第二開発室	716	0 8 3 2 0	並木 計介	30%		
3	第一開発セク 第二開発室	716	2 1 1 5 5	倉科 敬一	30%		
4	第一開発セク 第二開発室	716	1 3 0 1 0	三島 浩二	20%		
5					%		

※3 届出発明が職務発明でないと考え場合は認印欄に押印せずに送付する。

※4 米国に在住している場合はレ印を付ける。

出願形式	1. EBR 単独	2. EBR と EBR 以外の者との共同	3. EBR 以外の者の単独	4. その他
------	-----------	-----------------------	----------------	--------

出願手続会社	1. EBR	2. EBR 以外の者 ()		
費用負担	1. EBR 負担	2. 均等負担	3. その他	
EBR 以外の 出願人名義※5 (計 名)	会社名又は氏名	連絡先 (住所、Tel、知財部門担当者名等)	権利持分 %	費用負担 %
			%	%

※5 荏原ボイラ(EB)、荏原工業洗浄(EICC)は上記「EBR 以外の出願人名義」の欄に記入する。荏原総合研究所(ER)は記入要領を参照のこと。

社外発明者(計)※6	会社名	氏名	住所	権利持分
				%
				%
				%

※6 「社外発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)以外の発明者等を記入する。

出願 緩急	1. 普通 2. 至急 (月 日まで) 理由: a. 社外発表 (右欄記入) b. 当社先願公開期限 c. 国内優先権主張期限	発表日: 年 月 日 発表先:
----------	---	--------------------

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

発明等届出書 (2/2)

社外秘

契約関係※7	共同研究等契約書	1. 有 (相手:) ② 無
	共同出願契約書	1. 要 (作成担当: a. 当社 b. 相手先 ()) 2. 不要

※7 共同出願、他社名義の出願とする根拠として契約書がある場合、契約書の写しを添付する。

調査実施状況 1. 調査済み (右欄記入) 2. 未調査	関連出願・公知例 出願内容に最も近い 公知例を2部添付す る。	当社のもの	1. 有 (特開 11-367759) 2. 無
		他社のもの	1. 有 (特開 2000-248397) 2. 無

評価項目	発明の性質によりA, B, Cのうち一列を選択 (記号を○) して評価		
	A. 現在製品・技術の発明	B. 新事業製品・技術の発明	C. 先行アイデア発明
① 先行技術に対する技術的 優位性	1. 同等	2. 若干優位	3. 相当優位 ④ 断然優位
② 他社侵害確認の難易度※8	1. 極めて困難	2. かなり困難	3. やや困難 4. 容易
③ 課題・手段の重要性	1. 不明	2. 普通	3. 重要 ④ 最重要
④ 他社における本発明の 回避困難度	1. 容易	2. やや困難 ③ かなり困難	4. 不可
⑤ 実施関係	1. 不明 2. 国内のみ小規模 3. 国内のみ大規模 4. 国内と外国で実施	1. 未定 2. 試作予定 ③ 試作中又は済 4. 採用決定	—
⑥ 技術的実現性	—	—	1. 不明 2. 困難 3. 容易 4. 検討済
⑦ 独創性	—	—	1. 不明 2. 小 3. 中 4. 大
⑧ 群評価※9	1. 普通 (1倍) 2. 重要 (2倍) ③ 最重要 (3倍)		

※8 他社が本発明等を侵害しているか否かの判別の程度のこと。

※9 本発明及び他の関連する発明で形成する発明群における、本発明の他の発明に対する相対的な重要度の評価。

評価計算式	依頼元評価ランク※10
A列, B列発明 (①+②+③+④+⑤)×⑧= 51	45以上 (S) 30~44 → A
C列発明 (①+②+③+⑥+⑦)×⑧=	20~29 → B 19以下 → C

出願要否	① 要 2. 公開技報でよい 3. 不要 (理由:)
外国出願	① 要 (国名: 米, 中, 韓, 日, 欧) 2. 不要 3. 未定

※10 該当の評価ランクに○を付ける。

特記事項

発 明 の 評 価	知財部評価点	知財部評価ランク※11	総 合 評 価 ※ 12	S: 最重要 A: 重要 ③ B: 通常 C: 公開技報 D: 見合せ E: 会社都合
	① 特許性: 2	(①+②+③+④)×⑤= 16		
	② 権利の広さ: 2	36以上 → S		
	③ 他社侵害確認の難易度: 2	24~35 → A		
	④ 本発明の回避困難度: 2	16~23 → ③		
	⑤ 群評価: 2	15以下 → C		

※11 評価点を記入し、該当の評価ランクに○を付ける。 ※12 該当の評価ランクに○を付ける。

出願 形 態	① 通常出願 2. 国内優先権主張 基礎出願番号: 3. 分割 4. 変更	特許事務所 渡辺・堀田
出願賞	① 支給する 2. 支給しない (理由:)	
備考		

4

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).

The column below is applicable only to inventors in EBR. Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company (Ebara Corporation) upon invention. The column below is applicable only to inventors in ER, EB, EICC, and ERS. Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company () upon invention.	In-house inventor (Total: inventor(s)) ²		Dept.	Post Tel	Employee No. (five digits)	Name	Share of the rights	Seal for confirming the transfer	Living in U.S. ³
		1	Process Development Office 2 Development Center 1	716	20248	Tsutomu Nakada	20%	Nakada	
		2	Process Development Office 1 Development Center 1	715	08320	Keisuke Namiki	30%	Namiki	
		3	Process Development Office 2 Development Center 1	716	21155	Keiichi Kurashina	30%	Kurashina	
		4	Same as above	716	13010	Koji Mlshima	20%	Mlshima	
		5							

³ Put a checkmark if the inventor is living in U.S.

5

Application type	1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR 3. Sole application by a company other than EBR 4. Other
------------------	--

6

*4 The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	1. EBR 2. Other than EBR ()			
Expense is:	1. Paid by EBR 2. Equally shared 3. Paid otherwise			
Applicant other than EBR ⁴ (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
			%	%

7

*5 The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor (Total: inventor(s)) ⁵	Company	Name	Address	Share of the interest
				%
				%

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

8

Urgency of application filing	1. Normal 2. High (by January 21.) Reason: a. External release (Fill the right column.) b. Deadline for publication of our prior application c. Deadline for claiming domestic priority Collaboration contract	Released on: Released to:
-------------------------------	---	------------------------------

Notification of Invention (2/2)

Support Document BE

Confidential

9

Related contract ⁶	Written contract for joint research	1. Available (partner:) 2. N/A (current)
	Written contract for joint filing of patent applications	1. Required (Prepared by: a. Us b. Partner ()) 2. Not required

⁶ When there is a written contract that justifies the joint filing or filing under other name, attach a copy of it to this form.

10

Prior-art search 1. Done (Fill the right column.) 2. Not done	Related application and prior art: Attach two items of prior art related to the application.	Ours	1. Available (Heisei 11-367754) 2. N/A
		Others'	1. Available (Publication No. 2000-248397) 2. N/A

11

Evaluation item	Nature of invention		
	Choose A, B, or C (enclose with a circle), considering the nature of the invention.		
	A. Invention for current products/technologies	B. Invention for new products/technologies	C. Invention of new ideas
(1) Technical superiority over prior art	1. None 2. A little 3. Considerable 4. Very large		
(2) Difficulty to find infringement ⁸	1. Very difficult 2. Considerably difficult 3. A little difficult 4. Easy		
(3) Severity of challenge/means	1. Unknown 2. Normal 3. High 4. Very high		
(4) Difficulty of design around	1. Easy 2. A little difficult 3. Considerably difficult 4. Impossible		-
(5) Applicability to production	1. Unknown 2. Domestic small scale 3. Domestic large scale 4. Domestic and abroad	1. Not decided 2. Planned to trial prod. 3. Under or finished trial production 4. Decided to adopt	-
(6) Technical realizability			1. Unknown 2. Difficult 3. Easy 4. Study finished
(7) Originality			1. Unknown 2. Low 3. Medium 4. High
(8) Group judgement ⁹	1. Normal (single) 2. Important (double) 3. Most important (triple)		

⁸ Difficulty to judge if other company infringes this invention⁹ Judge of importance of this invention to other inventions in an invention group comprising this invention and other related inventions

12

Calculation for rating	Rating by requesting department
For inventions of A or B ((1)+(2)+(3)+(4)+(5))×(8) = 51	45 or higher → S 30-44 → A 20-29 → B
For inventions of C ((1)+(2)+(3)+(6)+(7))×(8) =	Less than 19 → C

13

Filing of the patent application is:	1. Required 2. Not required; it should be published on Journal of Technical Disclosure. 3. Not required (reason:)
Foreign filing is:	1. Required (country name: US, CN, KR, TW, EU) 2. Not required 3. Not decided

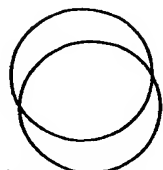
14

Special note	
--------------	--

Boss's seal of approval:
Mishima

15

Evaluation	Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept ^{*11}	Overall evaluation ^{*12}
	(1) Patentability: 2 (2) Scope of rights: 2 (3) Difficulty to find infringement: 2 (4) Difficulty of design around: 2 (5) Group judgement: 2	$((1)+(2)+(3)+(4)) \times (5) = 16$ 36 or higher → S 24-35 → A 16-23 → B Less than 15 → C	S: Most important A: Important B: Normal C: Journal of Technical Disclosure. D: No filing E: By company circumstance


 Evaluation
Approver
Seal:

 Evaluation
Approver
Seal:
Shinozuka
03.4.15

^{*11} Enter the evaluation values and circle the appropriate rank. ^{*12} Place a circle on the appropriate item of the evaluation level.

16

Application category	<input checked="" type="radio"/> 1. Regular application <input type="radio"/> 2. Domestic priority <input type="radio"/> 3. Division <input type="radio"/> 4. Change	Original application No.:	Patent firm
			Watanabe Hotta
Award for filing the patent application		1. Will be offered 2. N/A (reason:)	
Remarks			

Should you have any comment on the evaluation, contact us within two weeks.

発明等届出書 (1/2)

1.特許

2.意匠

3.その他

(補足書 1.有・2.無)

社外秘

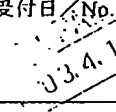
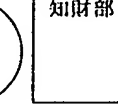
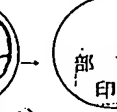
①

Post (716)

Post (708)

Post (52) 知的財産部

※1 原則として特許出願とする。但し、実用新案で出願したい場合は、「3.その他」に○を付し知的財産部と出願する。



2/2の依頼元上長記入欄の捺印欄もお忘れなく御捺印下さい。

K1030264

知財部 受付日 No.

2003.4.16

依頼日(西暦)

'03年

3月25日

依頼元 Doc.No.716-

②

太枠内をご記入下さい。

依頼元部門	(部門コード) (V350)	区分(本部)	1. 管理 2. 情報・通信・制御 3. 風水力 4. エンジニアリング 5. 精密・電子	6. 荏原総研 7. 荏原ボイラ 8. 荏原工業洗浄
部門名	第一開発セク、第二開発室、開発一部			
書類送付先担当者	氏名: 中田 勉 個人コード: 20248 (Post:716 Tel:8566)			

③

発明等の名称	基板のめっき装置及びめっき方法		
キーワード	めっき、平坦性、均一性、埋設性		
関連する製品又は技術	DMP、含浸めっき、パンプめっき		
製品の性格	1. 重点拡販機種である	2. 重点拡販機種でない	研番成果 研 No. L-02D547

④

※2 「社内発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)の発明者等のみ記入する。

下欄はEBRの発明者等だけに適用する。 上記の職務発明等 ^{※3} 等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社(株式会社荏原製作所)に譲渡したことを確認します。	社内発明者(計名) ^{※2}	所属部門名	Post Tel	個人コード	氏名	権利 持分	認印	米国 ^{※4} 在住
下欄はER、EB、EICCの発明者等だけに適用する。 上記の職務発明等 ^{※3} 等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社()に譲渡したことを確認します。	1	第一開発セク 第二開発室	716	211155	倉科 敬一	40%		
	2	第一開発セク 第一開発室	715	08320	並木 計介	40%		
	3	第一開発セク 第二開発室	716	20248	中田 勉	10%		
	4	第一開発セク 第二開発室	716	13010	三島 浩二	10%		
	5						%	

⑤

※3 届出発明が職務発明でないとする場合は認印欄に押印せずに送付する。

※4 米国に在住している場合はレ印を付ける。

出願形式	1. EBR 単独	2. EBR と EBR 以外の者との共同	3. EBR 以外の者の単独	4. その他
------	-----------	-----------------------	----------------	--------

⑥

出願手続会社	1. EBR	2. EBR 以外の者 ()		
費用負担	1. EBR 負担	2. 均等負担	3. その他	
EBR 以外の出願人名義 ^{※5} (計 名)	会社名又は氏名	連絡先 (住所、Tel、知財部門担当者名等)	権利持分	費用負担
			%	%
			%	%

⑦

※5 荏原ボイラ(EB)、荏原工業洗浄(EICC)は上記「EBR 以外の出願人名義」の欄に記入する。荏原総合研究所(ER)は記入要領を参照のこと。

社外発明者 ^{※6} (計 名)	会社名	氏名	住所	権利持分
				%
				%
				%

⑧

※6 「社外発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)以外の発明者等を記入する。

出願 緩急	1. 普通 2. 至急 (月 日まで) 理由: a. 社外発表 (右欄記入) b. 当社先願公開期限 c. 国内優先権主張期限	発表日: 年 月 日 発表先:
----------	---	--------------------

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

発明等届出書 (2/2)

社外秘

⑦

契約関係※7	共同研究等契約書	1. 有 (相手:) 2. 無
	共同出願契約書	1. 要 (作成担当: a. 当社 b. 相手先 ()) 2. 不要

※7 共同出願、他社名義の出願とする根拠として契約書がある場合、契約書の写しを添付する。

⑧

調査実施状況 1. 調査済み (右欄記入) 2. 未調査	関連出願・公知例 出願内容に最も近い 公知例を2部添付す る。	当社のもの	1. 有 (特開 2000-13205) 2. 無
		他社のもの	1. 有 (特開 2000-248397) 2. 無

⑨

発明の性質	発明の性質によりA, B, Cのうち一列を選択 (記号を○) して評価		
評価項目	A. 現在製品・技術の発明	B. 新事業製品・技術の発明	C. 先行アイデア発明
① 先行技術に対する技術的 優位性	1. 同等	2. 若干優位	3. 相当優位
② 他社侵害確認の難易度※8	1. 極めて困難	2. かなり困難	3. やや困難
③ 課題・手段の重要性	1. 不明	2. 普通	3. 重要
④ 他社における本発明の 回避困難度	1. 容易	2. やや困難	3. かなり困難
⑤ 実施関係	1. 不明 2. 国内のみ小規模 3. 国内のみ大規模 4. 国内と外国で実施	1. 未定 2. 試作予定 3. 試作中又は済 4. 採用決定	1. 不明 2. 困難 3. 容易 4. 検討済
⑥ 技術的実現性	1. 不明 2. 困難 3. 容易 4. 検討済	1. 不明 2. 困難 3. 容易 4. 検討済	1. 不明 2. 困難 3. 容易 4. 検討済
⑦ 独創性	1. 不明 2. 小 3. 中 4. 大	1. 不明 2. 小 3. 中 4. 大	1. 不明 2. 小 3. 中 4. 大
⑧ 群評価※9	1. 普通 (1倍)	2. 重要 (2倍)	3. 最重要 (3倍)

※8 他社が本発明等を侵害しているか否かの判別の程度のこと。

※9 本発明及び他の関連する発明で形成する発明群における、本発明の他の発明に対する相対的な重要度の評価。

⑩

評価計算式	依頼元評価ランク※10	出願要否	1. 要 2. 公開技報でよい 3. 不要 (理由:)
A 列, B 列発明 (①+②+③+④+⑤)×⑧= 30	45 以上 → S 30~44 → A	外国出願	1. 要 (国名: 米国) 2. 不要 3. 未定
C 列発明 (①+②+③+⑥+⑦)×⑧=	20~29 → B 19 以下 → C		

※10 該当の評価ランクに○を付ける。

⑪

特記事項

⑫

発 明 の 評 価	知財部評価点	知財部評価ランク※11	総 合 評 価 ※ 12	S: 最重要 A: 重要 B: 通常 C: 公開技報 D: 見合せ E: 会社都合
	① 特許性: 2	(①+②+③+④)×⑤= 16		
	② 権利の広さ: 2	36 以上 → S		
	③ 他社侵害確認の難易度: 2	24~35 → A		
	④ 本発明の回避困難度: 2	16~23 → B		
	⑤ 群評価: 2	15 以下 → C		

※11 評価点を記入し、該当の評価ランクに○を付ける。 ※12 該当の評価ランクに○を付ける。

⑬

出 願 形 態	① 通常出願	基礎出願番号:	特許事務所: 渡辺・土田
	2. 国内優先権主張		
	3. 分割		
	4. 変更		
出願賞	1. 支給する	2. 支給しない (理由:)	
備考			

Notification of Invention (1/2) (1. Patent 2. Design 3. Other)* (Supplement: 1. Attached 2. N/A) **Confidential**
 *Use this form for patent application filing. For utility model application, enclose "3. Other" with a circle and consult with Intellectual Property Dept.

Post (718)	Post ()	Post (52) Intellectual Property Dept.	K1030264
This form filled by: Nakada 03.3.25	Manager: Nakada 03.3.25	Patent liaison: Nagai 03.3.31	General manager: Mishima
Related dept.: Sasabe 03.4.8	General manager:	Manager: Kondo	Responsible person:
Date of receipt by IP Dept./No. 2003.04.16			

Be sure to affix the seal in the appropriate space of the "For the boss of the requesting dept." column on 2/2.

Sakaguchi
03.4.08

Date of request (Christian year): 2003/4/1
 Requesting dept. Doc.No.: 716

2
 Fill in within heavy-line frames.

Requesting dept.	(Dept. code) Dept. name	(V350) Process Development Office 2 Development Center 1	Category (Group)	1. Corporate 2. Strategic Information and Communication Systems 3. Fluid Machinery & Systems 4. Engineering 5. Precision Machinery	(Affiliate)	6. Ebara Research 7. Ebara Boiler Co.,Ltd. 8. Ebara Industrial Cleaning Co.,Ltd.
	Person responsible for the documents	Name: Tsutomu Nakada Employee No.: 20248 (Post: 716 Tel: 8566)				

Title of the invention	Plating Method and apparatus of substrate		pp,01	limura
Keyword	Plating, planarity, uniformity, filling ability		03.4.16	
Related product or technology	DMP, Impregnation plating, Bump plating			
Character of the product	1. Sales-focused 2. Not sales-focused	Result of:	Job No. L-02D547	

4

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).

The column below is applicable only to inventors in EBR. Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company (Ebara Corporation) upon invention. The column below is applicable only to inventors in ER, EB, EICC, and ERS. Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company () upon invention.	In-house inventor (Total: Inventor(s)) ²		Dept.	Post Tel	Employee No. (five digits)	Name	Share of the rights	Seal for confirming the transfer	Living in U.S. ³
		1	Process Development Office 2 Development Center 1	716	21155	Keiichi Kurashina	40%	Kurashina	
		2	Process Development Office 1 Development Center 1	715	08320	Keisuke Namiki	40%	Namiki	
		3	Process Development Office 2 Development Center 1	716	20248	Tsutomu Nakada	10%	Nakada	
		4	Same as above	716	13010	Koji Mlshima	10%	Mlshima	
		5							

³ Put a checkmark if the investor is living in U.S.

5

Application type	1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR 3. Sole application by a company other than EBR 4. Other
------------------	--

6

*4 The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	1. EBR 2. Other than EBR ()			
Expense is:	1. Paid by EBR 2. Equally shared 3. Paid otherwise			
Applicant other than EBR ⁴ (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
			%	%

7

*5 The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor (Total: inventor(s)) ⁵	Company	Name	Address	Share of the interest
				%
				%

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

8

Urgency of application filing	1. Normal 2. High (by) Reason: a. External release (Fill the right column.) b. Deadline for publication of our prior application c. Deadline for claiming domestic priority Collaboration contract	Released on: Released to:
-------------------------------	--	------------------------------

Notification of Invention (2/2)

Support Document BF

Confidential

9

Related contract ⁶	Written contract for joint research	1. Available (partner:) 2. N/A
	Written contract for joint filing of patent applications	1. Required (Prepared by: a. Us b. Partner ()) 2. Not required

⁶ When there is a written contract that justifies the joint filing or filing under other name, attach a copy of it to this form.

10

Prior-art search 1. Done (Fill the right column.) 2. Not done	Related application and prior art: Attach two items of prior art related to the application.	Ours	1. Available (Application 2000-132015) 2. N/A
		Others'	1. Available (Publication No. 2000-248397) 2. N/A

11

Evaluation item	Nature of invention		
	Choose A, B, or C (enclose with a circle), considering the nature of the invention.		
	A. Invention for current products/technologies	B. Invention for new products/technologies	C. Invention of new ideas
(1) Technical superiority over prior art	1. None 2. A little 3. Considerable 4. Very large		
(2) Difficulty to find infringement ⁸	1. Very difficult 2. Considerably difficult 3. A little difficult 4. Easy		
(3) Severity of challenge/means	1. Unknown 2. Normal 3. High 4. Very high		
(4) Difficulty of design around	1. Easy 2. A little difficult 3. Considerably difficult 4. Impossible		-
(5) Applicability to production	1. Unknown 2. Domestic small scale 3. Domestic large scale 4. Domestic and abroad	1. Not decided 2. Planned to trial prod. 3. Under or finished trial production 4. Decided to adopt	-
(6) Technical realizability			1. Unknown 2. Difficult 3. Easy 4. Study finished
(7) Originality			1. Unknown 2. Low 3. Medium 4. High
(8) Group judgement ⁹	1. Normal (single) 2. Important (double) 3. Most important (triple)		

⁸ Difficulty to judge if other company infringes this invention.⁹ Judge of importance of this invention to other inventions in an invention group comprising this invention and other related inventions

12

Calculation for rating	Rating by requesting department
For inventions of A or B $((1)+(2)+\textcircled{3})+(4)+(5)) \times (8)$ = 30	45 or higher → S. 30-44 → A 20-29 → B Less than 19 → C
For inventions of C $((1)+(2)+(3)+(6)+(7)) \times (8)$ =	

13

Filing of the patent application is:	1. Required 2. Not required; it should be published on Journal of Technical Disclosure. 3. Not required (reason:)
Foreign filing is:	1. Required (country name: US) 2. Not required 3. Not decided

14

Special note	
--------------	--

Boss's seal of approval:
Mishima

15

Evaluation	Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept ^{*11}	Overall evaluation ^{*12}
	(1) Patentability: 2 (2) Scope of rights: 2 (3) Difficulty to find infringement: 2 (4) Difficulty of design around: 2 (5) Group judgement: 2	$((1)+(2)+(3)+(4)) \times (5) = 16$ 36 or higher → S 24-35 → A 16-23 → B Less than 15 → C	S: Most important A: Important B: Normal C: Journal of Technical Disclosure. D: No filing E: By company circumstance

Evaluation
Approver
Seal:
Kondo

Evaluation
Approver
Seal:

^{*11} Enter the evaluation values and circle the appropriate rank. ^{*12} Place a circle on the appropriate item of the evaluation level.

16

Application category	1. Regular application 2. Domestic priority 3. Division 4. Change	Original application No.:	Patent firm	
			Watanabe Hotta	
Award for filing the patent application		1. Will be offered 2. N/A (reason:)		
Remarks				

Should you have any comment on the evaluation, contact us within two weeks.

発明等届出書 (1/2)

(1.特許)

2.意匠

3.その他)※1

(補足書 1.有・2.無)

社外秘

Post (716)

※1 原則として特許出願とする。但し、実用新案で出願したい場合は、「3.その他」に○を付し知的財産部と相談する。

Post (708)

Post (52) 知的財産部

K1030261

知財部 受付日/No.

2003.04.16/K1030261

2/2の依頼元上長記入欄の捺印欄もお忘れなく御捺印下さい。

依頼日(西暦)

'03年 3月 25日

依頼元 Doc.No.716-

② 太枠内をご記入下さい。

依頼元部門	(部門コード) 部門名 書類送付先 担当者	(V350) 第一開発セク、第二開発室、開発一部 氏名: 神田 裕之 個人コード: 21559 (Post:716 Tel:9426 7247)	区分(本部)	1. 管理 2. 情報・通信・制御 3. 風水力 4. エンジニア 5. 精密・電子	関係会社	6. 荏原総研 7. 荏原ポンプ 8. 荏原工業洗浄 03.4.16
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③ 発明等の名称 基板のめっき装置及びめっき方法

キーワード めっき、平坦性、均一性、埋設性

関連する製品又は技術 DMP、含浸めっき、パンプめっき

製品の性格 1. 重点拡販機種である 2. 重点拡販機種でない 研番成果 研 No. L-02D547

※2「社内発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)の発明者等のみ記入する。

下欄はEBRの発明者等だけに適用する。

上記の職務発明※3等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社(株式会社荏原製作所)に譲渡したことを確認します。

下欄はER、EB、EICCの発明者等だけに適用する。

上記の職務発明※3等に関し、私(発明者・考案者・創作者)は発明等の時点において日本及び外国における一切の権利を会社()に譲渡したことを確認します。

社内発明者(計)	所属部門名	Post Tel	個人コード	氏名	権利 持分	認印	米国※4 在住
1	第一開発セク 第二開発室	716	21559	神田 裕之	40%	(神田)	
2	第一開発セク 第一開発室	716	20894	長井 瑞樹	20%	(長井)	
3	第一開発セク 第二開発室	716	21630	山本 暁	20%	(山本)	
4	第一開発セク 第二開発室	716	13010	三島 浩二	20%	(三島)	
5					%		

※3 届出発明が職務発明でないと考えた場合は認印欄に押印せずに送付する。

※4 米国に在住している場合はレ印を付ける。

出願形式 (1) EBR 単独 2. EBR と EBR 以外の者との共同 3. EBR 以外の者の単独 4. その他

出願手続会社	(1) EBR 2. EBR 以外の者 ()			
費用負担	(1) EBR 負担 2. 均等負担 3. その他			
EBR 以外の 出願人名義※5 (計 名)	会社名又は氏名	連絡先 (住所、Tel、知財部門担当者名等)	権利持分	費用負担
			%	%
			%	%

※5 荏原ボイラ(EB)、荏原工業洗浄(EICC)は上記「EBR 以外の出願人名義」の欄に記入する。荏原総合研究所(ER)は記入要領を参照のこと。

社外発明者(計 名)※6	会社名	氏名	住所	権利持分
				%
				%
				%

※6「社外発明者」欄には荏原製作所(EBR)、荏原総合研究所(ER)、荏原ボイラ(EB)、荏原工業洗浄(EICC)以外の発明者等を記入する。

出願 緩急	(1) 普通 2. 至急 (月 日まで) 理由: a. 社外発表 (右欄記入) b. 当社先願公開期限 c. 国内優先権主張期限	発表日: 年 月 日 発表先:
----------	--	--------------------

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

発明等届出書 (2/2)

社外秘

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契約関係※7	共同研究等契約書	1. 有 (相手:) 2. 無
	共同出願契約書	1. 要 (作成担当: a. 当社 b. 相手先 ()) 2. 不要

※7 共同出願、他社名義の出願とする根拠として契約書がある場合、契約書の写しを添付する。

調査実施状況 1. 調査済み (右欄記入) 2. 未調査	関連出願・公知例 出願内容に最も近い 公知例を2部添付する。	当社のもの	1. 有 () 2. 無
		他社のもの	1. 有 () 2. 無

評価項目	発明の性質によりA, B, Cのうち一列を選択 (記号を○) して評価			
	A. 現在製品・技術の発明	B. 新事業製品・技術の発明	C. 先行アイデア発明	
①先行技術に対する技術的優位性	1. 同等	2. 若干優位	3. 相当優位	4. 断然優位
②他社侵害確認の難易度※8	1. 極めて困難	2. かなり困難	3. やや困難	4. 容易
③課題・手段の重要性	1. 不明	2. 普通	3. 重要	4. 最重要
④他社における本発明の回避困難度	1. 容易	2. やや困難	3. かなり困難	4. 不可
⑤実施関係	1. 不明 2. 国内のみ小規模 3. 国内のみ大規模 4. 国内と外国で実施	1. 未定 2. 試作予定 3. 試作中又は済 4. 採用決定	—	
⑥技術的実現性	—	—	1. 不明 3. 容易	2. 困難 4. 検討済
⑦独創性	—	—	1. 不明 3. 中	2. 小 4. 大
⑧群評価※9	(1) 普通 (1倍) (2) 重要 (2倍) 3. 最重要 (3倍)			

※8 他社が本発明等を侵害しているか否かの判別の程度のこと。

※9 本発明及び他の関連する発明で形成する発明群における、本発明の他の発明に対する相対的な重要度の評価。

評価計算式	依頼元評価ランク※10	出願要否	1. 要 2. 公開技報でよい 3. 不要 (理由:)
A 列, B 列発明 (①+②+③+④+⑤) × ⑧ = 20	45 以上 → S 30 ~ 44 → A	外国出願	1. 要 (国名:) 2. 不要 (3) 未定
C 列発明 (①+②+③+⑥+⑦) × ⑧ =	20 ~ 29 → B 19 以下 → C		

※10 該当の評価ランクに○を付ける。

特記事項

発明の評価	知財部評価点	知財部評価ランク※11	総合評価※12
	①特許性: 2	(①+②+③+④) × ⑤ = 18	
	②権利の広さ: 2	36 以上 → S	
	③他社侵害確認の難易度: 3	24 ~ 35 → A	
	④本発明の回避困難度: 2	16 ~ 23 → B	
	⑤群評価: 2	15 以下 → C	

※11 評価点を記入し、該当の評価ランクに○を付ける。 ※12 該当の評価ランクに○を付ける。

出願形態	① 通常出願	基礎出願番号:	特許事務所 クマ
	2. 国内優先権主張		
	3. 分割		
	4. 変更		
出願賞	① 支給する 2. 支給しない (理由:)		
備考			

Notification of Invention (1/2) (1. Patent 2. Design 3. Other)* (Supplement: 1. Attached 2. N/A) **Confidential**
 *Use this form for patent application filing. For utility model application, enclose "3. Other" with a circle and consult with Intellectual Property Dept.

Post (716)								Post ()	Post (52) Intellectual Property Dept.	K1030264
This form filled by: Kanda	Manager: Kanda	Patent liaison: Nagai	General manager: Mishima	Related dept.: Sasabe 03.4.8	General manager: Nakashiba	Manager: Kondo	Responsible person: Yamaji 03.4.15	Date of receipt by IP Dept./No 2003.04.16		

Be sure to affix the seal in the appropriate space of the "For the boss of the requesting dept." column on 2/2.

Sakaguchi
03.4.08

Date of request (Christian year): 2003/3/25
 Requesting dept. Doc.No.: 716-

2
 Fill in within heavy-line frames.

Requesting	(Dept. code) Dept. name	(V350) Process Development Office 2 Development Center 1	Category	1. Corporate 2. Strategic Information and Communication Systems 3. Fluid Machinery & Systems 4. Engineering 5. Precision Machinery	(Affiliate)	6. Ebara Research 7. Ebara Boiler Co.,Ltd. 8. Ebara Industrial Cleaning Co.,Ltd.
	Person responsible for the documents	Name: Hiroyuki Kanda Employee No.: 21559 (Post: 716 Tel: 7247)				

Title of the invention		Plating Method and apparatus of substrate		pp,01	limura
Keyword		Plating, planarity, uniformity, filling ability			
Related product or technology		DMP, Impregnation plating, Bump plating			
Character of the product	1. Sales-focused		Result of:	Job No. L-02D547	
	2. Not sales-focused				

4

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).

The column below is applicable only to inventors in EBR. Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company (Ebara Corporation) upon invention. The column below is applicable only to inventors in ER, EB, EICC, and ERS. Regarding to the service invention described above, I (inventor, deviser, or creator) acknowledge that any and all rights to the invention in Japan and other countries have been transferred to the Company () upon invention.	In-house inventor (Total: inventor(s)) ^{*2}		Dept.	Post Tel	Employee No. (five digits)	Name	Share of the rights	Seal for confirming the transfer	Living in U.S. ^{*3}
		1	Process Development Office 2 Development Center 1	716	21159	Hiroyuki Kanda	40%	Kanda	
		2	Process Development Office 2 Development Center 1	716	20894	Mizuki Nagai	20%	Nagai	
		3	Process Development Office 2 Development Center 1	716	21630	Satoru Yamamoto	20%	Yamamoto	
		4	Same as above	716	13010	Koji Mshima	10%	Mshima	
		5							

^{*3} Put a checkmark if the investor is living in U.S.

5

Application type	1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR 3. Sole application by a company other than EBR 4. Other
------------------	--

6

*4 The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	1. EBR 2. Other than EBR ()			
Expense is:	1. Paid by EBR 2. Equally shared 3. Paid otherwise			
Applicant other than EBR ^{*4} (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
			%	%

7

*5 The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor (Total: inventor(s)) ^{*5}	Company	Name	Address	Share of the interest
				%
				%

If descriptions of in-house/external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

8

Urgency of application filing	1. Normal 2. High (by) Reason: a. External release (Fill the right column.) b. Deadline for publication of our prior application c. Deadline for claiming domestic priority Collaboration contract	Released on: Released to:
-------------------------------	--	------------------------------

Notification of Invention (2/2)

Confidential

9

Related contract ⁶	Written contract for joint research	1. Available (partner:) 2. N/A
	Written contract for joint filing of patent applications	1. Required (Prepared by: a. Us b. Partner ()) 2. Not required

⁶ When there is a written contract that justifies the joint filing or filing under other name, attach a copy of it to this form.

10

Prior-art search	Related application and prior art: Attach two items of prior art related to the application.	Ours	1. Available () 2. N/A
1. Done (Fill the right column.) 2. Not done		Others'	1. Available () 2. N/A

11

Nature of invention Evaluation item	Choose A, B, or C (enclose with a circle), considering the nature of the invention.		
	A. Invention for current products/technologies	B. Invention for new products/technologies	C. Invention of new ideas
(1) Technical superiority over prior art	1. None 2. A little 3. Considerable 4. Very large		
(2) Difficulty to find infringement ⁸	1. Very difficult 2. Considerably difficult 3. A little difficult 4. Easy		
(3) Severity of challenge/means	1. Unknown 2. Normal 3. High 4. Very high		
(4) Difficulty of design around	1. Easy 2. A little difficult 3. Considerably difficult 4. Impossible		-
(5) Applicability to production	1. Unknown 2. Domestic small scale 3. Domestic large scale 4. Domestic and abroad	1. Not decided 2. Planned to trial prod. 3. Under or finished trial production 4. Decided to adopt	-
(6) Technical realizability			1. Unknown 2. Difficult 3. Easy 4. Study finished
(7) Originality			1. Unknown 2. Low 3. Medium 4. High
(8) Group judgement ⁹	(1) Normal (single) 2. Important (double) 3. Most important (triple)		

⁸ Difficulty to judge if other company infringes this invention⁹ Judge of importance of this invention to other inventions in an invention group comprising this invention and other related inventions

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Calculation for rating	Rating by requesting department
For inventions of A or B ((1)+(2)+(3)+(4)+(5))×(8) = 20	45 or higher → S 30-44 → A 20-29 → B
For inventions of C ((1)+(2)+(3)+(6)+(7))×(8) =	Less than 19 → C

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Filing of the patent application is:	1. Required 2. Not required; it should be published on Journal of Technical Disclosure. 3. Not required (reason:)
Foreign filing is:	1. Required (country name:) 2. Not required 3. Not decided

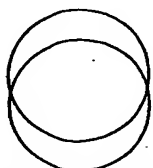
14

Special note	
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Boss's seal of approval:
Mishima

15

Evaluation	Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept ^{*11}	Overall evaluation ^{*12}
	(1) Patentability: 2 (2) Scope of rights: 2 (3) Difficulty to find infringement: 3 (4) Difficulty of design around: 2 (5) Group judgement: 2	$((1)+(2)+(3)+(4)) \times (5) = 18$ 36 or higher → S 24-35 → A 16-23 → B Less than 15 → C	S: Most important A: Important B: Normal C: Journal of Technical Disclosure. D: No filing E: By company circumstance



Evaluation Approver Seal: Kondo	Evaluation Approver Seal: Yamaji 03.4.17
---------------------------------------	---

^{*11} Enter the evaluation values and circle the appropriate rank. ^{*12} Place a circle on the appropriate item of the evaluation level.

16

Application category	① Regular application 2. Domestic priority 3. Division 4. Change	Original application No.:	Patent firm
			Kuma
Award for filing the patent application		1. Will be offered 2. N/A (reason:)	
Remarks			

Should you have any comment on the evaluation, contact us within two weeks.

発明部門メニューへ

事業本部特許部メニュー

社外秘

一時保存したものに追記する場合、または、承認／否認する場合、上部の「編集」リンクをクリックしてください。

発明等届出書

届出日: 2003/06/27

知的財産部受付番号: K1030415 受付日: 2003/07/03

依頼元担当一記入

▼依頼元上長一記入

▼事業本部特許部一記入

▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄

①【依頼元情報】

会社★	01 荏原製作所	部門	V350ニプロ開発一
整理番号 (Doc.No.)	716-L36271		
担当者	会社区分+社員番号: 0121155 氏名: 倉科 敬一 TEL: 8556		
本部名★	PP 精密・電子		

②【基本情報】

国内／外国★	国内			
四法★	特許			
発明の名称★	基板のめっき装置及びめっき方法			
キーワード	めっき、平坦性、均一性、埋設性			
関連する製品名	DMP、含浸めっき、パンプめっき			
関連する業務コード	その1	7B配線めっき装置	その2	7Cパンプめっき装置
研番	L-03D51306			
研番依頼元	部署名	V350ニプロ開発一		
職務発明について★	1.職務発明である			

③【荏原製作所／荏原総合研究所／荏原電産の発明者】

	会社	社員番号／氏名 (会社区分+社員番号)	内線NO／ポストNO／E-mail	所属部門コード／名称	持分 (%)	米国在住	代表発明者★
1	EK0001/ 荏原製作所	0121155 倉科 敬一	内線NO: 9293 ポストNO: 716 E-mail: kurashina.keiichi@ebara.com	V350ニプロ 開発一	25		Check
2	EK0001/ 荏原製作所	0120894 長井 瑞樹	内線NO: 9293 ポストNO: 716 E-mail: nagai.mizuki@ebara.com	V350ニプロ 開発一	25		
3	EK0001/ 荏原製作所	0121630 山本 暁	内線NO: 9293 ポストNO: 716 E-mail: yamamoto.satoru@ebara.com	V350ニプロ 開発一	25		
4	EK0001/ 荏原製作所	0121559 神田 裕之	内線NO: 7247 ポストNO: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350ニプロ 開発一	15		

5	EK0001/ 荏原製作 所	0113010 三島 浩二	内線NO: 9427 ポストNO: 716 E-mail: mishima.koji@ebara.com	V350ニプロ 開発一	10
該当無しおよび予定発明者					



④【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

	会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1			TEL: E-mail:		
該当無しおよび予定発明者					



⑤【出願人】

	コード／名称(略称)	住所連絡先など	権利持 分(%)	費用負 担(%)	手続担 当★
1	EK0001 荏原製作所	本社住所: 連絡先住所: 〒 部署: 担当: TEL: FAX: E-MAIL:	E	E	担当
該当無しおよび予定出願人					



⑥【出願緩急】

出願緩急	至急	出願希望日	2003/07/09		
		理由	社外発表	発表先: redacted	発表日: 2003/07/10
				その他:	

⑦【契約関係】

契約書有無★	無	種類			
		その他			
相手先	1				
	2				
	3				
	4				
	5				
	その他				
契約書					
共同出願契約書作 成★	不要	作成担当			
		相手先			
		その他			



⑧【調査実施状況】

--	--

調査状況★	未調査		
調査内容	検索式: 資料:		
競合メーカー	ノベラス、ニューツール、アプライドマテリアル、AMCリサーチ		

⑨【関連出願公知例】

当社の関連出願公知例★		有	
1	特願2003-15236号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	

他社の関連出願公知例★		無	
1	号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	



⑩【特記事項】

特記事項

⑪【発明等説明書(明細書素案)】

明細書	図面	その他
- なじませ条件3521.doc サイズ:196608バイト 添付者: keiichi kurashina/e/ebara.jp 添付日: 2003/06/27	- なじませ条件3521.TIF サイズ:356976バイト 添付者: keiichi kurashina/e/ebara.jp 添付日: 2003/06/27	添付者: 添付日:

▲依頼元担当一記入	依頼元上長一記入	▼事業本部特許部一記入	▼ワークフロー情
-----------	----------	-------------	----------

▼依頼元上長一記入欄

⑫【発明部門評価】

発明の性質	A: 現在製品・技術の発明
-------	---------------

①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)	3. 相当優位
②課題・手段の重要性	4. 最重要
③独創性 (発明の性質がCのときのみ必須)	0. 未評価
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)	4. 開発計画の初期段階である
⑤本発明が製品に占める重要度(割合)	4. 大きい
⑥依頼元総合評価	4. 最重要
評価点	60点
出願要否	要(理由:)
外国出願要否	要
特記事項	関連特許をまとめ、年内海外出願が必須。

▲依頼元担当一記入 ▲依頼元上長一記入 事業本部特許部一記入 ▼ワークフロー情報

13 ▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	お願いします。
担当者記入欄	コメント	CL1に記載の構成は、特開2000-232078(東芝)に開示されているが、CL2の含浸体と基板の被めつき面が接触と非接触を繰り返す振動である点の記載はありません。よって、出願することはOKと考えます。
	添付文書	
	作業終了サイン	坂口: 終了

▲依頼元担当一記入 ▲依頼元上長一記入 ▲事業本部特許部一記入 ワークフロー情報

▼ワークフロー情報

現在のユーザ: kenichi sasabe/e/ebara.jp
現在の承認者:
要求 ID: NTNN-5NW6L3

ステータス: 完了

14

申請者	承認者
keiichi kurashina/e/ebara.jp	<div>→</div> hiroyuki kanda/e/ebara.jp tsutomu nakada/e/ebara.jp koji mishima/e/ebara.jp kenichi

		sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp
--	--	--

▼承認者情報

⑮

申請者名	申請日	CCメール
keiichi kurashina/e/ebara_jp	2003/06/27	akira fukunaga/e/ebara_jp

⑯

承認者役職	承認者名	承認期限	ステータス	承認日	CCメール
発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/04	承認	2003/06/30	
リエゾン	tsutomu nakada/e/ebara_jp	2003/07/07	承認	2003/06/30	
部長	koji mishima/e/ebara_jp	2003/07/07	承認	2003/06/30	hiroyuki kanda/e/ebara_jp katsuhiko tokushige/e/ebara_jp hidenao suzuki/e/ebara_jp hidekazu nagano/e/ebara_jp
事業部側特許部門長	kenichi sasabe/e/ebara_jp	2003/07/07	承認	2003/07/02	
知的財産部部長	masamichi nakashiba/e/ebara_jp	2003/07/09	承認	2003/07/03	

▼コメント

CN=hiroyuki kanda/OU=e/0=ebara_jp 承認 2003/06/30 14:10:56 特になし
 CN=tsutomu nakada/OU=e/0=ebara_jp 承認 2003/06/30 14:53:34 承認しました。
 CN=koji mishima/OU=e/0=ebara_jp 承認 2003/06/30 15:15:30 第一クレームのドライシール規定
 を外せるのならば外すこと。AMATはシールレスのため。
 CN=kenichi sasabe/OU=e/0=ebara_jp 承認 2003/07/02 23:50:33 承認します。
 CN=masamichi nakashiba/OU=e/0=ebara_jp 承認 2003/07/03 10:51:41

◆アクション

To the menu for the dept. of the inventor(s)	To the menu for Patent Dept. of the Group
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Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/06/27

Intellectual Property Dept's receipt No.: K1030415 Date of receipt: 2003/07/03

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name ★	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2
Reference No. (Doc.No.)	716-L36271		
Responsible person	Company category + Employee No.: 0121155 Name: Keiichi Kurashina TEL: 8556		
Group name★	PP Precision Machinery		

2 [Basic information]

Domestic/foreign ★	Domestic			
IP category ★	Patent			
Title of the invention	Plating apparatus and method of substrate			
Keyword	Plating, planarity, uniformity, filling ability			
Names of related products	DMP, Impregnation plating apparatus, Bump plating apparatus			
Related job code	No. 1	7B Wire plating apparatus	No. 2	Bump plating apparatus
Job No.	L-03D51306			
Requesting dept.	Dept. name	V350 Development Department 1, Process Development Office 2		
About service invention ★	1. Yes			

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor ★
1	EK0001/ Ebara Corporation	0121155 Keiichi Kurashina	Extension No.: 9293 Post No.: 716 E-mail: kurashina.keiichi@ebara.com	V350 Development Department 1, Process Development Office 2	25		Check
2	EK0001/ Ebara Corporation	0120894 Mizuki Nagai	Extension No.: 9293 Post No.: 716 E-mail: nagai.mizuki@ebara.com	V350 Development Department 1, Process Development Office 2	25		
3	EK0001/ Ebara Corporation	0121630 Satoru Yamamoto	Extension No.: 9293 Post No.: 716 E-mail: yamamoto.satoru@ebara.com	V350 Development Department 1, Process Development Office 2	25		
4	EK0001/ Ebara Corporation	0121559 Hiroyuki Kanda	Extension No.: 7247 Post No.: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350 Development Department 1, Process Development Office 2	15		

5	EK0001/ Ebara Corporation	0113010 Koji Mishima	Extension No.: 9427 Post No.: 716 E-mail: mishima.koji@ebara.com	V350 Development Department 1, Process Development Office 2	10
N/A and potential inventor(s)					

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1			TEL: E-mail:		
N/A and potential inventor(s)					

5 [Applicant]

Code/name (abbreviation)	Contact address, etc.	Share of the rights (%)	Share of the costs (%)	Prosecution by: ★
EK0001 Ebara Corporation	Headquarter address: Contact address:〒 Dept.: Responsible: TEL: FAX: E-mail:	E	E	Responsible person
N/A and potential inventor(s)				

6 [Urgency of application filing]

Urgency		Preferred data of filing	2003/07/09	
		Reason	Outside presentation	Released to: [redacted] Released on: 2003.07.10 Other:

7 [Related contract]

Written contract ★	N/A	Type Other
Partner	1 2 3 4 5 Other	
Contract		
Preparation of contract documents for joint application filing ★	Not required	Prepared by: Partner Other

8 [Prior-art search]

Prior-art search ★	Not done	
Search details		Search formula: Material:
Competitor	Novellus, Nutool, Applied Materials, AMC Research	

9 [Related application and prior art]

Ours: ★	N/A	
1	Application No. 2003-15236 or document title:	File
2	No. or document title:	File
3	No. or document title:	File
4	No. or document title:	File

5	No. or document title:	File	
---	---------------------------	------	--

Others': ★		N/A	
1	No. or document title:	File	
2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

10 [Special note]

Special note	
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11 [Description of invention (specification draft)]

Specification	Drawings	Others
Adaptation Condition 3521.doc Size: 196608 bite	Adaptation Condition 3521.TIF Size: 356976 bite	
Attached by: Keiichi kurashina/e/ebara_jp Attached on: 2003/06/27	Attached by: Keiichi kurashina/e/ebara_jp Attached on: 2003/06/27	Attached by: Attached on:

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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▼ For the boss of the requesting side

12 [Evaluation by the dept. of the inventor(s)]

Nature of the invention	A. Invention for Current products/technologies
(1) Technical superiority over prior art (Quality improvement, cost reduction, energy saving, etc.)	3. Considerable
(2) Severity of challenge/means	4. Highest
(3) Originality (Enter data if the nature of the invention is C.)	0. Null
(4) Project for products based on the invention (development, sales, etc) (Enter data if the nature of the invention is A or B.)	4. In the initial stage
(5) Importance of the invention to the products	4. High
(6) Overall judgment by the requesting side	4. Most Important
Rating of evaluation	60 points
Filing of the patent application is:	Required (reason:)
Foreign filing of the patent application is:	Required
Special note	Combining related applications and file foreign application in this year

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
---	--	----------------------------------	------------------------

13 ▼ For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	Please check the draft.
Responsible person:	Comment	The construction of CL1 is disclosed in Publication 2000232078 (Toshiba), but the repetitive movement of CL2 of the impregnation element and plating surface of the substrate to touch and separate to each other is not disclosed. Filing of this application is OK.

Attachment	
Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
---	---------------------------------------	---------------------------------	----------------------

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5NW6L3

Status: completed

14

Requested by:	Approved by:
Keiichi kurashina/e/ebara_jp	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp keniichi sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
Keiichi kurashina/e/ebara_jp	2003/06/27	akira fukunaga/e/ebara_jp

16

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara_jp	2003/07/04	Approved	2003/06/30	
Liaison	tsutomu nahada/e/ebara_jp	2003/07/07	Approved	2003/06/30	
General manager	koji mishima/e/ebara_jp	2003/07/07	Approved	2003/06/30	hiroyuki kanda/e/ebara_jp katsuhiko tokushige/e/ebara_jp hidenao suzuki/e/ebara_jp hidekazu nagano/e/ebara_jp
Patent Dept. of the Group	kenichi sasabe/e/ebara_jp	2003/07/07	Approved	2003/07/02	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/09	Approved	2003/07/03	

▼Comment

CN=hiroyuki kanda/OU=e/0=ebara_jp Approved 2003/06/30 14:10:56 nothing special.

CN=tsutomu nahada /OU=e/0=ebara_jp Approved 2003/06/30 14:53:34 I approved

CN=koji mishima /OU=e/0=ebara_jp Approved 2003/06/30 15:15:30 if dry seal limitation in the first claim can be dismissed, please dismiss it. AMAT is seal-less.

CN=kenichi sasabe /OU=e/0=ebara_jp Approved 2003/07/02 23:50:33 I approved

CN=masamichi nakashiba /OU=e/0=ebara_jp Approved 2003/07/03 10:51:41

発明部門メニューへ

事業本部特許部メニュー

社外秘

一時保存したものに追記する場合、または、承認／否認する場合、上部の「編集」リンクをクリックしてください。

発明等届出書

届出日: 2003/07/15

知的財産部受付番号: K1030448 受付日: 2003/07/18

依頼元担当一記入

▼依頼元上長一記入

▼事業本部特許部一記入

▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄



①【依頼元情報】

会社★	01 荏原製作所	部門	V350ニプロ開発一
整理番号 (Doc.No.)	716-L37152		
担当者	会社区分+社員番号: 0121155 氏名: 倉科 敬一 TEL: 8556		
本部名★	PP 精密・電子		

②【基本情報】

国内／外国★	国内			
四法★	特許			
発明の名称★	基板のめっき装置			
キーワード	めっき、平坦性、均一性、埋設性			
関連する製品名	DMP、含浸めっき、パンプめっき			
関連する業務コード	その1	7B配線めっき装置	その2	7Cパンプめっき装置
研番	L-03D51306			
研番依頼元	部署名	V350ニプロ開発一		
職務発明について★	1.職務発明である			



③【荏原製作所／荏原総合研究所／荏原電産の発明者】

	会社	社員番号／氏名 (会社区分+社員番号)	内線NO／ポストNO／E-mail	所属部門コード／名称	持分 (%)	米国在住	代表発明者★
1	EK0001/ 荏原製作所	0121155 倉科 敬一	内線NO: 9293 ポストNO: 716 E-mail: kurashina.keiichi@ebara.com	V350ニプロ 開発一	30		Check
2	EK0001/ 荏原製作所	0120894 長井 瑞樹	内線NO: 9293 ポストNO: 716 E-mail: nagai.mizuki@ebara.com	V350ニプロ 開発一	20		
3	EK0001/ 荏原製作所	0121630 山本 暁	内線NO: 9293 ポストNO: 716 E-mail: yamamoto.satoru@ebara.com	V350ニプロ 開発一	20		
4	EK0001/ 荏原製作所	0121559 神田 裕之	内線NO: 7247 ポストNO: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350ニプロ 開発一	20		

5	EK0001/ 荏原製作所	0113010 三島 浩二	内線NO:9427 ポストNO:716 E-mail: mishima.koji@ebara.com	V350ニプロ 開発一	10
該当無しおよび予定発明者					



④【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

	会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1			TEL: E-mail:		
該当無しおよび予定発明者					



⑤【出願人】

	コード／名称(略称)	住所連絡先など	権利持 分(%)	費用負 担(%)	手続担 当★
1	EK0001 荏原製作所	本社住所: 連絡先住所:〒 部署:担当: TEL: FAX: E-MAIL:	E	E	担当
該当無しおよび予定出願人					



⑥【出願緩急】

出願緩急	至急	出願希望日	2003/08/05
		理由	その他
		発表先: 発表日: その他:次世代配線めっき装置の基本 特許であり、早急に特許を固める必要 有り。早ければ早いほど良い。	

⑦【契約関係】

契約書有無★	無	種類	
		その他	
相手先	1		
	2		
	3		
	4		
	5		
	その他		
契約書			
共同出願契約書作 成★	不要	作成担当	
		相手先	
		その他	



⑧【調査実施状況】

調査状況★	未調査		
調査内容	検索式: 資料:		
競合メーカー	ノベラス、アプライドマテリアル、ニューツール		

⑨【関連出願公知例】

当社の関連出願公知例★		有	
1	特願2003-15236号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	

他社の関連出願公知例★		無	
1	号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	



⑩【特記事項】

特記事項

⑪【発明等説明書(明細書素案)】

明細書		図面		その他	
- 分割含浸材3714.doc サイズ:64512バイト					
添付者: keiichi kurashina/e/ebara_jp 添付日: 2003/07/15		添付者: 添付日:		添付者: 添付日:	

▲依頼元担当一記入	依頼元上長一記入	▼事業本部特許部一記入	▼ワークフロー情
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▼依頼元上長一記入欄

⑫【発明部門評価】

発明の性質	A: 現在製品・技術の発明
-------	---------------

①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)	3. 相当優位
②課題・手段の重要性	3. 重要
③独創性 (発明の性質がCのときのみ必須)	0. 未評価
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)	4. 開発計画の初期段階である
⑤本発明が製品に占める重要度(割合)	3. やや大きい
⑥依頼元総合評価	4. 最重要
評価点	52点
出願要否	要(理由:)
外国出願要否	要
特記事項	関連特許をまとめ、年内海外出願が必須

▲依頼元担当一記入	▲依頼元上長一記入	事業本部特許部一記入	▼ワークフロー情
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⑬ ▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	お願いします。非分割パッドの1件と纏めてもいいと思います。
担当者記入欄	コメント	本発明に関連出願である親水性パッドの発明を含めることは可能と考えます。
	添付文書	
	作業終了サイン	坂口 : 終了

▲依頼元担当一記入	▲依頼元上長一記入	▲事業本部特許部一記入	ワークフロー情
-----------	-----------	-------------	---------

▼ワークフロー情報

現在のユーザ: kenichi sasabe/e/ebara_jp

現在の承認者:

要求 ID NTNN-5PG6JH

ステータス： 完了

14

申請者		承認者
keiichi kurashina/e/ebara_jp	➡	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp kenichi sasabe/e/ebara_jp

	masamichi nakashiba/e/ebara_jp
--	-----------------------------------

▼承認者情報

⑮

申請者名	申請日	CCメール
keiichi kurashina/e/ebara_jp	2003/07/15	akira fukunaga/e/ebara_jp

⑯

承認者役職	承認者名	承認期限	ステータス	承認日	CCメール
発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/22	承認	2003/07/15	
リエゾン	tsutomu nakada/e/ebara_jp	2003/07/22	承認	2003/07/15	
部長	koji mishima/e/ebara_jp	2003/07/22	承認	2003/07/15	hidenao suzuki/e/ebara_jp kunihiro ide/e/ebara_jp kazufumi nomura/e/ebara_jp
事業部側特許部門長	kenichi sasabe/e/ebara_jp	2003/07/22	承認	2003/07/18	
知的財産部部長	masamichi nakashiba/e/ebara_jp	2003/07/25	代理承認	2003/07/18	

▼コメント

CN=hiroyuki kanda/OU=e/0=ebara_jp 承認 2003/07/15 13:59:21 特になし
 CN=tsutomu nakada/OU=e/0=ebara_jp 承認 2003/07/15 14:57:15 承認いたしました。
 CN=koji mishima/OU=e/0=ebara_jp 承認 2003/07/15 15:32:11 第一クレームがface-downも含むように
 留意。アノードの記載内容が含浸face-upを限定している。
 CN=kenichi sasabe/OU=e/0=ebara_jp 承認 2003/07/18 15:19:30 承認します。
 CN=masaaki miyazaki/OU=e/0=ebara_jp 代理承認 2003/07/18 17:12:32 中柴Bの委任により宮崎代
 理受入2003.7.18

◆アクション

To the menu for the dept. of the inventor(s)	To the menu for Patent Dept. of the Group
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To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/07/15

Intellectual Property Dept's receipt No.: K1030448 Date of receipt: 2003/07/18

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name ★	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2
Reference No. (Doc.No.)	716-L37152		
Responsible person	Company category + Employee No.: 0121155 Name: Keiichi Kurashina TEL: 8556		
Group name★	PP Precision Machinery		

2 [Basic information]

Domestic/foreign ★		Domestic			
IP category ★		Patent			
Title of the invention		Plating apparatus of substrate			
Keyword		Plating, planarity, uniformity, filling ability			
Names of related products		DMP, Impregnation plating apparatus, Bump plating apparatus			
Related job code		No. 1	7B Wire plating apparatus	No. 2	Bump plating apparatus
Job No.		L-03D51306			
Requesting dept.		Dept. name	V350 Development Department 1, Process Development Office 2		
About service invention ★		1. Yes			

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor ★
1	EK0001/ Ebara Corporation	0121155 Keiichi Kurashina	Extension No.: 9293 Post No.: 716 E-mail: kurashina.keiichi@ebara.com	V350 Development Department 1, Process Development Office 2	30		Check
2	EK0001/ Ebara Corporation	0120894 Mizuki Nagai	Extension No.: 9293 Post No.: 716 E-mail: nagai.mizuki@ebara.com	V350 Development Department 1, Process Development Office 2	20		
3	EK0001/ Ebara Corporation	0121630 Satoru Yamamoto	Extension No.: 9293 Post No.: 716 E-mail: yamamoto.satoru@ebara.com	V350 Development Department 1, Process Development Office 2	20		
4	EK0001/ Ebara Corporation	0121559 Hiroyuki Kanda	Extension No.: 7247 Post No.: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350 Development Department 1, Process Development Office 2	20		

5	EK0001/ Ebara Corporation	0113010 Koji Mishima	Extension No.: 9427 Post No.: 716 E-mail: mishima.koji@ebara.com	V350 Development Department 1, Process Development Office 2	10
N/A and potential inventor(s)					

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1			TEL: E-mail:		
N/A and potential inventor(s)					

5 [Applicant]

Code/name (abbreviation)	Contact address, etc.	Share of the rights (%)	Share of the costs (%)	Prosecution by: ★
EK0001 Ebara Corporation	Headquarter address: Contact address:〒 Dept.: Responsible: TEL: FAX: E-mail:	E	E	Responsible person
N/A and potential inventor(s)				

6 [Urgency of application filing]

Urgency	Preferred data of filing Reason	2003/08/05 Outside presentation	Released to: Released on: Other: As this is a basic patent for a next generation wire plating apparatus, it is necessary to file patents regarding this relation. Sooner the better.

7 [Related contract]

Written contract ★	N/A	Type Other
Partner	1 2 3 4 5 Other	
Contract		
Preparation of contract documents for joint application filing ★	Not required	Prepared by: Partner Other

8 [Prior-art search]

Prior-art search ★	Not done	
Search details		Search formula: Material:
Competitor	Novellus, Applied Materials, Nutool	

9 [Related application and prior art]

Ours: ★	N/A	
1	Application No. 2003-15236 or document title:	File
2	No. or document title:	File

3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

Others: ★		N/A	
1	No. or document title:	File	
2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

10 [Special note]

Special note	
--------------	--

11 [Description of invention (specification draft)]

Specification	Drawings	Others
Segmented impregnation element 3714.doc Size: 64512 bite		
Attached by: Keiichi kurashina/e/ebara_jp Attached on: 2003/07/15	Attached by: Attached on:	Attached by: Attached on:

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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▼ For the boss of the requesting side

12 [Evaluation by the dept. of the inventor(s)]

Nature of the invention	A. Invention for Current products/technologies
(1) Technical superiority over prior art (Quality improvement, cost reduction, energy saving, etc.)	3. Considerable
(2) Severity of challenge/means	3. High
(3) Originality (Enter data if the nature of the invention is C.)	0. Null
(4) Project for products based on the invention (development, sales, etc) (Enter data if the nature of the invention is A or B.)	4. In the initial stage
(5) Importance of the invention to the products	3. A little high
(6) Overall judgment by the requesting side	4. Most Important
Rating of evaluation	52 points
Filing of the patent application is:	Required (reason:)
Foreign filing of the patent application is:	Required
Special note	Combining related applications and file foreign application in this year

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
---	--	----------------------------------	------------------------

13 ▼ For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	Please check the draft. It may be possible to combine with a non segmented pad.

Responsible person:	Comment	It seems to be possible to combine with the hydrophilic pad application, which is related to this application.
	Attachment	
	Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
---	---------------------------------------	---------------------------------	----------------------

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5PG6JH

Status: completed

14

Requested by:	Approved by:
Keiichi kurashina/e/ebara_jp	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp keniichi sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
Keiichi kurashina/e/ebara_jp	2003/07/15	akira fukunaga/e/ebara_jp

16

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara_jp	2003/07/22	Approved	2003/07/15	
Liaison	tsutomu nahada/e/ebara_jp	2003/07/22	Approved	2003/07/15	
General manager	koji mishima/e/ebara_jp	2003/07/22	Approved	2003/07/15	hidenao suzuki/e/ebara_jp kunihiro ide/e/ebara_jp kazufumi nomura/e/ebara_jp
Patent Dept. of the Group	kenichi sasabe/e/ebara_jp	2003/07/22	Approved	2003/07/18	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/25	Approved by a proxy	2003/07/18	

▼Comment

CN=hiroyuki kanda/OU=e/0=ebara_jp Approved 2003/07/15 13:59:21 nothing special.

CN=tsutomu nahada /OU=e/0=ebara_jp Approved 2003/07/15 14:57:15 I approve

CN=koji mishima /OU=e/0=ebara_jp Approved 2003/07/15 15:32:11 pay attention so that the first claim include the face-down. The description of the anode limits to the face-up impregnation.

CN=kenichi sasabe /OU=e/0=ebara_jp Approved 2003/07/18 15:19:30 I approve

CN=masamichi nakashiba /OU=e/0=ebara_jp Approved 2003/07/18 17:12:32 Miyazaki, or his proxy, approves the request. 2003.7.18

発明部門メニューへ 事業本部特許部メニュー

社外秘

一時保存したものに追記する場合、または、承認／否認する場合、上部の「編集」リンクをクリックしてください。

発明等届出書

届出日: 2003/07/03

知的財産部受付番号: K1030456 受付日: 2003/07/24

依頼元担当一記入 ▼依頼元上長一記入 ▼事業本部特許部一記入 ▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄

☐ ☐

①【依頼元情報】

会社★	01 荏原製作所	部門	V350ニプロ開発一
整理番号 (Doc.No.)	716-E37031		
担当者	会社区分+社員番号: 0120894 氏名: 長井 瑞樹 TEL: 9293		
本部名★	PP 精密・電子		

②【基本情報】

国内／外国★	国内		
四法★	特許		
発明の名称★	めっき方法及びめっき装置		
キーワード	半導体基板、めっき、銅、多孔質材料、電解めっき		
関連する製品名	DMP、含浸めっき		
関連する業務コード	その1	7B配線めっき装置	その2
研番	L-03D51306		
研番依頼元	部署名		
職務発明について★	1.職務発明である		

☐ ☐

③【荏原製作所／荏原総合研究所／荏原電産の発明者】

	会社	社員番号／氏名 (会社区分+社員番号)	内線NO／ポストNO／E-mail	所属部門コード／名称	持分 (%)	米国在住	代表発明者★
1	EK0001/ 荏原製作所	0120894 長井 瑞樹	内線NO: 9293 ポストNO: 716 E-mail: nagai.mizuki@ebara.com	V350ニプロ 開発一	70		Check
2	EK0001/ 荏原製作所	0121559 神田 裕之	内線NO: 7247 ポストNO: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350ニプロ 開発一	10		
3	EK0001/ 荏原製作所	0121155 倉科 敬一	内線NO: 8556 ポストNO: 716 E-mail: kurashina.keiichi@ebara.com	V350ニプロ 開発一	10		
4	EK0001/ 荏原製作所	0121630 山本 暁	内線NO: 9293 ポストNO: 716 E-mail: yamamoto.satoru@ebara.com	V350ニプロ 開発一	10		

該当無しおよび予定発明者



④ 【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

	会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1	EK0049荏原ユージライト	君塚 亮一	TEL: 81-3855 E-mail: eu-ryo.kimizuka@nifty.ne.jp	中央研究所	
該当無しおよび予定発明者					



⑤ 【出願人】

	コード／名称(略称)	住所連絡先など	権利持分(%)	費用負担(%)	手続担当★
1	EK0001 荏原製作所	本社住所: 連絡先住所: 〒 部署: 担当: TEL: FAX: E-MAIL:	E	E	担当
該当無しおよび予定出願人					



⑥ 【出願緩急】

出願緩急	至急	出願希望日	2003/07/25
		理由	その他
		発表先: 発表日: その他: 本開発テーマの基本特許の一つ。競合メーカーも同様技術の開発を行っている可能性大。	

⑦ 【契約関係】

契約書有無★	無	種類	その他
相手先	1		
	2		
	3		
	4		
	5		
	その他		
契約書			
共同出願契約書作成★	不要	作成担当	
		相手先	
		その他	



⑧ 【調査実施状況】

--

発明の性質		A: 現在製品・技術の発明	
①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)		2. 若干優位	
②課題・手段の重要性		3. 重要	
③独創性 (発明の性質がCのときのみ必須)		0. 未評価	
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)		4. 開発計画の初期段階である	
⑤本発明が製品に占める重要度(割合)		3. やや大きい	
⑥依頼元総合評価		3. 重要	
評価点		36点	
出願要否	要(理由:)		
外国出願要否	要		
特記事項			

▲依頼元担当一記入	▲依頼元上長一記入	事業本部特許部一記入	▼ワークフロー情
-----------	-----------	------------	----------

⑬▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	チェックして下さい。
担当者記入欄	コメント	出願要と判断いたします。なお、めっき液については、当社出願である公知例(特開2000-345392)があります。
	添付文書	
	作業終了サイン	坂口 : 終了

▲依頼元担当一記入	▲依頼元上長一記入	▲事業本部特許部一記入	ワークフロー情
-----------	-----------	-------------	---------

▼ワークフロー情報

現在のユーザ: kenichi sasabe/e/ebara_jp

現在の承認者:

要求 ID NTNN-5P49LK

ステータス： 完了

申請者		承認者
mizuki nagai/e/ebara_jp	➡	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp

	kenichi
	sasabe/e/ebara_jp
	masamichi
	nakashiba/e/ebara_jp

承認者情報

15

申請者名	申請日	C Cメール
mizuki nagai/e/ebara_jp	2003/07/03	akira fukunaga/e/ebara_jp

⑬

承認者役職	承認者名	承認期限	ステータス	承認日	ＣＣメール
発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/10	承認	2003/07/03	
リエゾン	tsutomu nakada/e/ebara_jp	2003/07/10	承認	2003/07/07	
部長	koji mishima/e/ebara_jp	2003/07/14	承認	2003/07/08	hidenao suzuki/e/ebara_jp kunihiro ide/e/ebara_jp kazufumi nomura/e/ebara_jp
事業部側特許部門長	kenichi sasabe/e/ebara_jp	2003/07/15	承認	2003/07/23	
知的財産部部長	masamichi nakashiba/e/ebara_jp	2003/07/30	代理承認	2003/07/24	

▼コメント

CN=hiroyuki kanda/OU=e/0=ebara_jp	否認	2003/07/03 17:08:33	山本君の社員番号が違っていた
CN=hiroyuki kanda/OU=e/0=ebara_jp	承認	2003/07/03 17:20:29	
CN=tsutomu nakada/OU=e/0=ebara_jp	承認	2003/07/07 10:32:42	承認します
CN=koji mishima/OU=e/0=ebara_jp	承認	2003/07/08 15:25:54	クレーム前半は既出願と同様なの
で、組み替えが必要であり、知財部殿にご指導願いたい			
CN=kenichi sasabe/OU=e/0=ebara_jp	承認	2003/07/23 18:13:13	承認します。
CN=masaaki miyazaki/OU=e/0=ebara_jp	代理承認	2003/07/24 14:04:43	中柴B不在のため宮崎代理
受入2003.7.24			

◆アクション

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

· Filed on: 2003/07/03

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
---	---------------------------------------	---------------------------------	------------------------

▼For the responsible person in the requesting side

Company name ★	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2
Reference No. (Doc.No.)	716-L37031		
Responsible person	Company category + Employee No.: 0120894 Name: Mizuki Nagai TEL: 9293		
Group name★	PP Precision Machinery		

Domestic/foreign ★	Domestic			
IP category ★	Patent			
Title of the invention	Plating method and plating apparatus			
Keyword	Semiconductor substrate, plating, copper, porous material, electrolytic plating			
Names of related products	DMP, Impregnation plating apparatus			
Related job code	No. 1	7B Wire plating apparatus	No. 2	
Job No.	L-03D51306			
Requesting dept.	Dept. name			
About service invention ★	1. Yes			

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor ★
1	EK0001/ Ebara Corporation	0120894 Mizuki Nagai	Extension No.: 9293 Post No.: 716 E-mail: nagai.mizuki@ebara.c om	V350 Developme nt Department 1, Process Developme nt Office 2	30		Check
2	EK0001/ Ebara Corporation	0121559 Hiroyuki Kanda	Extension No.: 7247 Post No.: 716-2 E-mail: kanda.hiroyuki@ebara .com	V350 Developme nt Department 1, Process Developme nt Office 2	20		
3	EK0001/ Ebara Corporation	0121155 Keiichi Kurashina	Extension No.: 9293 Post No.: 716 E-mail: kurashina.keiichi@eba ra.com	V350 Developme nt Department 1, Process Developme nt Office 2	20		
4	EK0001/ Ebara Corporation	0121630 Satoru Yamamoto	Extension No.: 9293 Post No.: 716 E-mail: yamamoto.satoru@eb ara.com	V350 Developme nt Department 1, Process Developme nt Office 2	20		
N/A and potential inventor(s)							

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1	EK0049 Ebara-Udylife Co. Ltd.	Ryoichi Kimizuka	TEL: 81-3855 E-mail: eu-ryo.kimizuka @nifty.ne.jp	Research & Development Center	
N/A and potential inventor(s)					

5 [Applicant]

Code/name (abbreviation)	Contact address, etc.	Share of the rights (%)	Share of the costs (%)	Prosecution by: ★
EK0001 Ebara Corporation	Headquarter address: Contact address:〒 Dept.: Responsible: TEL: FAX: E-mail:	E	E	Responsible person
N/A and potential inventor(s)				

6 [Urgency of application filing]

Urgency	Urgent	Preferred data of filing Reason	2003/07/25 Outside presentation	Released to: Released on: Other: This is one of basic patents for this development theme. Our competitors are possibly developing a similar technology.

7 [Related contract]

Written contract ★	N/A	Type Other
Partner	1 2 3 4 5 Other	
Contract		
Preparation of contract documents for joint application filing ★	Not required	Prepared by: Partner Other

8 [Prior-art search]

Prior-art search ★	Done
Search details	Computer search Search formula: plating x (polish + chemical mechanical polish + chemical mechanical-polish + electrolytic polish) x copper x planarization Material:
Competitor	Novellus, Semitool, Applied Materials, Nutool, ACM research

9 [Related application and prior art]

Ours: ★		N/A	
1	Application No. 2003-15236 or document title:	File	
2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	

5	No. or document title:	File	
---	---------------------------	------	--

Others': ★		N/A	
1	Application H11-33234 or document title:	File	
2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

10 [Special note]

Special note	
--------------	--

11 [Description of invention (specification draft)]

Specification	Drawings	Others
Patent explanation document (planarization PO).doc Size: 48640 bite		
Attached by: mizuki nagai/e/ebara_jp Attached on: 2003/07/03	Attached by: Attached on:	Attached by: Attached on:

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
---	--	------------------------------------	------------------------

▼ For the boss of the requesting side

12 [Evaluation by the dept. of the inventor(s)]

Nature of the invention	A. Invention for Current products/technologies
(1) Technical superiority over prior art (Quality improvement, cost reduction, energy saving, etc.)	2. A little
(2) Severity of challenge/means	3. High
(3) Originality (Enter data if the nature of the invention is C.)	0. Null
(4) Project for products based on the invention (development, sales, etc) (Enter data if the nature of the invention is A or B.)	4. In the initial stage
(5) Importance of the invention to the products	3. A little high
(6) Overall judgment by the requesting side	3. Important
Rating of evaluation	36 points
Filing of the patent application is:	Required (reason:)
Foreign filing of the patent application is:	Required
Special note	

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
---	--	----------------------------------	------------------------

13 ▼ For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	Please check the draft.
Responsible person:	Comment	I judge it to be filed. Regarding the plating solution, our application (application 2000-345392) is a prior art.
	Attachment	
	Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
---	---------------------------------------	---------------------------------	----------------------

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5P49LK

Status: completed

14

Requested by:	Approved by:
mizuki nagai/e/ebara_jp	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp keniichi sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
mizuki nagai/e/ebara_jp	2003/07/15	akira fukunaga/e/ebara_jp

16

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara_jp	2003/07/10	Approved	2003/07/03	
Liaison	tsutomu nahada/e/ebara_jp	2003/07/10	Approved	2003/07/03	
General manager	koji mishima/e/ebara_jp	2003/07/14	Approved	2003/07/08	hidenao suzuki/e/ebara_jp kunihiro ide/e/ebara_jp kazufumi nomura/e/ebara_jp
Patent Dept. of the Group	kenichi sasabe/e/ebara_jp	2003/07/15	Approved	2003/07/23	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/30	Approved by a proxy	2003/07/24	

▼Comment

CN=hiroyuki kanda/OU=e/0=ebara_jp Rejected 2003/07/03 17:08:33 Yamamoto's employee number is wrong.

CN=hiroyuki kanda/OU=e/0=ebara_jp Approved 2003/07/03 17:20:29

CN=tsutomu nahada/OU=e/0=ebara_jp Approved 2003/07/07 10:32:42 I approve

CN=koji mishima/OU=e/0=ebara_jp Approved 2003/07/08 15:25:54 front half of the claim is similar to the previously filed application. IP department please lead us for the re-arrangement.

CN=kenichi sasabe/OU=e/0=ebara_jp Approved 2003/07/23 18:13:13 I approve

CN=masaaki miyazaki/OU=e/0=ebara_jp Approved 2003/07/24 14:04:43 As Mr. Nakashiba is out of the office, Miyazaki, or his proxy, approves the request. 2003.7.24

発明部門メニューへ

事業本部特許部メニュー

社外秘

一時保存したものに追記する場合、または、承認／否認する場合、上部の「編集」リンクをクリックしてください。

発明等届出書

届出日: 2003/07/16

知的財産部受付番号: K1030466 受付日: 2003/07/24

依頼元担当一記入

▼依頼元上長一記入

▼事業本部特許部一記入

▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄



①【依頼元情報】

会社★	01 荏原製作所	部門	V350ニプロ開発一
整理番号 (Doc.No.)	716-L37161		
担当者	会社区分+社員番号: 0121155 氏名: 倉科 敬一 TEL: 8556		
本部名★	PP 精密・電子		

②【基本情報】

国内／外国★	国内			
四法★	特許			
発明の名称★	基板のめっき装置およびめっき方法			
キーワード	めっき、平坦性、均一性、埋設性			
関連する製品名	DMP、含浸めっき、パンプめっき			
関連する業務コード	その1	7B配線めっき装置	その2	7Cパンプめっき装置
研番	L-03D51306			
研番依頼元	部署名	V350ニプロ開発一		
職務発明について★	1.職務発明である			



③【荏原製作所／荏原総合研究所／荏原電産の発明者】

	会社	社員番号／氏名 (会社区分+社員番号)	内線NO／ポストNO／E-mail	所属部門コード／名称	持分 (%)	米国在住	代表発明者★
1	EK0001/ 荏原製作所	0121155 倉科 敬一	内線NO: 9293 ポストNO: 716 E-mail: kurashina.keiichi@ebara.com	V350ニプロ 開発一	60		Check
2	EK0001/ 荏原製作所	0120894 長井 瑞樹	内線NO: 9293 ポストNO: 716 E-mail: nagai.mizuki@ebara.com	V350ニプロ 開発一	10		
3	EK0001/ 荏原製作所	0121630 山本 暁	内線NO: 9293 ポストNO: 716 E-mail: yamamoto.satoru@ebara.com	V350ニプロ 開発一	10		
4	EK0001/ 荏原製作所	0121559 神田 裕之	内線NO: 7247 ポストNO: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350ニプロ 開発一	10		

5	EK0001/ 荏原製作 所	0113010 三島 浩二	内線NO:9427 ポストNO:716 E-mail: mishima.koji@ebara.com	V350ニプロ 開発一	10
該当無しおよび予定発明者					



④【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

	会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1			TEL: E-mail:		
該当無しおよび予定発明者					



⑤【出願人】

	コード／名称(略称)	住所連絡先など	権利持 分(%)	費用負 担(%)	手続担 当 ★
1	EK0001 荏原製作所	本社住所: 連絡先住所:〒 部署:担当: TEL: FAX: E-MAIL:	E	E	担当
該当無しおよび予定出願人					



⑥【出願緩急】

出願緩急	至急	出願希望日	2003/08/06	
		理由	その他	発表先: 発表日: その他:次世代配線めっき装置の基 本的な特許で、早急に特許を固めておく 必要がある。早ければ早いほど良い。

⑦【契約関係】

契約書有無★	無	種類			
		その他			
相手先	1				
	2				
	3				
	4				
	5				
	その他				
契約書					
共同出願契約書作 成★	不要	作成担当			
		相手先			
		その他			



⑧【調査実施状況】

調査状況★	未調査		
調査内容	検索式: 資料:		
競合メーカー	ノベラス、アプライドマテリアル、ニューツール		

⑨【関連出願公知例】

当社の関連出願公知例★		有	
1	特願2003-15236号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	

他社の関連出願公知例★		無	
1	号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	



⑩【特記事項】

特記事項

⑪【発明等説明書(明細書素案)】

明細書		図面		その他	
- エントポイント3714.doc サイズ: 73216バイト					
添付者: keiichi.kurashina/e/ebara_jp 添付日: 2003/07/16		添付者: 添付日:		添付者: 添付日:	

▲依頼元担当一記入	依頼元上長一記入	▼事業本部特許部一記入	▼ワークフロー情
-----------	----------	-------------	----------

▼依頼元上長一記入欄

⑫【発明部門評価】

発明の性質	A: 現在製品・技術の発明
-------	---------------

①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)	3. 相当優位
②課題・手段の重要性	3. 重要
③独創性 (発明の性質がCのときのみ必須)	0. 未評価
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)	4. 開発計画の初期段階である
⑤本発明が製品に占める重要度(割合)	4. 大きい
⑥依頼元総合評価	4. 最重要
評価点	56点
出願要否	要(理由:)
外国出願要否	要
特記事項	関連特許をまとめ、年内海外特許出願は必須

▲依頼元担当一記入 ▲依頼元上長一記入 事業本部特許部一記入 ▼ワークフロー情報

⑬ ▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	お願いします。
担当者記入欄	コメント	出願要と判断いたします。
	添付文書	
	作業終了サイン	坂口 : 終了

▲依頼元担当一記入 ▲依頼元上長一記入 ▲事業本部特許部一記入 ワークフロー情報

▼ワークフロー情報

現在のユーザ: kenichi sasabe/e/ebara.jp

現在の承認者:

要求 ID NTNN-5PH77U

ステータス: 完了



⑭

申請者	承認者
keiichi kurashina/e/ebara.jp	<div>→</div> hiroyuki kanda/e/ebara.jp tsutomu nakada/e/ebara.jp koji mishima/e/ebara.jp kenichi sasabe/e/ebara.jp masamichi

	nakashiba/e/ebara_jp
--	----------------------

承認者情報

⑤

申請者名	申請日	C C メール
keiichi kurashina/e/ebara_jp	2003/07/16	akira fukunaga/e/ebara_jp

⑥

承認者役職	承認者名	承認期限	ステータス	承認日	C C メール
発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/23	承認	2003/07/16	
リエゾン	tsutomu nakada/e/ebara_jp	2003/07/23	承認	2003/07/17	
部長	koji mishima/e/ebara_jp	2003/07/24	承認	2003/07/18	hidenao suzuki/e/ebara_jp kunihiro ide/e/ebara_jp kazufumi nomura/e/ebara_jp
事業部側特許部門長	kenichi sasabe/e/ebara_jp	2003/07/25	承認	2003/07/23	
知的財産部部長	masamichi nakashiba/e/ebara_jp	2003/07/30	代理承認	2003/07/24	

コメント

CN=hiroyuki kanda/OU=e/0=ebara_jp 承認 2003/07/16 14:24:57 特になし
 CN=tsutomu nakada/OU=e/0=ebara_jp 承認 2003/07/17 17:42:05 承認しました。
 CN=koji mishima/OU=e/0=ebara_jp 承認 2003/07/18 08:20:56 第一クレーム、face-down(アノードは移動しない)のも包含するクレームに修正のこと
 CN=kenichi sasabe/OU=e/0=ebara_jp 承認 2003/07/23 18:15:31 承認します。
 CN=masaaki miyazaki/OU=e/0=ebara_jp 代理承認 2003/07/24 14:08:58 中柴B不在のため宮崎代理
 受入2003.7.24

◆アクション

To the menu for the dept. of the inventor(s)	To the menu for Patent Dept. of the Group
--	---

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/07/16

Intellectual Property Dept's receipt No.: K1030466 Date of receipt: 2003/07/24

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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Never fail to fill ★-marked columns.

▼ For the responsible person in the requesting side

1 [Information of the requesting side]

Company name ★	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2
Reference No. (Doc.No.)	716-L37161		
Responsible person	Company category + Employee No.: 0121155 Name: Keiichi Kurashina TEL: 8556		
Group name★	PP Precision Machinery		

2 [Basic information]

Domestic/foreign ★	Domestic			
IP category ★	Patent			
Title of the invention	Plating apparatus and method of substrate			
Keyword	Plating, planarity, uniformity, filling ability			
Names of related products	DMP, Impregnation plating apparatus, Bump plating apparatus			
Related job code	No. 1	7B Wire plating apparatus	No. 2	7C Bump plating apparatus
Job No.	L-03D51306			
Requesting dept.	Dept. name	V350 Development Department 1, Process Development Office 2		
About service invention ★	1. Yes			

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor ★
1	EK0001/ Ebara Corporation	0121155 Keiichi Kurashina	Extension No.: 9293 Post No.: 716 E-mail: kurashina.keiichi@ebara.com	V350 Development Department 1, Process Development Office 2	60		Check
2	EK0001/ Ebara Corporation	0120894 Mizuki Nagai	Extension No.: 9293 Post No.: 716 E-mail: nagai.mizuki@ebara.com	V350 Development Department 1, Process Development Office 2	10		
3	EK0001/ Ebara Corporation	0121630 Satoru Yamamoto	Extension No.: 9293 Post No.: 716 E-mail: yamamoto.satoru@ebara.com	V350 Development Department 1, Process Development Office 2	10		
4	EK0001/ Ebara Corporation	0121559 Hiroyuki Kanda	Extension No.: 7247 Post No.: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350 Development Department 1, Process Development Office 2	10		

5	EK0001/ Ebara Corporation	0113010 Koji Mishima	Extension No.: 9427 Post No.: 716 E-mail: mishima.koji@ebara.com	V350 Development Department 1, Process Development Office 2	10
N/A and potential inventor(s)					

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1			TEL: E-mail:		
N/A and potential inventor(s)					

5 [Applicant]

Code/name (abbreviation)	Contact address, etc.	Share of the rights (%)	Share of the costs (%)	Prosecution by: ★
EK0001 Ebara Corporation	Headquarter address: Contact address:〒 Dept.: Responsible: TEL: FAX: E-mail:	E	E	Responsible person
N/A and potential inventor(s)				

6 [Urgency of application filing]

Urgency		Preferred data of filing Reason	2003/08/06 others	Released to: Released on: Other: As this is a basic patent for a next generation wire plating apparatus, it is necessary to file patents regarding this relation. Sooner the better.
---------	--	------------------------------------	----------------------	--

7 [Related contract]

Written contract ★	N/A	Type Other
Partner	1 2 3 4 5 Other	
Contract		
Preparation of contract documents for joint application filing ★	Not required	Prepared by: Partner Other

8 [Prior-art search]

Prior-art search ★	Not done	
Search details		Search formula: Material:
Competitor	Novellus, Applied Materials, Nutool	

9 [Related application and prior art]

Ours: ★	N/A	
1	Application No. 2003-15236 or document title:	File
2	No. or document title:	File

3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

Others': ★		N/A	
1	No. or document title:	File	
2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

10 [Special note]

Special note	
--------------	--

11 [Description of invention (specification draft)]

Specification	Drawings	Others
Endpoint 3714.doc Size: 73216 bites		
Attached by: Keiichi kurashina/e/ebara_jp Attached on: 2003/07/16	Attached by: Attached on:	Attached by: Attached on:

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
---	--	------------------------------------	------------------------

▼ For the boss of the requesting side

12 [Evaluation by the dept. of the inventor(s)]

Nature of the invention	A. Invention for Current products/technologies
(1) Technical superiority over prior art (Quality improvement, cost reduction, energy saving, etc.)	3. Considerable
(2) Severity of challenge/means	3. High
(3) Originality (Enter data if the nature of the invention is C.)	0. Null
(4) Project for products based on the invention (development, sales, etc) (Enter data if the nature of the invention is A or B.)	4. In the initial stage
(5) Importance of the invention to the products	4. High
(6) Overall judgment by the requesting side	4. Most Important
Rating of evaluation	56 points
Filing of the patent application is:	Required (reason:)
Foreign filing of the patent application is:	Required
Special note	Combining related applications and file foreign application in this year

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
---	--	----------------------------------	------------------------

13 ▼For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	Please check the draft.
Responsible person:	Comment	Filing of this invention is necessary.
	Attachment	
	Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
---	---------------------------------------	---------------------------------	----------------------

▼Workflow information

Current user: kenichi sasabe/e/ebara_jp

Current approver:

Request ID NTNN-5PH77U

Status: completed

14

Requested by:	Approved by:
keiichi kurashina/e/ebara_jp	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp kenichi sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
keiichi kurashina/e/ebara_jp	2003/07/16	akira fukunaga/e/ebara_jp

16

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara_jp	2003/07/23	Approved	2003/07/16	
Liaison	tsutomu nakada/e/ebara_jp	2003/07/23	Approved	2003/07/17	
General manager	koji mishima/e/ebara_jp	2003/07/24	Approved	2003/07/18	hidenao suzuki/e/ebara_jp kunihiro ide/e/ebara_jp kazufumi nomura/e/ebara_jp
Patent Dept. of the Group	kenichi sasabe/e/ebara_jp	2003/07/25	Approved	2003/07/23	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/30	Approved by a proxy	2003/07/24	

▼Comment

CN=hiroyuki kanda/OU=e/0=ebara_jp Approved 2003/07/16 14:24:57 nothing special.

CN=tsutomu nakada/OU=e/0=ebara_jp Approved 2003/07/17 17:42:05 I approve.

CN=koji mishima/OU=e/0=ebara_jp Approved 2003/07/18 08:20:56 Modify the first claim to include face-down (anode does not move).

CN=kenichi sasabe/OU=e/0=ebara_jp Approved 2003/07/23 18:15:31 I approve.

CN=masaaki miyazaki/OU=e/0=ebara_jp Approved by a proxy 2003/07/24 14:08:58 Mr. Nakashiba is out of office; so Miyazaki, or his proxy, approves the request. 2003.7.24

発明部門メニューへ 事業本部特許部メニュー

社外秘

一時保存したものに追記する場合、または、承認／否認する場合、上部の「編集」リンクをクリックしてください。
発明等届出書

届出日:2003/12/26

知的財産部受付番号:K1040012 受付日:2004/01/13

依頼元担当一記入 ▼依頼元上長一記入 ▼事業本部特許部一記入 ▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄

☐ ▼

①【依頼元情報】

会社★	01 荏原製作所	部門	V350ニプロ開発一
整理番号 (Doc.No.)			
担当者	会社区分+社員番号:0121559 氏名:神田 裕之 TEL:7247		
本部名★	PP 精密・電子		

②【基本情報】

国内／外国★	国内	
四法★	特許	
発明の名称★	基板のめっき装置およびその方法	
キーワード		
関連する製品名		
関連する業務コード	その1	その2
研番	L-	
研番依頼元	部署名	
職務発明について★	1.職務発明である	

☐ ▼

③【荏原製作所／荏原総合研究所／荏原電産の発明者】

	会社	社員番号／氏名 (会社区分+社員番号)	内線NO／ポストNO／E-mail	所属部門コード／名称	持分 (%)	米国在住	代表発明者★
1	EK0001/ 荏原製作所	0121559 神田 裕之	内線NO:7247 ポストNO:716-3 E-mail:kanda.hiroyuki@ebara.com	V350ニプロ 開発一	20		Check
2	EK0001/ 荏原製作所	0113010 三島 浩二	内線NO:9427 ポストNO:716 E-mail:mishima.koji@ebara.com	V350ニプロ 開発一	20		
3	EK0001/ 荏原製作所	0120308 森澤 伸哉	内線NO:9088 ポストNO:717 E-mail:morisawa.shinya@ebara.com	V510一プロ 開発一	20		
4	EK0001/ 荏原製作所	0121105 國澤 淳次	内線NO:9488 ポストNO:718 E-mail:kunisawa.junji@ebara.com	V370ニプロ 設計課	20		

5	EK0001/ 荏原製作 所	0121368 井出 邦仁	内線NO:9025 ポストNO:716 E-mail:ide.kunihito@ebaracom	V350ニプロ 開発一	10
6	EK0001/ 荏原製作 所	0107426 鈴木 秀直	内線NO:9025 ポストNO:716-3 E-mail:suzuki.hidenao@ebaracom	V350ニプロ 開発一	10
該当無しおよび予定発明者					

④【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

	会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1			TEL: E-mail:		
該当無しおよび予定発明者					



⑤【出願人】

	コード／名称(略称)	住所連絡先など	権利持分(%)	費用負担(%)	手続担当★
1	EK0001 荏原製作所	本社住所: 連絡先住所: 〒 部署: 担当: TEL: FAX: E-MAIL:	E	E	担当

該当無しおよび予定出願人

⑥【出願緩急】

出願緩急	出願希望日	発表先: 発表日: その他:
	理由	

⑦【契約関係】

契約書有無★	無	種類	
		その他	
相手先	1		
	2		
	3		
	4		
	5		
	その他		
契約書			
共同出願契約書作成★	不要	作成担当	
		相手先	
		その他	



⑨【調査実施状況】

調査状況★	未調査		
調査内容	検索式: 資料:		
競合メーカー			

⑩【関連出願公知例】

当社の関連出願公知例★		有	
1	特開2002-129383号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	

他社の関連出願公知例★		無	
1	号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	



⑪【特記事項】

特記事項

⑫【発明等説明書(明細書素案)】

明細書	図面	その他
- 分割アノード+含浸材 特許.doc サイズ:35840バイト	- 分割アノード+含浸材.doc サイズ:44544バイト	
添付者:hiroyuki kanda/e/ebara_jp 添付日:2003/12/26	添付者:hiroyuki kanda/e/ebara_jp 添付日:2003/12/26	添付者: 添付日:

▲依頼元担当一記入	依頼元上長一記入	▼事業本部特許部一記入	▼ワークフロー情
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▼依頼元上長一記入欄

⑬【発明部門評価】

発明の性質		B:新事業製品・技術の発明
①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)	3. 相当優位	
②課題・手段の重要性	4. 最重要	
③独創性 (発明の性質がCのときのみ必須)	0. 未評価	
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)	3. 開発計画の中間段階である	
⑤本発明が製品に占める重要度(割合)	4. 大きい	
⑥依頼元総合評価	4. 最重要	
評価点	56点	
出願要否	要(理由:)	
外国出願要否	要	
特記事項		

▲依頼元担当一記入	▲依頼元上長一記入	事業本部特許部一記入	▼ワークフロー情
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⑬ ▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	めっき膜の均一化のみを述べていますが、後工程に望ましい膜厚分布とすることを含めておいてください。方法クレームもこの考えのものを追加しておいてください。
担当者記入欄	コメント	<発明の効果>で述べているように例えば、後工程に望ましい膜厚分布とすることの具体例等を明細書に記載しておく方がよい。また、方法クレームには上記の具体的手法を追加した方がよいと思います。
	添付文書	
	作業終了サイン	坂口：終了

▲依頼元担当一記入	▲依頼元上長一記入	▲事業本部特許部一記入	ワークフロー情
-----------	-----------	-------------	---------

▼ワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara_jp
現在の承認者:
要求 ID NTNN-5UL5AZ

ステータス： 完了

(14)

申請者		承認者
hiroyuki kanda/e/ebara_jp	➡	tsutomu nakada/e/ebara_jp koji

	mishima/e/ebara_jp seimitsu zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp
--	--

▼承認者情報

15

申請者名	申請日	CCメール
hiroyuki kanda/e/ebara_jp	2003/12/26	

16

承認者役職	承認者名	承認期限	ステータス	承認日	CCメール
発明者上司	(承認不要)				
リエゾン	tsutomu nakada/e/ebara_jp	2004/01/02	承認	2003/12/26	
部長	kaji mishima/e/ebara_jp	2004/01/02	承認	2004/01/05	masao hodai/e/ebara_jp kunihiro ide/e/ebara_jp hiroyuki kanda/e/ebara_jp satoru yamamoto01/e/ebara_jp seiji katsuoka/e/ebara_jp masaaki kimbara/e/ebara_jp masaji akahori/e/ebara_jp sota nakagawa/e/ebara_jp
事業部側特許部門	seimitsu zzchizai/e/ebara_jp	2004/01/12	承認	2004/01/13	
知的財産部-部長	masamichi nakashiba/e/ebara_jp	2004/01/20	受入	2004/01/13	

▼コメント

CN=tsutomu nakada/OU=e/0=ebara_jp 承認 2003/12/26 12:49:20 承認します
 CN=kaji mishima/OU=e/0=ebara_jp 承認 2004/01/05 10:26:25 めっき限定ではなく電解装置を対象とすること、第一項からシールの限定は削除すること。
 CN=seimitsu zzchizai/OU=e/0=ebara_jp 承認 2004/01/13 09:41:47 承認します。
 CN=masamichi nakashiba/OU=e/0=ebara_jp 受入 2004/01/13 11:38:55

◆アクション

To the menu for the dept. of the inventor(s)	To the menu for Patent Dept. of the Group
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To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/12/26

Intellectual Property Dept's receipt No.: K1040012 Date of receipt: 2001/01/13

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name ★	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2
Reference No. (Doc.No.)			
Responsible person	Company category + Employee No.: 0121559 Name: Hiroyuki Kanda TEL: 7247		
Group name★	PP Precision Machinery		

2 [Basic information]

Domestic/foreign ★	Domestic			
IP category ★	Patent			
Title of the invention	Plating apparatus and method of substrate			
Keyword				
Names of related products				
Related job code	No. 1		No. 2	
Job No.	L-			
Requesting dept.	Dept. name			
About service invention ★	1. Yes			

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor ★
1	EK0001/ Ebara Corporation	0121559 Hiroyuki Kanda	Extension No.: 7247 Post No.: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350 Development Department 1, Process Development Office 2	20		Check
2	EK0001/ Ebara Corporation	0113010 Koji Mishima	Extension No.: 9427 Post No.: 716 E-mail: mishima.koji@ebara.com	V350 Development Department 1, Process Development Office 2	20		
3	EK0001/ Ebara Corporation	0120308 Shinya Morisawa	Extension No.: 9088 Post No.: 717 E-mail: morisawa.shinya@ebara.com	V510 Development Department 1, Process Development Office 1	20		
4	EK0001/ Ebara Corporation	012105 Junji Kunisawa	Extension No.: 9488 Post No.: 718 E-mail: kunisawa.junji@ebara.com	V370 Design Department, Process Development Office 2	20		

5	EK0001/ Ebara Corporation	0121368 Kunihito Ide	Extension No.: 9025 Post No.: 716 E-mail: ide.kunihito@ebara.com	V350 Development Department 1, Process Development Office 2	10
6	EK0001/ Ebara Corporation	0107426 Hidenao Suzuki	Extension No.: 9025 Post No.: 716-3 E-mail: suzuki.hidenao@ebara.com	V350 Development Department 1, Process Development Office 2	10
N/A and potential inventor(s)					

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1					
N/A and potential inventor(s)					

5 [Applicant]

Code/name (abbreviation)	Contact address, etc.	Share of the rights (%)	Share of the costs (%)	Prosecution by: ★
EK0001 Ebara Corporation	Headquarter address: Contact address: 〒 Dept.: Responsible: TEL: FAX: E-mail:	E	E	Responsible person
N/A and potential inventor(s)				

6 [Urgency of application filing]

Urgency	Preferred data of filing Reason	Released to: Released on: Other:

7 [Related contract]

Written contract ★	N/A	Type Other
Partner	1 2 3 4 5 Other	
Contract		
Preparation of contract documents for joint application filing ★	Not required	Prepared by: Partner Other

8 [Prior-art search]

Prior-art search ★	Not done
Search details	Search formula: Material:
Competitor	

9 [Related application and prior art]

Ours: ★	N/A
1	Publication No. 2002-129383 or document title:
	File

2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

Others': ★		N/A	
1	No. or document title:	File	
2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

10 [Special note]

Special note	
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11 [Description of invention (specification draft)]

Specification	Drawings	Others
Segmented anode + impregnation element patent.doc Size: 35840 bites	Segmented anode + impregnation element.doc Size: 44544 bites	
Attached by: hiroyuki kanda/e/ebara_jp Attached on: 2003/12/26	Attached by: hiroyuki kanda/e/ebara_jp Attached on: 2003/12/26	Attached by: Attached on:

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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▼ For the boss of the requesting side

12 [Evaluation by the dept. of the inventor(s)]

Nature of the invention	B. Invention for New products/technologies
(1) Technical superiority over prior art (Quality improvement, cost reduction, energy saving, etc.)	3. high
(2) Severity of challenge/means	4. Highest
(3) Originality (Enter data if the nature of the invention is C.)	0. Null
(4) Project for products based on the invention (development, sales, etc) (Enter data if the nature of the invention is A or B.)	3. Middle stage of development plan
(5) Importance of the invention to the products	4. High
(6) Overall judgment by the requesting side	4. Most important
Rating of evaluation	56 points
Filing of the patent application is:	Required (reason:)
Foreign filing of the patent application is:	Required
Special note	

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
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13 ▼For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	Specification describes only uniform plating in detail, but please modify to include controlling film thickness distribution suitable for the following process. Add method claims in this way.
Responsible person:	Comment	As described in <effect of the invention>, detailed embodiment of film thickness control suitable for the following process should be added to the specification. Specific method should be added to method claims.
	Attachment	
	Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
---	---------------------------------------	---------------------------------	----------------------

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5UL5AZ

Status: completed

14

Requested by:	Approved by:
mizuki nagai/e/ebara_jp	tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
hiroyuki kanda/e/ebara_jp	2003/12/26	

16

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	(Approval not necessary)				
Liaison	tsutomu nakada/e/ebara_jp	2004/01/02	Approved	2003/12/26	
General manager	koji mishima/e/ebara_jp	2004/01/02	Approved	2004/01/05	masao hodai/e/ebara_jp kunihiro ide/e/ebara_jp hiroyuki kanda/e/ebara_jp seiji katsuoka/e/ebara_jp masaaki kimbara/e/ebara_jp masaji akahori/e/ebara_jp sota nakagawa/e/ebara_jp
Patent Dept. of the Group	seimitsu zzchizai/e/ebara_jp	2004/01/12	Approved	2004/01/13	

General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2004/01/20	Received	2004/01/13	
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▼Comment

CN=tsutomu nakada/OU=e/0=ebara_jp Approved 2003/12/26 12:49:20 I approve.

CN=koji mishima /OU=e/0=ebara_jp Approved 2004/01/05 10:26:25 Modify specification and claims to include electrolytic apparatus not only plating tool. The limitation of the seal should be deleted from the first element.

CN=seimitsu zzchizai /OU=e/0=ebara_jp Approved 2004/01/13 09:41:47 I approve.

CN=masamichi nakashiba /OU=e/0=ebara_jp Received 2004/01/13 11:38:55

発明部門メニューへ

事業本部特許部メニューへ

社外秘

一時保存したものに追記する場合、または、承認／否認する場合、上部の「編集」リンクをクリックしてください。

発明等届出書

届出日: 2003/11/14

知的財産部受付番号: K1040028 受付日: 2004/01/19

依頼元担当一記入欄

▼依頼元上長一記入欄

▼事業本部特許部一記入欄

▼ワークフロー情報

★は必須入力項目です。

▼依頼元担当一記入欄



①【依頼元情報】

会社★	01 荏原製作所	部門	V350ニプロ開発一
整理番号 (Doc.No.)			
担当者	会社区分+社員番号: 0121559 氏名: 神田 裕之 TEL: 7247		
本部名★	PP 精密・電子		

②【基本情報】

国内／外国★	国内	
四法★	特許	
発明の名称★	基板のめっき装置及びその方法	
キーワード		
関連する製品名		
関連する業務コード	その1	その2
研番	レ-	
研番依頼元	部署名	
職務発明について★	1.職務発明である	



③【荏原製作所／荏原総合研究所／荏原電産の発明者】

	会社	社員番号／氏名 (会社区分+社員番号)	内線NO／ポストNO／E-mail	所属部門コード／名称	発明者の持分 (%)	米国在住	代表発明者★
1	EK0001/ 荏原製作所	0121559 神田 裕之	内線NO: 7247 ポストNO: 716-3 E-mail: kanda.hiroyuki@ebara.com	V350ニプロ 開発一	E		Check
2	EK0001/ 荏原製作所	0121155 倉科 敬一	内線NO: 9293 ポストNO: 716-3 E-mail: kurashina.keiichi@ebara.com	V350ニプロ 開発一	E		
3	EK0001/ 荏原製作所	0107426 鈴木 秀直	内線NO: 9025 ポストNO: 716-3 E-mail: suzuki.hidenao@ebara.com	V350ニプロ 開発一	10		
4	EK0001/ 荏原製作所	0120894 長井 瑞樹	内線NO: 9293 ポストNO: 716 E-mail: nagai.mizuki@ebara.com	V350ニプロ 開発一	E		

5	EK0001/ 荻原製作 所	0113010 三島 浩二	内線NO:9427 ポストNO:716 E-mail:mishima.koji@ebaracom	V350ニプロ 開発一	E
該当無しおよび予定発明者					



④【荏原総合研究所・荏原電産以外の関連会社／社外の発明者】

会社コード／名称	氏名	TEL／E-mail	所属部門または住所	米国在住
1		TEL: E-mail:		
該当無しおよび予定発明者				

⑤【出願人】

コード／名称(略称)	住所連絡先など	権利持分(%)	費用負担(%)	手続担当★
1 EK0001 荏原製作所	本社住所: 連絡先住所:〒 部署:担当: TEL: FAX: E-MAIL:	E	E	担当
該当無しおよび予定出願人				

⑥【出願緩急】

出願緩急	出願希望日	2003/12/12	
	理由		発表先: 発表日: その他:

⑦【契約関係】

契約書有無★		無		種類	
				その他	
相手先		1			
		2			
		3			
		4			
		5			
		その他			
契約書					
共同出願契約書作成★		不要		作成担当	
				相手先	
				その他	

⑧【調査実施状況】

--	--

調査状況★	未調査
調査内容	検索式: 資料:
競合メーカー	

⑨【関連出願公知例】

当社の関連出願公知例★		有	
1	特願2000-285740号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	



他社の関連出願公知例★		有	
1	特願2000-285740号 または文献名:	ファイル	
2	号 または文献名:	ファイル	
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
5	号 または文献名:	ファイル	



⑩【特記事項】

特記事項	2000-285740は荏原と東芝の共願であるが、今回の特許は荏原の出願している擦りめつきを加えたものである。今回の出願は荏原単願で行いたいため、2000-285740の位置付けをどうするかご相談したい。
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⑪【發明等說明書(明細書素案)】

明細書		図面		その他	
 <u>- 2ステップ・1セル特許.doc</u> サイズ:56832バイト		 <u>- 2ステップ・1セル特許.ppt</u> サイズ:68608バイト			
添付者:hiroyuki kanda/e/ebara.jp 添付日:2003/11/14		添付者:hiroyuki kanda/e/ebara.jp 添付日:2003/11/14		添付者: 添付日:	

▲依頼元担当一記入欄 依頼元上長一記入欄 ▼事業本部特許部一記入欄 ▼ワークフロー情報

▼依頼元上長一記入欄

⑫【發明部門評価】

--	--

発明の性質		B:新事業製品・技術の発明	
①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)		3. 相当優位	
②課題・手段の重要性		4. 最重要	
③独創性 (発明の性質がCのときのみ必須)		0. 未評価	
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)		4. 開発計画の初期段階である	
⑤本発明が製品に占める重要度(割合)		3. やや大きい	
⑥依頼元総合評価		3. 重要	
評価点		42点	
出願要否	要(理由:)		
外国出願要否	要		
特記事項			

▲依頼元担当一記入欄	▲依頼元上長一記入欄	事業本部特許部一記入欄	▼ワークフロー情報
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⑬ ▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	液交換などがシート補強に該当しないか注意してみてください。含浸体とウエハとの間のめっき駅量が増加し、アノードより高い位置までめっき液が満たされる場合に、他社特許との関連で問題がないか確認しておいてください。
担当者記入欄	コメント	本願は含浸めっき+擦りめっき+めっき液添加剤濃度可変とする組み合わせ特許であって、出願要と判断いたします。
	添付文書	
	作業終了サイン	坂口：終了

▲依頼元担当－記入欄 ▲依頼元上長－記入欄 ▲事業本部特許部－記入欄 ワークフロー情報

▼ワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara.jp

現在の承認者:

要求 ID NTNN-5TA4SN

ステータス：完了

申請者		承認者
hiroyuki kanda/e/ebara_jp	➡	tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp

	seimitsu zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp
--	--

▼承認者情報

⑮

申請者名	申請日	CCメール
hiroyuki kanda/e/ebara_jp	2003/11/14	

⑯

承認者役職	承認者名	承認期限	ステータス	承認日	CCメール
発明者上司	(承認不要)				
リエゾン	tsutomu nakada/e/ebara_jp	2003/11/21	承認	2003/12/26	
部長	koji mishima/e/ebara_jp	2004/01/02	承認	2004/01/05	masao hodai/e/ebara_jp kunihiro ide/e/ebara_jp hiroyuki kanda/e/ebara_jp satoru yamamoto01/e/ebara_jp seiji katsuoka/e/ebara_jp masaaki kimbara/e/ebara_jp masaji akahori/e/ebara_jp sota nakagawa/e/ebara_jp
事業部側特許部門	seimitsu zzchizai/e/ebara_jp	2004/01/12	承認	2004/01/16	
知的財産部-部長	masamichi nakashiba/e/ebara_jp	2004/01/23	承認	2004/01/19	

▼コメント

CN=tsutomu nakada/OU=e/0=ebara_jp 承認 2003/12/26 11:51:23 承認します。
 CN=koji mishima/OU=e/0=ebara_jp 承認 2004/01/05 10:52:44 第一クレームからシールは除外すること。ウェットコンタクトも網羅するため。
 CN=seimitsu zzchizai/OU=e/0=ebara_jp 承認 2004/01/16 19:20:29 承認します。
 CN=masamichi nakashiba/OU=e/0=ebara_jp 承認 2004/01/19 08:45:34

To the menu for the dept. of the inventor(s) | To the menu for Patent Dept. of the Group

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Notification of Invention

Filed on: 2003/11/14

Intellectual Property Dept's receipt No.: K1040028 Date of receipt: 2004/01/19

For the responsible person in the requesting side	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name ★	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2
Reference No. (Doc.No.)			
Responsible person	Company category + Employee No.: 0121559 Name: Hiroyuki Kanda TEL: 7247		
Group name★	PP Precision Machinery		

2 [Basic information]

Domestic/foreign ★	Domestic		
IP category ★	Patent		
Title of the invention	Plating apparatus and method of substrate		
Keyword			
Names of related products			
Related job code	No. 1	No. 2	
Job No.	L-		
Requesting dept.	Dept. name		
About service invention ★	1. Yes		

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor ★
1	EK0001/ Ebara Corporation	0121559 Hiroyuki Kanda	Extension No.: 7247 Post No.: 716-3 E-mail: kanda.hiroyuki@ebara.com	V350 Development Department 1, Process Development Office 2	E		Check
2	EK0001/ Ebara Corporation	0121155 Keiichi Kurashina	Extension No.: 9293 Post No.: 716-3 E-mail: kurashina.keiichi@ebara.com	V350 Development Department 1, Process Development Office 2	E		
3	EK0001/ Ebara Corporation	0107426 Hidenao Suzuki	Extension No.: 9025 Post No.: 716-3 E-mail: Suzuki.hidenao@ebara.com	V350 Development Department 1, Process Development Office 2	10		
4	EK0001/ Ebara Corporation	0120894 Mizuki Nagai	Extension No.: 9293 Post No.: 716 E-mail: nagai.mizuki@ebara.com	V350 Development Department 1, Process Development Office 2	E		

5	EK0001/ Ebara Corporation	0113010 Koji Mishima	Extension No.: 9427 Post No.: 716 E-mail: mishima.koji@ebara.com	V350 Development Department 1, Process Development Office 2	E
N/A and potential inventor(s)					

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1			TEL: E-mail:		
N/A and potential inventor(s)					

5 [Applicant]

Code/name (abbreviation)	Contact address, etc.	Share of the rights (%)	Share of the costs (%)	Prosecution by: ★
EK0001 Ebara Corporation	Headquarter address: Contact address:〒 Dept.: Responsible: TEL: FAX: E-mail:	E	E	Responsible person
N/A and potential inventor(s)				

6 [Urgency of application filing]

Urgency	Preferred data of filing Reason	2003/12/12	Released to: Released on: Other

7 [Related contract]

Written contract ★	N/A	Type Other
Partner	1 2 3 4 5 Other	
Contract		
Preparation of contract documents for joint application filing ★	Not required	Prepared by: Partner Other

8 [Prior-art search]

Prior-art search ★	Not done
Search details	Search formula: Material:
Competitor	

9 [Related application and prior art]

Ours: ★	N/A
1 Application No. 2000-285740 or document title:	File
2 No. or document title:	File
3 No. or document title:	File
4 No. or document title:	File

5	No. or document title:	File	
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Others': ★		N/A	
1	Application No. 2000-285740 or document title:	File	
2	No. or document title:	File	
3	No. or document title:	File	
4	No. or document title:	File	
5	No. or document title:	File	

10 [Special note]

Special note	2000-285740 is a joint-application of Ebara and Toshiba. Current application is adding scrub-polishing which Ebara is proposing. I would like to make this application a sole application of Ebara. I want to discuss how to evaluate the position of 2000-285740.
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11 [Description of invention (specification draft)]

Specification	Drawings	Others
2 step 1 cell patent.doc Size: 56832 bites	2 step 1 cell patent.doc Size: 68608 bites	
Attached by: hiroyuki kanda/e/ebara_jp Attached on: 2003/11/14	Attached by: hiroyuki kanda/e/ebara_jp Attached on: 2003/11/14	Attached by: Attached on:

▲ For the responsible person in the requesting side	For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
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▼ For the boss of the requesting side

12 [Evaluation by the dept. of the inventor(s)]

Nature of the invention	A. Invention for Current products/technologies
(1) Technical superiority over prior art (Quality improvement, cost reduction, energy saving, etc.)	3. Considerable
(2) Severity of challenge/means	4. Highest
(3) Originality (Enter data if the nature of the invention is C.)	0. Null
(4) Project for products based on the invention (development, sales, etc) (Enter data if the nature of the invention is A or B.)	4. In the initial stage
(5) Importance of the invention to the products	3. Considerable
(6) Overall judgment by the requesting side	3. Important
Rating of evaluation	42 points
Filing of the patent application is:	Required (reason:)
Foreign filing of the patent application is:	Required
Special note	

▲ For the responsible person in the requesting side.	▲ For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
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13 ▼For Patent Dept. of the Group

General manager:	Responsible	Mr. Sakaguchi
	Comment	Please check the draft carefully if the liquid exchange etc. will not be related to the seed repair. In the case of the liquid quantity increase and the liquid is filled up higher than anode, please check if there is any patent issue with patents of other companies.
Responsible person:	Comment	This application is a combination of impregnation plating + scrub plating + flexible additive concentration of the plating liquid. I consider this filling is necessary.
	Attachment	
	Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the requesting side	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group.	Workflow information
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▼Workflow information

Current user: kenichi sasabe/e/ebara_jp

Current approver:

Request ID NTNN-5TA4SN

Status: completed

14

Requested by:	Approved by:
hiroyuki kanda/e/ebara_jp	tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp seimitsu zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
hiroyuki kanda/e/ebara_jp	2003/11/14	

16

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	Approval not necessary				
Liaison	tsutomu nakada/e/ebara_jp	2003/11/21	Approved	2003/12/26	
General manager	koji mishima/e/ebara_jp	2004/01/12	Approved	2004/01/05	masao hodai/e/ebara_jp kunihiro ide/e/ebara_jp hiroyuki kanda/e/ebara_jp satoru yamamoto/e/ebara_jp seiji katsuoka/e/ebara_jp masaaki kimbara/e/ebara_jp masaji akahori/e/ebara_jp sota nakagawa/e/ebara_jp
Patent Dept. of	seimitsu	2004/01/12	Approved	2003/01/16	

the Group	zzchizai/e/ebara_jp				
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2004/01/23	Approved	2004/01/19	

▼Comment

CN=tsutomu nakada/OU=e/0=ebara_jp Approved 2003/12/26 11:51:23 I approve.

CN=koji mishima /OU=e/0=ebara_jp Approved 2004/01/05 10:52:44 Delete seal limitation from the first claim so that it covers wet contact.

CN=seimitsu zzchizai /OU=e/0=ebara_jp Approved 2004/01/16 19:20:29 I approve.

CN=masaaki miyazaki/OU=e/0=ebara_jp Approved 2004/01/19 08:45:34

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